

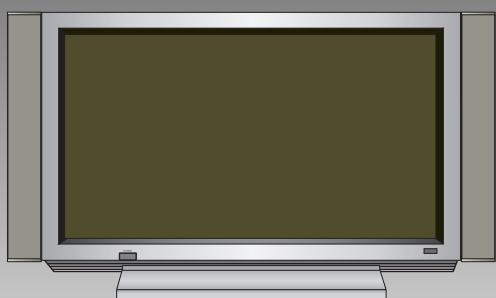


PLASMA DISPLAY TV

Chassis : D53A(P)
Model: PS42P2SDX/XEC

SERVICE *Manual*

PLASMA DISPLAY TV



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1. Precautions

Follow these safety, servicing and ESD precautions to prevent damage and protect against potential hazards such as electrical shock and X-rays.

1-1 Safety Precautions

1. Be sure that all of the built-in protective devices are replaced. Restore any missing protective shields.
2. When reinstalling the chassis and its assemblies, be sure to restore all protective devices, including: nonmetallic control knobs and compartment covers.
3. Make sure that there are no cabinet openings through which people—particularly children—might insert fingers and contact dangerous voltages. Such openings include the spacing between front cabinet and back cabinet, excessively wide cabinet ventilation slots, and improperly fitted back covers.
4. Leakage Current Hot Check (Figure 1-1):
Warning: Do not use an isolation transformer during this test. Use a leakage-current tester or a metering system that complies with American National Standards Institute (ANSI C101.1, Leakage Current for Appliances), and Underwriters Laboratories (UL Publication UL1950.5.2).
5. With the unit completely reassembled, plug the AC line cord directly into the power outlet. With the unit's AC switch first in the ON position and then OFF, measure the current between a known earth ground (metal water pipe, conduit, etc.) and all exposed metal parts, including: antennas, handle brackets, metal cabinets, screwheads and control shafts. The current measured should not exceed 3.5 milliamp. Reverse the power-plug prongs in the AC outlet and repeat the test.

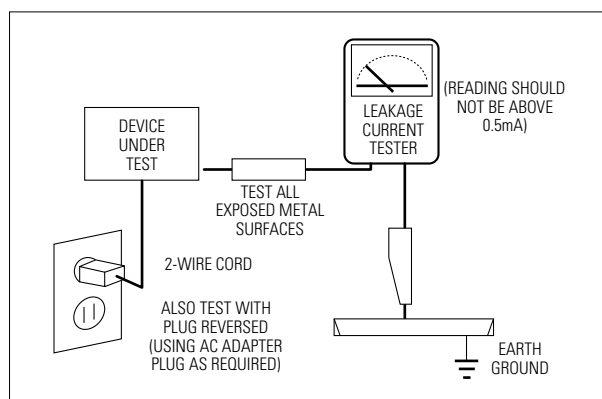


Fig. 1-1 AC Leakage Test

6. Antenna Cold Check:
With the unit's AC plug disconnected from the AC source, connect an electrical jumper across the two AC prongs. Connect one lead of the ohmmeter to an AC prong. Connect the other lead to the coaxial connector.
7. High Voltage Limits:
High voltage must be measured each time servicing is done on the B+, horizontal deflection or high voltage circuits.



1-2 Safety Precautions (Continued)

8. High voltage is maintained within specified limits by close-tolerance, safety-related components and adjustments. If the high voltage exceeds the specified limits, check each of the special components.
9. Design Alteration Warning:
Never alter or add to the mechanical or electrical design of this unit. Example: Do not add auxiliary audio or video connectors. Such alterations might create a safety hazard. Also, any design changes or additions will void the manufacturer's warranty.
10. Hot Chassis Warning:
Some TV receiver chassis are electrically connected directly to one conductor of the AC power cord. If an isolation transformer is not used, these units may be safely serviced only if the AC power plug is inserted so that the chassis is connected to the ground side of the AC source.

To confirm that the AC power plug is inserted correctly, do the following: Using an AC voltmeter, measure the voltage between the chassis and a known earth ground. If the reading is greater than 1.0V, remove the AC power plug, reverse its polarity and reinsert. Re-measure the voltage between the chassis and ground.
11. Some TV chassis are designed to operate with 85 volts AC between chassis and ground, regardless of the AC plug polarity. These units can be safely serviced only if an isolation transformer inserted between the receiver and the power source.
12. Some TV chassis have a secondary ground system in addition to the main chassis ground. This secondary ground system is not isolated from the AC power line. The two ground systems are electrically separated by insulating material that must not be defeated or altered.
13. Components, parts and wiring that appear to have overheated or that are otherwise damaged should be replaced with parts that meet the original specifications. Always determine the cause of damage or overheating, and correct any potential hazards.
14. Observe the original lead dress, especially near the following areas: Antenna wiring, sharp edges, and especially the AC and high

voltage power supplies. Always inspect for pinched, out-of-place, or frayed wiring. Do not change the spacing between components and the printed circuit board. Check the AC power cord for damage. Make sure that leads and components do not touch thermally hot parts.

15. Product Safety Notice:
Some electrical and mechanical parts have special safety-related characteristics which might not be obvious from visual inspection. These safety features and the protection they give might be lost if the replacement component differs from the original—even if the replacement is rated for higher voltage, wattage, etc.

Components that are critical for safety are indicated in the circuit diagram by shading, () or ().

Use replacement components that have the same ratings, especially for flame resistance and dielectric strength specifications. A replacement part that does not have the same safety characteristics as the original might create shock, fire or other hazards.

1-3 Servicing Precautions

Warning 1 : First read the "Safety Precautions" section of this manual. If some unforeseen circumstance creates a conflict between the servicing and safety precautions, always follow the safety precautions.

Warning 2 : An electrolytic capacitor installed with the wrong polarity might explode.

1. Servicing precautions are printed on the cabinet. Follow them.
2. Always unplug the unit's AC power cord from the AC power source before attempting to: (a) Remove or reinstall any component or assembly, (b) Disconnect an electrical plug or connector, (c) Connect a test component in parallel with an electrolytic capacitor.
3. Some components are raised above the printed circuit board for safety. An insulation tube or tape is sometimes used. The internal wiring is sometimes clamped to prevent contact with thermally hot components. Reinstall all such elements to their original position.
4. After servicing, always check that the screws, components and wiring have been correctly reinstalled. Make sure that the portion around the serviced part has not been damaged.
5. Check the insulation between the blades of the AC plug and accessible conductive parts (examples: metal panels, input terminals and earphone jacks).
6. Never defeat any of the B+ voltage interlocks. Do not apply AC power to the unit (or any of its assemblies) unless all solid-state heat sinks are correctly installed.
7. Always connect a test instrument's ground lead to the instrument chassis ground before connecting the positive lead; always remove the instrument's ground lead last.
8. Plasma display panels have partial afterimages when a same picture continues to be displayed for a certain time. This happens due to the degradation of brightness caused by a scale-down effect.
To prevent such afterimages when displaying a same picture for a certain time, be sure to reduce the level of brightness and contrast.
ex) Contrast : 50 or 75, Brightness : 25
9. Plasma display is an array of pixels(cells). Therefore, if at least 99.9% pixels keep normal, the appropriate panel is judged as 'approved product.' Even though some of pixels keep luminescent or always light off, do not worry because the panel is approved.

1-4 Precautions for Electrostatically Sensitive Devices (ESDs)

1. Some semiconductor (“solid state”) devices are easily damaged by static electricity. Such components are called Electrostatically Sensitive Devices (ESDs); examples include integrated circuits and some field-effect transistors. The following techniques will reduce the occurrence of component damage caused by static electricity.
2. Immediately before handling any semiconductor components or assemblies, drain the electrostatic charge from your body by touching a known earth ground. Alternatively, wear a discharging wrist-strap device. (Be sure to remove it prior to applying power—this is an electric shock precaution.)
3. After removing an ESD-equipped assembly, place it on a conductive surface such as aluminum foil to prevent accumulation of electrostatic charge.
4. Do not use freon-propelled chemicals. These can generate electrical charges that damage ESDs.
5. Use only a grounded-tip soldering iron when soldering or unsoldering ESDs.
6. Use only an anti-static solder removal device. Many solder removal devices are not rated as “anti-static”; these can accumulate sufficient electrical charge to damage ESDs.
7. Do not remove a replacement ESD from its protective package until you are ready to install it. Most replacement ESDs are packaged with leads that are electrically shorted together by conductive foam, aluminum foil or other conductive materials.
8. Immediately before removing the protective material from the leads of a replacement ESD, touch the protective material to the chassis or circuit assembly into which the device will be installed.
9. Minimize body motions when handling unpackaged replacement ESDs. Motions such as brushing clothes together, or lifting a foot from a carpeted floor can generate enough static electricity to damage an ESD.

2. Reference Information

2-1 Tables of Abbreviations and Acronyms

Table 2-1 Abbreviations			
A	Ampere	MV	Megavolt
Ah	Ampere-hour	MW	Megawatt
Å	Angstrom	MΩ	Megohm
dB	Decibel	m	Meter
dBm	Decibel Referenced to One Milliwatt	μA	Microampere
°C	Degree Celsius	μF	Microfarad
°F	Degree Fahrenheit	μH	Microhenry
°K	degree Kelvin	μm	Micrometer
F	Farad	μs	Microsecond
G	Gauss	μW	Microwatt
GHz	Gigahertz	mA	Milliampere
g	Gram	mg	Milligram
H	Henry	mH	Millihenry
Hz	Hertz	ml	Milliliter
h	Hour	mm	Millimeter
ips	Inches Per Second	ms	Millisecond
kWh	Kilowatt-hour	mV	Millivolt
kg	Kilogram	nF	Nanofarad
kHz	Kilohertz	Ω	Ohm
kΩ	Kilohm	pF	Picofarad
km	Kilometer	lb	Pound
km/h	Kilometer Per Hour	rpm	Revolutions Per Minute
kV	Kilovolt	rps	Revolutions Per Second
kVA	Kilovolt-ampere	s	Second (Time)
kW	Kilowatt	V	Volt
l	Liter	VA	Volt-ampere
MHz	Megahertz	W	Watt
		Wh	Watt-hour

Table 2-2 Table of Acronyms

ABL	Automatic Brightness Limiter	I/O	Input/output
AC	Alternating Current	L	Left
ACC	Automatic Chroma Control	L	Low
AF	Audio Frequency	LED	Light Emitting Diode
AFC	Automatic Frequency Control	LF	Low Frequency
AFT	Automatic Fine Tuning	MOSFET	Metal-Oxide-Semiconductor-Field-Effect-Tr
AGC	Automatic Gain Control	MTS	Multi-channel Television Sound
AM	Amplitude Modulation	NAB	National Association of Broadcasters
ANSI	American National Standards Institute	NEC	National Electric Code
APC	Automatic Phase Control	NTSC	National Television Systems Committee
APC	Automatic Picture Control	OSD	On Screen Display
A/V	Audio-Video	PCB	Printed Circuit Board
AVC	Automatic Volume Control	PLL	Phase-Locked Loop
BAL	Balance	PWM	Pulse Width Modulation
BPF	Bandpass Filter	QIF	Quadrature Intermediate Frequency
B-Y	Blue-Y	R	Right
CATV	Community Antenna Television (Cable TV)	RC	Resistor & Capacitor
CB	Citizens Band	RF	Radio Frequency
CCD	Charge Coupled Device	R-Y	Red-Y
CCTV	Closed Circuit Television	SAP	Second Audio Program
Ch	Channel	SAW	Surface Acoustic Wave(Filter)
CRT	Cathode Ray Tube	SIF	Sound Intermediate Frequency
CW	Continuous Wave	SMPS	Switching Mode Power Supply
DC	Direct Current	S/N	Signal/Noise
DVM	Digital Volt Meter	SW	Switch
EIA	Electronics Industries Association	TP	Test Point
ESD	Electrostatic Discharge	TTL	Transistor Transistor Logic
ESD	Electrostatically Sensitive Device	TV	Television
FBP	Feedback Pulse	UHF	Ultra High Frequency
FBT	Flyback Transformer	UL	Underwriters Laboratories
FF	Flip-Flop	UV	Ultraviolet
FM	Frequency Modulation	VCD	Variable-Capacitance Diode
FS	Fail Safe	VCO	Voltage Controlled Oscillator
GND	Ground	VCXO	Voltage Controlled Crystal Oscillator
G-Y	Green-Y	VHF	Very High Frequency
H	High	VIF	Video Intermediate Frequency
HF	High-Frequency	VR	Variable Resistor
HI-FI	High Fidelity	VTR	Video Tape Recorder
IC	Inductance-Capacitance	VTVM	Vacuum Tube Voltmeter
IC	Integrated Circuit	TR	Transistor
IF	Intermediate Frequency		

3. Specifications

3-1 Display(PDP Monitor)

MODEL		PS-42P2S
SCREEN SIZE		16:9
Dimensions (mm/inch)	Display	1039(W) x 89(D) x 635(H)/40.9(W) x 3.5(D) x 25(H)
	Remote Control	54(W) x 31.5(D) x 220(H)/2.13(W) x 1.24(D) x 8.66(H)
Terminal	Display	32Kg/70.54 lbs
	Remote Control	150g/0.33 lbs
In/Out Terminals	Front	POWER , MUTE, -VOLME+, ▲SELECT▼, MENU,SOURCE
	Back	AV1(S-VHS IN, VIDEO IN) AV2(SCART IN) PC IN AUDIO IN(AV1, PC) RS232C(only for service) External Speaker Out
Power Supply		AC220V 50/60Hz
Power Consumption		350W
Screen Size		852 x 474(106 cm)/33.54 x 18.66(42inchs)
Adjustment System		Electronic Function Adjustment

MENO

4. Alignment and Adjustments

4-1 Service Mode

4-1-1 SERVICE MODE ENTRY METHOD (General Transmitter)

1. Turn off the power to make the SET STAND-BY mode.
2. In order to enter the Service Mode, select MUTE-1-8-2-POWER.

* In case entry into SERVICE MODE is unsuccessful, repeat the procedures above.

4-1-2 Initial DISPLAY State in times of SERVICE MODE Switch overs

4-1-2(A) OSD DISPLAY

1. PWS364A	9. PinP Control
2. VPC3230	10. OSD Position
3. SDA9400	11. Test Position
4. SDA9280	12. Option Table
5. AD9884-Video	13. Reset
6. AD9884-DTV/PC	
7. CXA2101Q-1	
8. CXA2101Q-2	
Release Time :	

4-1-2(B) BUTTONS OPERATIONS WITHIN SERVICE MODE

Menu	Entire menu display
Joystick UP/DOWN	Cursor move to select items
Joystick	Enable to increase and decrease the data of the selected items

#Notice

1. In case of no signal in ALL MODE. entry into the FACTORY MODE cannot be made.

4-1-3 Details of Control

4-1-3(A) PW364A

No	OSD	Item	Range	Default	Description
1	H Position	H Position	0 ~ 127	30	H-Position(The Picture moves left when the value increase)
2	V Position	V Position	0 ~ 84	34	V-Position(The Picture moves up when the value increase)
3	Red Gain	Red Gain	0 ~ 255	116	High Light Adjustment(Variable)
4	Green Gain	Green Gain	0 ~ 255	116	High Light Adjustment(Variable)
5	Blue Gain	Blue Gain	0 ~ 255	116	High Light Adjustment(Fixed)
6	Red offset	Red Cutoff	0 ~ 255	128	Low Light Adjustment(Variable)
7	Green offset	Green Cutoff	0 ~ 255	128	Low Light Adjustment(Variable)
8	Blue offset	Blue Cutoff	0 ~ 255	128	Low Light Adjustment(Fixed)
9	APL on/off	APL on/off	0, 1	1	Fixed, Shipment Setting : APL On
10	High Light	High Light	0 ~ 255	116	
11	Low Light	Low Light	0 ~ 255	128	
12	Shift Pixel	Shift Pixel	off, on	Off	
13	Test	Test	0,1	0	
14	Pixel Number	Pixel Number	0 ~ 5	4	
15	Shift Line	Shift Live	0 ~ 5	4	
16	Time	Time	0 ~ 60	4	

4-1-3(B) VPC3230

No	OSD	Item	Range	Default	Description
1	Bright YUV	Brightness of YUV	0 ~ 255	195	Comp, (DVD) Bright, Level (Fixed)
2	Cont YUV	Contrast of YUV	0 ~ 63	27	Comp, (DVD) Cont, Level (Fixed)
3	IF Comp	IF Compensation	0 ~ 3	2	Air IF Frequency Characteristic Setting (Fixed)
4	Chroma band	Chroma band width	0 ~ 4	3	Chroma Band Setting (Fixed)
5	Ena Luma	Enable Luma, LPF	0 ~ 1	1	Determines whether LPF is used or not (Fixed)
6	HPLL Speed	HPLL Speed	0 ~ 3	1	VCR/Air Sync, Response Velocity Setting
7	Luma Delay	Luma/Chroma Delay	0 ~ 9	5	Y/C Delay
8	3230 Bright	Brightness	0 ~ 255	168	
9	3230 Contrast	Contrast	0 ~ 63	36	
10	H LPF Y/C	H LPF for Y/C	0 ~ 4	0	By pass, f1, f2, f3
11	H LPF Chroma	H LPF Chroma	0 ~ 2	0	
12	H Peaking	H Peaking Filter	0 ~ 3	2	Board, Med, Narrow
13	Coaring Off/On	Coaring Off/On	0, 1	1	Coaring off, on

4-1-3(C) SDP9400

No	OSD	Item	Range	Default	Description
1	SNR On	SNR On	0, 1	1	Spatial Noise Reduction
2	VCSNR On	VCSNR On	0, 1	1	Vertical Spatial Noise Reduction
3	HCSNR On	HCSNR On	0, 1	0	Horiz, Spatial Noise Reduction
4	DTNR On	DTNR On	0, 1	1	Frame/Field Selection
5	TNRCLY	TNRCLY	0 ~ 15	5	
6	TNRCNC	TNRCNC	0 ~ 15	5	

4-1-3(D) SDA9280

No	OSD	Item	Range	Default	Description
1	CTI Thresh	CTI Thresh	0 ~ 15	0	
2	CTI Trawid	CTI Trawid	0 ~ 15	0	
3	Y-Delay	Y-Delay	0 ~ 15	11	
4	LPF Gain	LPF Gain	0 ~ 7	4	
5	BPF Gain	BPF Gain	0 ~ 15	8	
6	HPF Gain	HPF Gain	0 ~ 15	8	
7	Phacom	Phacom	0 ~ 3	0	
8	Cor	Cor	0, 1	1	

4-1-3(E) AD9884-VIDEO

No	OSD	Item	Range	Default	Description
1	Red Gain	Red Gain	0 ~ 255	137	PC Mode W/B (Fixed)
2	Green Gain	Green Gain	0 ~ 255	128	PC Mode W/B (Fixed)
3	Blue Gain	Blue Gain	0 ~ 255	141	PC Mode W/B (Fixed)
4	Red Offset	Red Offset	0 ~ 63	27	PC Mode W/B (Fixed)
5	Green Offset	Green Offset	0 ~ 63	32	PC Mode W/B (Fixed)
6	Blue Offset	Blue Offset	0 ~ 63	36	PC Mode W/B (Fixed)

4-1-3(F) AD9884 DTV/PC

No	OSD	Item	Range	Default	Description
1	Red Gain	Red Gain	0 ~ 255	125	PC Mode W/B (Fixed)
2	Green Gain	Green Gain	0 ~ 255	128	PC Mode W/B (Fixed)
3	Blue Gain	Blue Gain	0 ~ 255	127	PC Mode W/B (Fixed)
4	Red Offset	Red Offset	0 ~ 63	40	PC Mode W/B (Fixed)
5	Green Offset	Green Offset	0 ~ 63	32	PC Mode W/B (Fixed)
6	Blue Offset	Blue Offset	0 ~ 63	39	PC Mode W/B (Fixed)

4-1-3(G) CXA2101Q-1

No	OSD	Item	Range	Default	Description
1	Sub Bright	Sub Bright	0 ~ 63	51	
2	Limit Level	Limit Level	0 ~ 3	0	Limits the input level (Fixed)
3	System	System	0 ~ 3	1	480p, 720p, 1080i
4	D-Color	D-Color	0 ~ 2	1	Dynamic Color
5	R Drive	R Drive	0 ~ 63	32	DTV W/B (Fixed)
6	G Drive	G Drive	0 ~ 63	32	DTV W/B (Fixed)
7	B Drive	B Drive	0 ~ 63	32	DTV W/B (Fixed)
8	R CutOff	R CutOff	0 ~ 63	32	DTV W/B (Fixed)
9	G CutOff	G CutOff	0 ~ 63	32	DTV W/B (Fixed)
10	B CutOff	B CutOff	0 ~ 63	32	DTV W/B (Fixed)
11	ABL Mode	ABL Mode	0 ~ 3	0	ABL Mode Setting
12	ABL TH	ABL-TH	0 ~ 3	0	Voltage
13	H Sep Sel.	H Sep Sel.	0, 1	0	H-Sync, Separation System
14	Fix Sync.	Fix Sync.	0 ~ 3	0	0 : Auto
15	V Time Con	V Time Constant	0 ~ 3	1	Set the time constant for V-Sync Separation
16	H Width	H Width	0 ~ 3	1	H-Sync Width Adjustment
17	HHD timi Con	H timi Constant	0, 1	0	

4-1-3(H) CXA2101QQ-2

No	OSD	Item	Range	Default	Description
1	HS Mask	HS Mask	0, 1	1	
2	Sub Cont	Sub Contrast	0 ~ 15	7	
3	Sub Color	Sub Color	0 ~ 15	5	
4	Sub Hue	Sub Hue	0 ~ 15	8	
5	Sub SHP	Sub SHP	0 ~ 4	2	
6	R-Y/R	R-Y/R	0 ~ 15	13	13 (PAL), 5(NT)
7	R-Y/B	R-Y/B	0 ~ 15	15	
8	G-Y/R	G-Y/R	0 ~ 15	8	
9	G-Y/B	G-Y/B	0 ~ 15	4	4 (PAL), 8 (NT)
10	PABL Level	PABL Level	0 ~ 15	8	Peak ABL
11	SHP FO	SHP FO	0 ~ 4	2	Sharpness FO Selection
12	Pre/over	Pre/over	0 ~ 3	3	0=Pre. : Over=1:1.3 3=3:1
13	CTI Level	CTI Level	0 ~ 3	1	C Transition Level
14	LTI Level	LTI Level	0 ~ 3	0	Y Transition Level
15	DC-Tran	DC-Tran	0 ~ 3	1	Y DC Transmission Rate
16	D-Pic	D-Pic	0 ~ 3	1	Dynamic Picture

4-1-3(I) PINP CONTROL

No	OSD	Item	Range	Default	Description
1	PIP HPos	PIP HPos	0 ~ 63	6	PinP Horizontal Position
2	PIP VPos	PIP VPos	0 ~ 63	13	PinP Vertical Position
3	Bright YUV	Bright YUV	0 ~ 255	195	Comp. Bright. Level (Fixed)
4	Cont YUV	Cont YUV	0 ~ 63	27	Comp. Bright. Level (Fixed)
5	Luma Delay	Luma Delay	0	0	Y/C Delay
6	3230 Bright	3230 Bright	0 ~ 63	40	
7	3230 Contrast	3230 Contrast	0 ~ 63	38	

4-1-3(J) OSD POSITION

No	OSD	Item	Range	Default	Description
1	Horiz	Horiz(Left, Right)	8 ~ 104	104	Move 8 by 8 (Total : 12 Step), Fixed
2	Vert	Vert(Up, Down)	8 ~ 40	40	Move 8 by 8 (Total : 4 Step), Fixed

4-1-3(K) TEST PATTERN

No	OSD	Range	Default	Description
1	Pseudo Color Bar	0 ~ 15	-	
2	Luma Ramp	0 ~ 15	-	
3	White 16	0 ~ 15	-	
4	White 90	0 ~ 7	-	
5	White 240	0 ~ 15	-	
6	Red	0 ~ 15	-	
7	Green	0 ~ 3	-	
8	Blue	0, 1	-	

4-1-3(L) OPTION TABLE

No	ITEM	Default	Description
1	Rear Jack	Scart	Scart <--> RCA
2	Blue Screen	30	0 → 5 → 10 → 15 → 20 → 25 → 30 → 0
3	Picture Size-Aspect	Last Memory	Wide <--> Last Memory
4	Frame Lock	On	On <--> Off
5	Remocon Pin	01	00 ~ 99
6	Pivot	On	On <--> Off
7	Panel Life Time	-	Indicate total elapsed time

4-1-4 White Balance Adjust Method

1. Press MUTE-1-8-2-POWER to enter the factory mode.
2. Enter PW364A.
3. Adjust LOW coordinates as R, G, OFFSET and HIGH coordinates as R, G, GAIN.(Blue is fixed)
4. Adjust LOW light as Center Offset.
5. Adjust HIGH light as Gain Max.
6. Adjust fine as B-Offset and B-Gain.

- W/B Adjustment SPEC(Suwon Factory Toshiba PATTERN)

➤ VIDEO MODE

Adjustment Coordinates	Coordinates Value	Adjustment Deviation
H-LIGHT	x : 282 y : 296 Y : 24.5[fℓ]	± : 3 ± : 3 ± : 1
L-LIGHT	x : 282 y : 296 Y : 0.95[fℓ]	± : 5 ± : 5 ± : 0.1

➤ PC MODE

Adjustment Coordinates	Coordinates Value	Adjustment Deviation
H-LIGHT	x : 282 y : 296 Y : 15[fℓ]	± : 3 ± : 3 ± : 1
L-LIGHT	x : 282 y : 296 Y : 0.33[fℓ]	± : 5 ± : 5 ± : 0.05

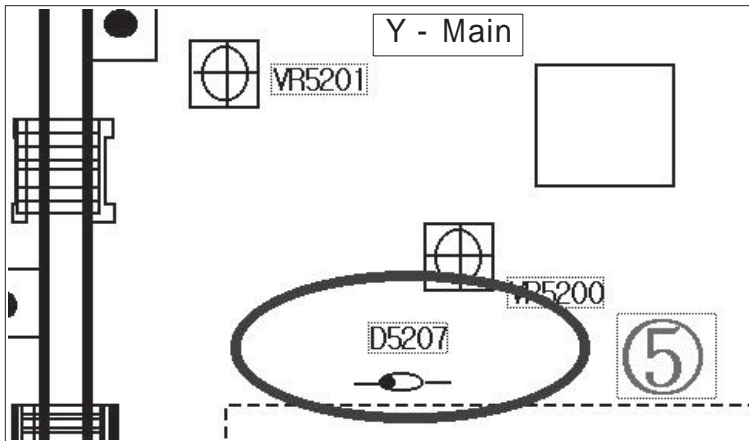


NO	HRes	VRes	HFreqSes	VTotal	H_P	V_P	Dot_c	HS1Period	HFreqSec	f0(Hz)	CLOCK/ PHASE	Factory HP/VP/P	USER V-Position
1	720	400	31.777	449	0	1	28.232	31.777u/10.1n=3146.2	/99=31.777	70.1	125/22/0/0	125/22/0/0	
2	640	350	31.777	449	1	0	25.175	31.777u/10.1n=3146.2	/99=31.777	70.0	125/16/0/0	125/16/0/0	
3	640	480	23.111	509	0	0	36.0	=2288.21	=23.111	85	125/8/0/1	125/8/0/1	
4	640	480	26.667	500	0	0	31.5	=2640.29	=26.666	75	124/31/0/0	124/31/0/0	
5	640	480	26.413	520	0	0	31.5	=2615.14	=26.414	72.8	125/31/0/0	125/31/0/0	
6	640	480	31.777	525	0	0	25.175	=3146.23	=31.777	59.9	125/2/0/0	125/2/0/0	
7	800	600	18.631	631	1	1	56.25	=1844.65	=18.626	85.1	125/9/1/2	125/9/1/2	
8	800	600	21.333	625	1	1	49.5	=2112.17	=21.333	75	125/0/0/1	125/0/0/1	
9	800	600	20.800	666	1	1	50.0	=2059.4	=20.797	72.2	125/31/0/2	125/31/0/2	
10	800	600	26.400	628	1	1	40.0	=2613.86	=26.393	60.3	125/15/0/1	125/15/0/1	
11	800	600	28.444	625			36.0	=2816.23	=28.444	56.3	126/1/0/1	126/1/0/1	
12	1024	768	14.561	808	1	1	94.5	=1441.68	=14.555	85	126/14/2/3	126/14/2/3	
13	1024	768	16.660	800	1	1	78.75	=1649.50	=16.656	75	125/20/1/3	125/20/1/3	
14	1024	768	17.707	806	0	0	75.000	=1753.16	=17.707	70.1	125/21/1/3	125/21/1/3	
15	1024	768	20.677	806	0	0	65.000	=2047.22	=20.676	60	125/16/1/2	125/16/1/2	

4-3 Discharge Voltage Adjustment Method (Monitor) in Times of ASS'Y Repair and Replacement

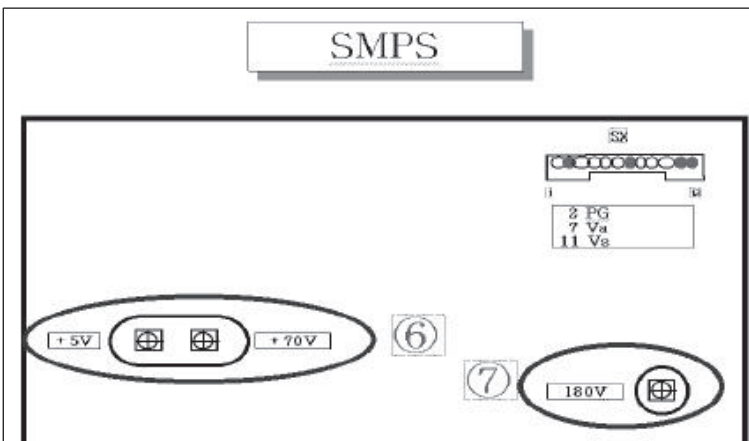
-All VR (Variable Resistor), except for VR for Vs, voltage goes down when turned counterclockwise.

● Vsc and Vy Adjustment Method



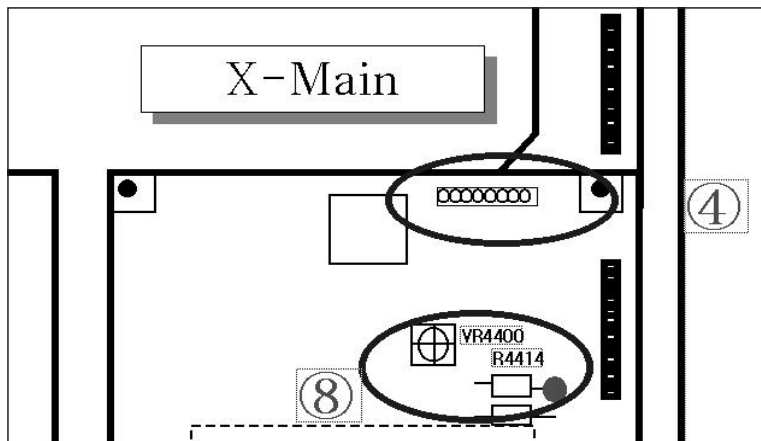
- Vsc is the voltage of the left terminal for D5207
- Voltage adjustment is made for Vsc by using VR5201
- Standard voltage for Vsc is $-55V \pm 10V$
- Vy is the voltage of the right terminal for D5207
- Voltage adjustment is made for Vy by using VR5200
- Standard voltage for Vy is $132V \pm 10V$

● Vs and Va Adjustment Method



- Vs is the voltage of the no.11 PIN of SX Connector.
- Voltage adjustment is made for Vs by using VR in 7
- Vs is $175 \pm 5V$
- Va is the voltage of the no.7 PIN of SX Connector.
- Voltage adjustment is made for Va by using right VR in 6
- Va is $75 \pm 5V$

● Vw Adjustment Method

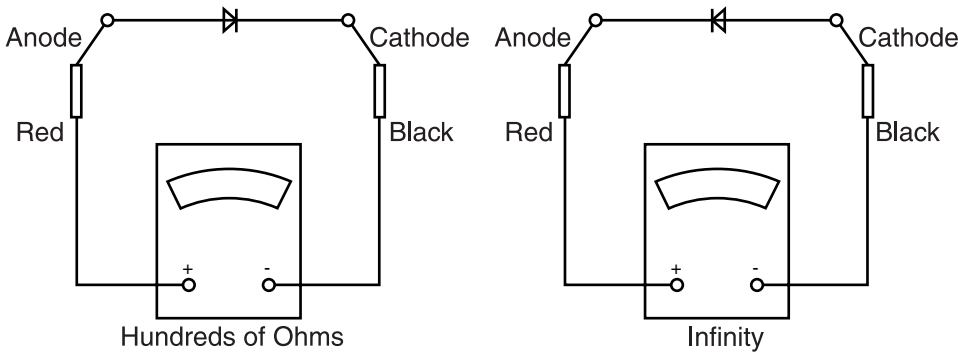


- Vw is the voltage of the right terminal for R4414
- Voltage adjustment is made for Vw by using VR4400
- Standard voltage for Vw is $175V \pm 5V$

4-4 Fault Finding Using MULTI METER

Parts defects can be found for DIODE TRANSISTOR IC, using MULTI TEST including Forward/Reverse direction Multi Test. Of course, in case resistance of several ohms and COIL are connected in parallel circuit, the lock out circuit parallel connected to part must be severed.

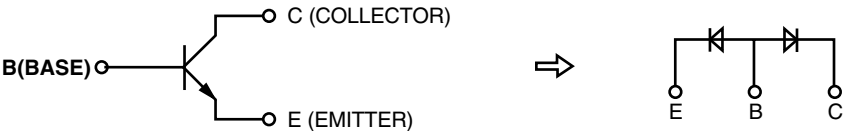
1. DIODE



	Forward Direction	Reverse Direction
Between Anode and Cathode	Hundreds of ohms	Infinity

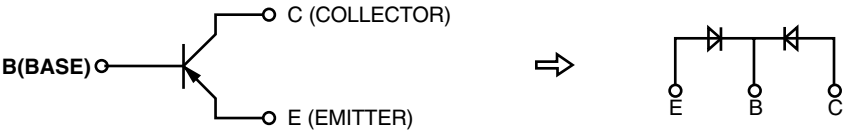
2. TRANSISTOR

- For NPN(KSC815-Y, 2SC2068, 2SC2331-Y)



	Forward Direction	Reverse Direction
Between B and E	Hundreds of ohms	Infinity
Between B and C	Hundreds of ohms	Infinity
Between E and C	Infinity	Infinity

- For PNP(KSA539-Y)



	Forward Direction	Reverse Direction
Between B and E	Hundreds of ohms	Infinity
Between B and C	Hundreds of ohms	Infinity
Between E and C	Infinity	Infinity

3. IC (INTEGRATED CIRCUIT)

IC has built in DIODE against overvoltage in PIN. Generally, except for internal circuit defects, IC defects can be found, by measuring the DIODE.

Forward Direction	Hundreds of ohms
Reverse Direction	Varying depending on IC but generally normal
	Infinity in DIODE TEST MODE

* Defects have SHORT(0 ohm) for both forward and reverse direction.

5. Circuit Description

5-1 Power supply

5-1-1 Outline(PDP SMPS)

Considering various related conditions, the switching regulator with good efficiency and allowing for its small size and lightweight was used as the power supply for PDP. Most of the power supply components used forward converter, and Vsamp and Vsb used simple flyback converter.

To comply with the international harmonics standards and improve the power factor, active PFC (Power Factor Correction) was used to rectify AC input into +400V DC output, which in turns used as input to the switching regulator.

5-1-2 42"SD SMPS SPECIFICATION

5-1-2(A) INPUT

PDP-42PS board is designed so that input power can be used within AC 90 VAC to 264 VAC with 50/60Hz \pm 3Hz.

5-1-2(B) OUTPUT

PDP-42PS board provides 13 output switching power supplies for PDP 50inch (+165Vs, +220Set, +185Ve, +75Va, +80Scan, +18Vg, +5Vsb, +5V(D), +5V(A), +12V, +9V, +12Vfan, and +12Vsamp). The output voltage, and current requirements for continuous operation are stated below (Table 3).

Table1. Specifications of Output Power Supplies for PDP SMPS

Output Name	Output Voltage	Output Current	Using in PDP driving
Vs	+165V	1.4A	Sustain Voltage of Drive Board
Va	+75V	0.5A	Address Voltage of Drive Board
Vscan	+80V	0.05A	
Vset	+220V	0.05A	
Ve	+185V	0.05A	
Vg	+18.3V	0.3A	
Vfan	+12V	0.8A	
V9	+9V	0.3A	
V5(A)	+5V	1.0A	Analog IC Drive Voltage of Video Board
V5(D)	+5.3V	3.5A	IC Drive Voltage of Logic Board
Vsb	+5V	0.4	Stand-by for Remote Control
V12	+12V	1.2A	
Vsmp	+12V	1.5A	

Table 2. Specifications to Protect PDP SMPS

Division	OCP Current	OVP Voltage	Short Circuit
Vs	5A	195V	O.K
Va	2A	90V	O.K
+5V	10A	6.2V	O.K

5-1-2(C) FUNCTION OF BOARD

(1) Remote control

Using 250V / 10A relay, the board makes remote control available.

(2) Free voltage

The board designed so that input voltage can be used within 90 VAC to 264VAC.

(3) Embedded thermal sensor

The board is equipped with thermal sensor to detect the internal temperature of the unit, and to short relay when the internal temperature is higher than specified temperature so as to shutdown the unit.

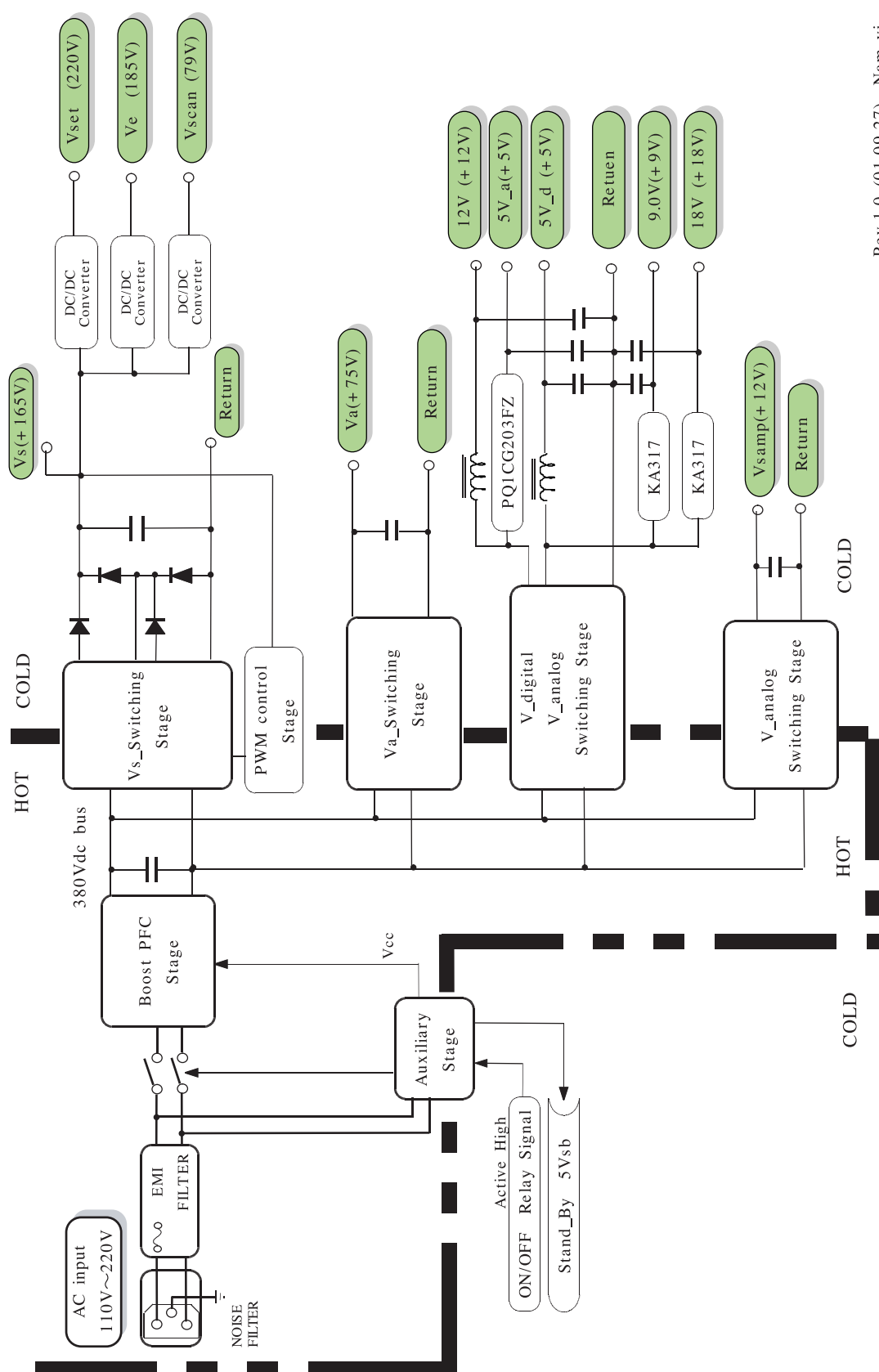
(4) Improvement of power factor

The board is designed using PFC circuit so that PF (Power Factor) can be over 0.95, because low PF can be a problem in high voltage power.

(5) Protection

The OCP (Over Current Protection), the OVP (Over voltage Protection), and the Short Circuit Protection functions are added against system malfunction.

5-1-2(D) PDP-PS-42 BLOCK DIAGRAM



Rev.1.0 (01.09.27) Nam_yi

(1) AC-DC Converter

PDP-42PS outputs +400V DC from the common AC power supply using the active PFC booster converter. This converter is designed for improving the power factor and preventing the noise with high frequency and finally becomes the input power system for the switching regulator on the output side.

(2) Auxiliary Power Supply

The auxiliary power supply is a block generating power of •I-com for remote controlling. Once the power plug is inserted, this block always comes into operation, causing •I-com to get into the stand-by state for the output. Thus, this output is called the stand-by voltage. And with the relay ON signal inputted through the remote controller, this block turns the mechanical switch of relay to ON for driving the main power supply.

(3) Implementation of Sustain Voltage

As the main part of a SMPS for PDP, sustain voltage must supply a high power, +165V/ 1.4A. It is designed using forward converter basically. At the output stage two 90V converters are connected serially for high efficiency and reduction of system size against a single 180V converter.

(4) Implementation of Small Power Output (Va, V(D), V(A), Vfan, V9, Vsamp, Ve, Vset, Vscan, V12, and Vg)Vset, Ve, and Vscan used DC-DC module. V(D), Va, V12, and Vfan used forward converter, and Vsamp used flyback converter. V(A), V9, and Vg are simply implemented using switching regulator.**5-1-3 Requirements of PDP SMPS**

Since SMPS does not operate alone, but it operates with the load of the whole system, it should be designed carefully considering the load of the system. In addition, it should be designed considering emerging issues such as EMC, and protection against heat as well as system stability especially.

5-1-3(A) SAFETY AND REMOTE CONTROL CAPABILITY

Stability is one of the most important requirements for SMPS. SMPS should be designed to prevent abnormal status due to abnormal load variation so as to keep the system stable, and guarantee customer safety.

The protection circuits of SMPS include over-current protection (OCP), over voltage protection (OVP), and under voltage lock-out (UVLO), and short circuit protection circuit. Although each circuit can be implemented by various procedures, the most popular is implementing with comparator that compares current value with that of standard and determine abnormality of the circuit.

In addition, surge current protection, insulation management, and static electricity protection circuit should be added, because it uses commercial power source as an input.

PDP SMPS should be designed using auxiliary power and relay to provide remote control capability.

5-1-3(B) THE RELATION BETWEEN POWER CONSUMPTION AND POWER CONVERSION Efficiency

The power consumption and the power conversion efficiency of SMPS affect protection against heat and system operation much.

[If the power conversion efficiency of 100W SMPS is 70%, is the power loss of internal circuit 30W?]

Output power consumption P_o is determined by the multiplication of DC output voltage V_o and output current I_o . Input power consumption P_i is determined by the addition of output power consumption P_o and internal power loss of SMPS P_L .

Provided that the power conversion efficiency is η ,

$$P_i = P_o + P_L$$

$$\eta = \frac{P_o}{P_i} \quad \text{----- Equation (1)}$$

$$P_L = \left(\frac{1}{\eta} - 1\right) \cdot P_o$$

If the power conversion efficiency of 100W SMPS is 70%, the internal power loss is about 42.8W by Equation (1). If the power conversion efficiency of 400W SMPS for 42"SD is 82%, the internal power loss is 87.8W by Equation (1). Table 4 shows internal power loss as a function of output power for various power conversion efficiencies.

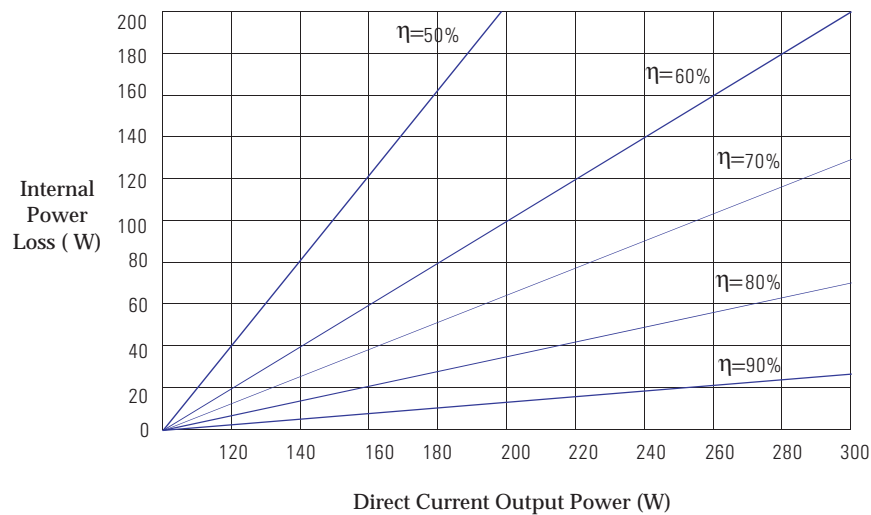


Table 4. Power Conversion Efficiency vs. Internal Power Loss

5-1-3(C) PFC (Power Factor Correction) Circuit Descriptions

The current electric devices use DC power supply and require a rectifier circuit converting AC into DC. As most rectifier circuits apply a capacitor input type, the rectifier circuit becomes the core of the occurrence of harmonics with lower reverse rate. If various electronic and electric devices are connected to a power system, high-frequency current will occur due to a power rectifier circuit, a phase control circuit with power input current of non-sine wave, or components with non-linear load characteristics, such as capacitor, inductor, etc. As the result, the disturbance of voltage occurs, and finally a power capacitor or a transformer generates heat, fire or noise occurs, controls malfunction, or the accessed devices abnormally operate or their lives are shortened. To prevent those symptoms, IEC (International Electrotechnical Commission) regulated standards for Power Supply Harmonics. (Refer to IEC 1000-3-2.) Figure 8 shows the basic structure of Active Boost PFC and waveforms.

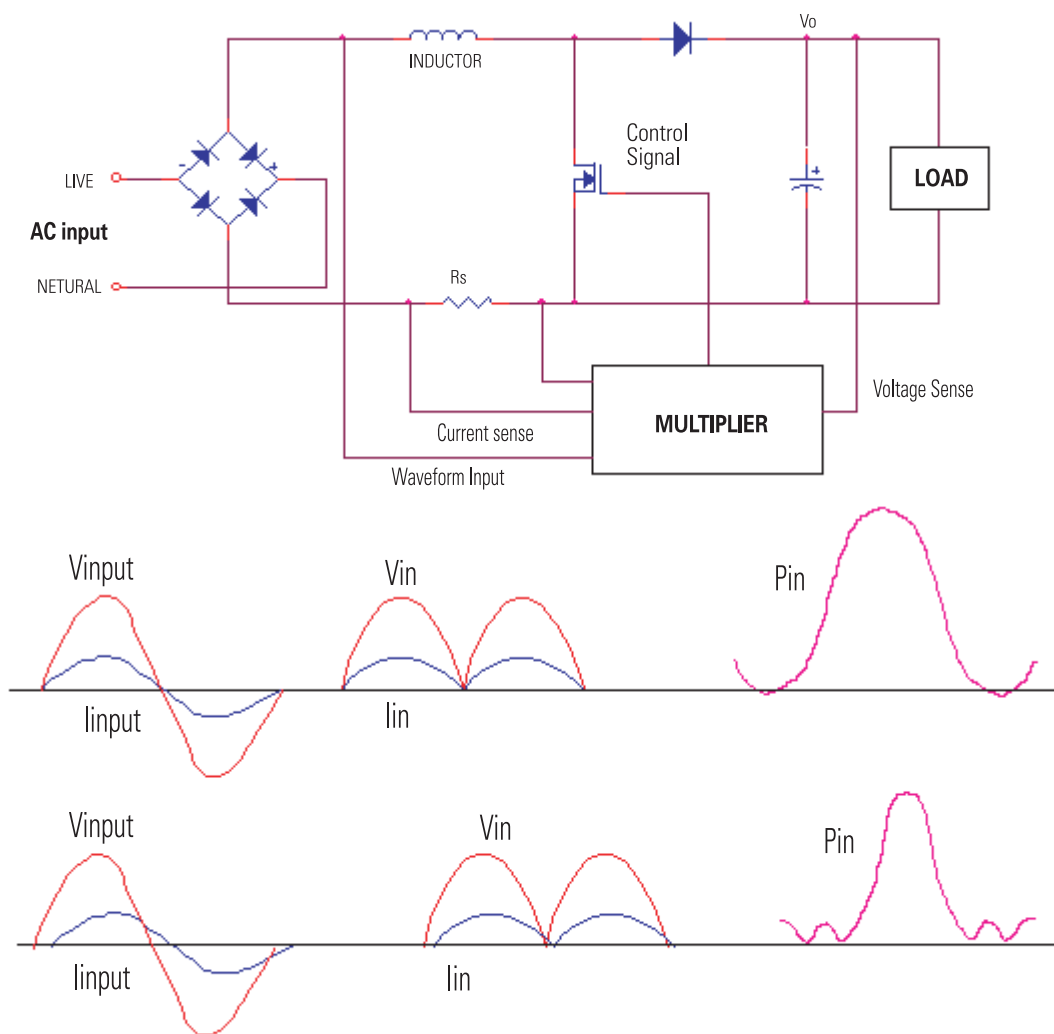
Standards for Power Supply Harmonics

Scale: Devices accessed to 220V/380V, 230V/400V, 240V/425V and lower than 16A (IEC 100-3-2)
 Devices with AC 230V and lower than 16A (IEC 555-2)

Applied Classes :

- ♣ Class A : Devices not included in another class
- ♣ Class B : Portable tools
- ♣ Class C : Lighting devices
- ♣ Class D : Devices with special current waveforms

Application Schedule : Except the devices less than rating input of 75W (1996~1999)
 Except the devices less than rating input of 50W (2000 and after)



The architecture and the pulse of active boost PFC

5-1-3(D) CONCLUSION

Although SMPS (Switching Mode Power Supply) enables small lightweight high-power consumption power design, it is hard to be used when stability and precise control are required. Power stage for PDP can be designed using the lightweight SMPS feature. It is important to design SMPS considering system load, stability, and related international standards.

5-2 Driver Circuit

5-2-1 Driver Circuit Overview

5-2-1(A) WHAT IS THE DEFINITION OF DRIVE CIRCUIT?

It is a circuit generating an appropriate pulse (High voltage pulse) and then driving the panel to implement images in the external terminals (X electrode group, Y electrode group and address electrode), and this high voltage switching pulse is generated by a combination of MOSFET's.

5-2-1(B) PANEL DRIVING PRINCIPLES

In PDP, images are implemented by impressing voltage on the X electrode, Y electrode and address electrode, components of each pixel on the panel, under appropriate conditions. Currently, ADS (Address & Display Separate: Driving is made by separating address and sustaining sections) is most widely used to generate the drive pulse. Discharges conducted within PDP pixels using this method can largely be classified into 3 types, as follows:

- (1) Address discharge : This functions to generate wall voltage within pixels to be lighted by addressing information to them (i.e., impressing data voltage)
- (2) Sustain discharge : This means a display section where only pixels with wall voltage by the address discharge display self-sustaining discharge by the support of such wall voltage. (Optic outputs realizing images are generated.)
- (3) Erase discharge : To have address discharge occur selectively in pixels, all pixels in the panel must have the same conditions (i.e., the same state of wall and space electric discharges). The ramp reset discharge section, therefore, is important to secure the drive margin, and methods most widely used to date include wall voltage controlling by ramp pulse.

5-2-1(C) TYPES AND DETAILED EXPLANATION OF DRIVE DISCHARGES

(1) Sustaining discharge

Sustaining discharge means a self-sustaining discharge generated by the total of the sustaining pulse voltage (usually, 160~170V) alternately given to X and Y electrodes during the sustaining period and the wall voltage that varies depending upon pixels' previous discharge status. It is operated by the memory function (through this, the current status is defined by previous operation conditions) AC PDP basically possesses. That is, when there is existing wall voltage in pixels (in other words, when pixels remain ON), the total of wall voltage and a sustaining voltage to be impressed subsequently impresses a voltage equal to or above the discharge start voltage, thereby generating discharge again, but when there is no existing wall voltage in pixels (in other words, when pixels remain OFF), the sustaining voltage only does not reach the discharge start voltage, thus causing no discharge. The sustaining discharge is a section generating actual optic outputs used in displaying images.

(2) Address discharge

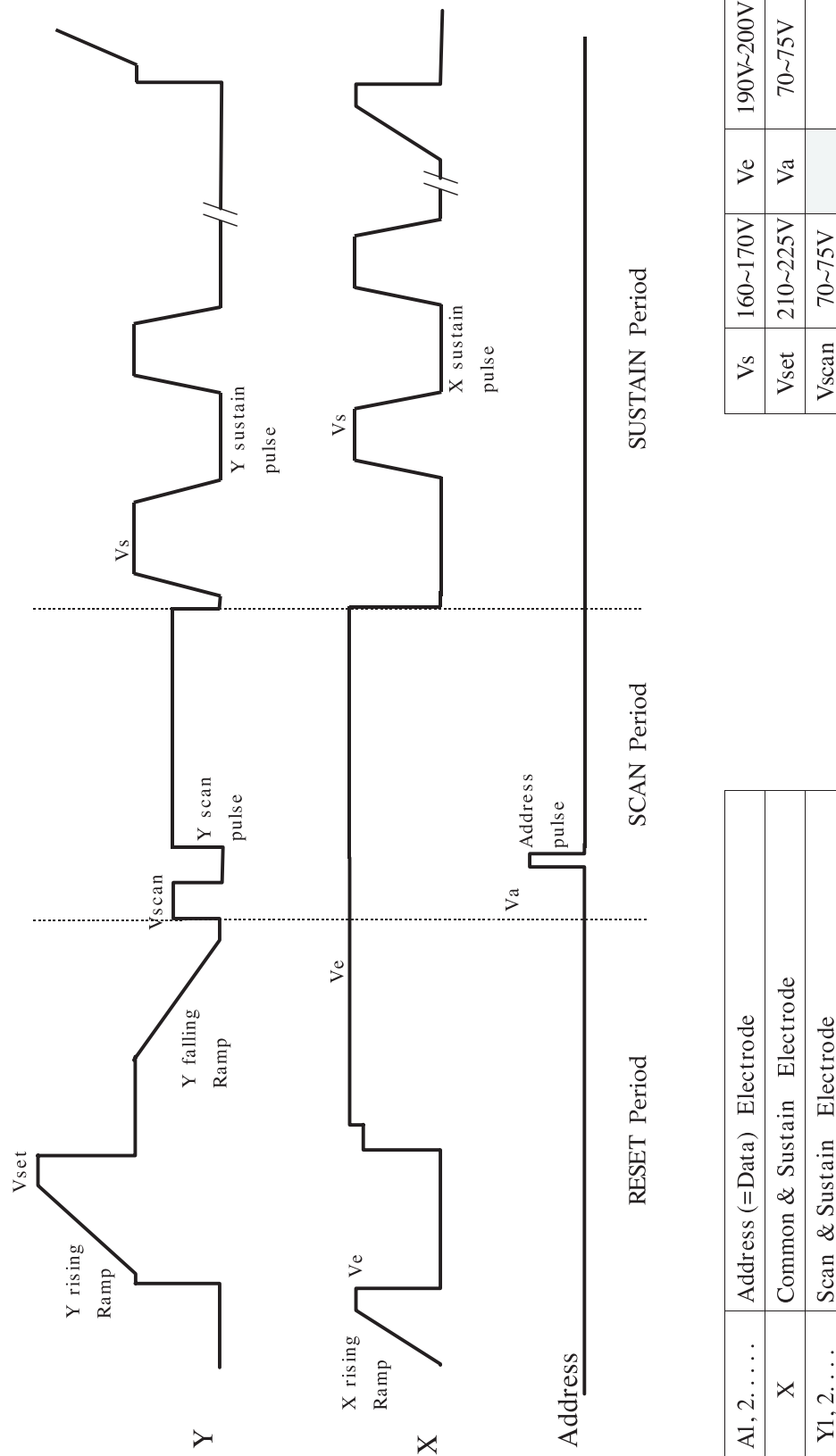
This means a discharge type generated by the difference between positive voltage of the address electrode (normally 70~75V determined by supplied V_a voltage + positive wall charge) and the negative potential of Y electrode (supplied GND level voltage + negative wall charge). The address discharge serves to generate wall voltage in pixels where images are to be displayed (that is, discharge is to be generated) prior to the sustaining discharge section. Namely, pixels with wall voltage by the address discharge will generate sustaining discharge by the following sustaining pulses.

(3) Erase discharge

The purpose of resetting or erase discharge is to make even wall voltage in all pixels on the panel. Wall voltage, which may vary depending upon the previous sustaining discharge status, must be made even. That is, wall voltage generated by the sustaining discharge must surely be removed, by making discharges and then supplying ions or electrons. Wall voltage can be removed by making discharges and then setting a limitation on time for opposite polarity charging of the wall voltage or generating weak discharge (Low voltage erasing) to supply an appropriate quantity of ions or electrons and keep polarities from being charged oppositely. The weak discharge (Low voltage erasing) methods, which have been known to date, can largely be into two types: 1) the log pulse adopted by most companies including F Company, and 2) the ramp pulse adopted by Matsushita. In both two methods, impression is made with a slow rising slope of the erasing pulse. Because the total of the existing wall voltage and a voltage on the rising pulse must be at least the drive start voltage to generate discharges, external impressed voltage is adjusted based on the difference in wall voltage between pixels. And, weak discharge is generated because of a small impressed voltage.

5-2-2 SPECIFICATION OF DRIVE PULSES

5-2-2(A) DRIVE PULSES



5-2-2(B) FUNCTIONS OF PULSES

(1) X rising ramp pulse

Just before X rising ramp pulse is impressed, the last Y electrode sustain pulse of previous sub field is impressed. The pulse causes sustain discharge. Consequently, positive wall charge is accumulated in X electrode, and negative wall charge is accumulated in Y electrode. X rising ramp erases wall charge produced by the last sustain discharge pulse using weak-discharge.

(2) Y rising ramp pulse

During Y rising ramp period, weak-discharge begins when external voltage of about 390V~400V is impressed to Y electrode, and each gap voltage is equal to discharge start voltage. Sustaining the weak-discharge, positive wall charge is accumulated in X electrode and address electrode, and negative wall charge is accumulated in Y electrode of the entire panel.

(3) Y falling ramp pulse

During Y falling ramp period, the negative wall charge in Y electrode accumulated by 200V of X bias is used to erase positive wall charge in X electrode. Address electrode (0V) sustains most of the positive electric charge accumulated during rising ramp period so that it can maintain wall charge distribution beneficial to the upcoming address discharge.

(4) Y scan pulse

This is called the scan pulse, selecting each of Y electrodes on a one-line-at-a-time basis. In this case, Vscan means the scan bias voltage. About 70 V (Vscan) voltage is impressed on the selected electrode lines, while 0 V (GND) voltage is impressed on the other lines.

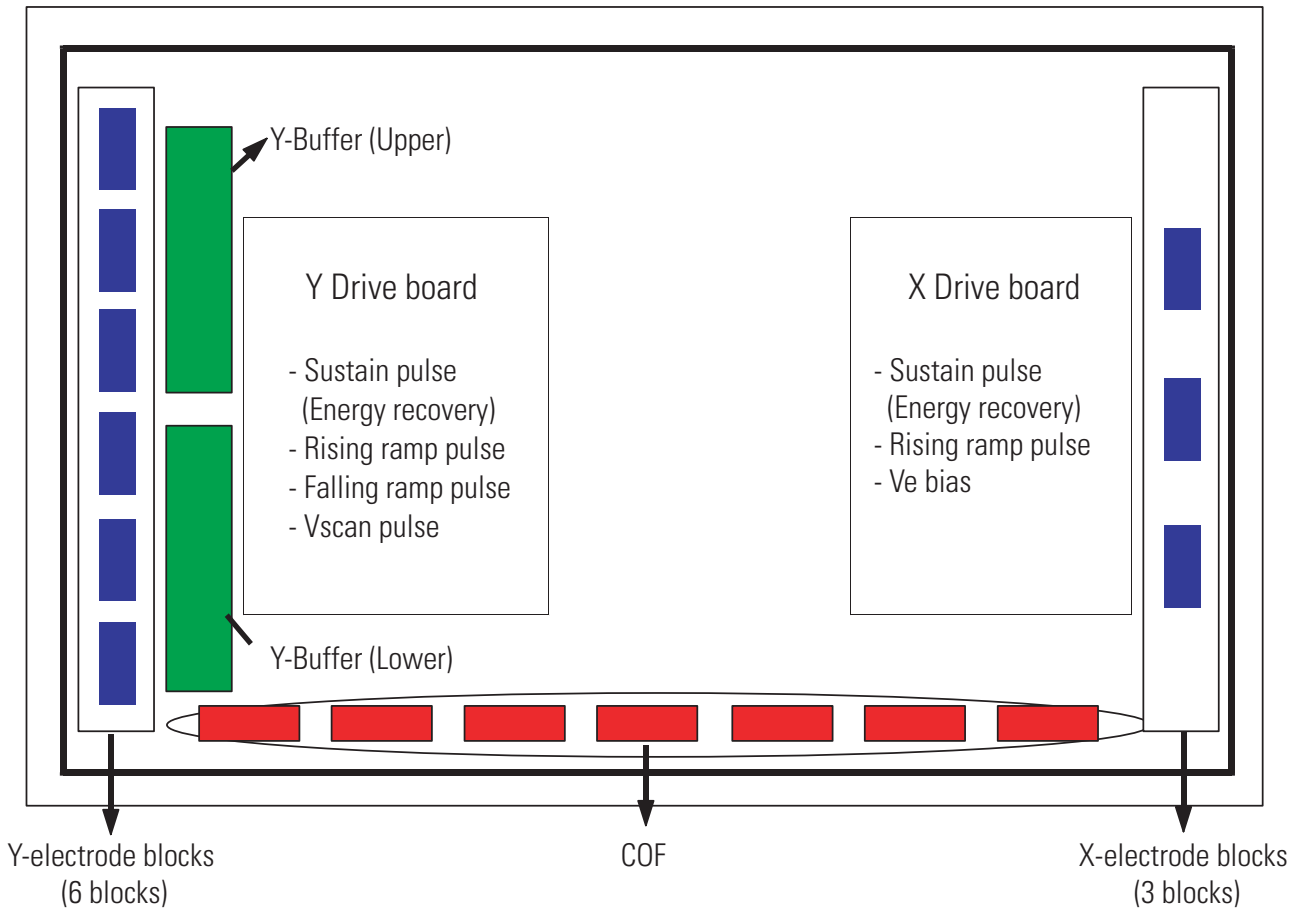
In the cells the address pulse (70V~75V) is impressed on, address discharge is occurred because negative wall charge is accumulated in Y electrode, positive wall charge is accumulated in address electrode by the applied ramp pulse, and the sum of impressed voltage is greater than discharge start voltage. Thus, because scan pulse and data pulse are impressed line by line, very long time is taken for PDP addressing.

(5) 1st sustain pulse

The sustaining pulse always begins with the Y electrode. This is because when address discharge is generated, positive wall voltage is generated on the Y electrodes. Because wall electric charge generated by address discharge is generally smaller than wall voltage generated by sustaining discharge, initial discharges have small discharge strength, and stabilization is usually obtained after 5~6 times discharges, subject to variations depending on the structure and environment of electrodes. The purpose of impressing the initial sustaining pulses long is to obtain stable initial discharges and generate wall electric charges as much as possible.

5-2-3 Configuration and Operation Principles of Driver Circuit

5-2-3(A) FUNCTIONS OF EACH BOARD



(1) X board

X board is connected to the panel's X-electrode blocks, 1) generates sustain voltage pulse (including ERC), 2) generates X rising ramp pulse, and 3) sustains Ve bias during scan period.

(2) Y board

Y board is connected to the Y-electrode blocks of panel, 1) generates sustain voltage pulse (including ERC), 2) generates Y rising and falling ramp pulse, and 3) sustains Vscan bias.

(3) Y buffer board (upper and lower)

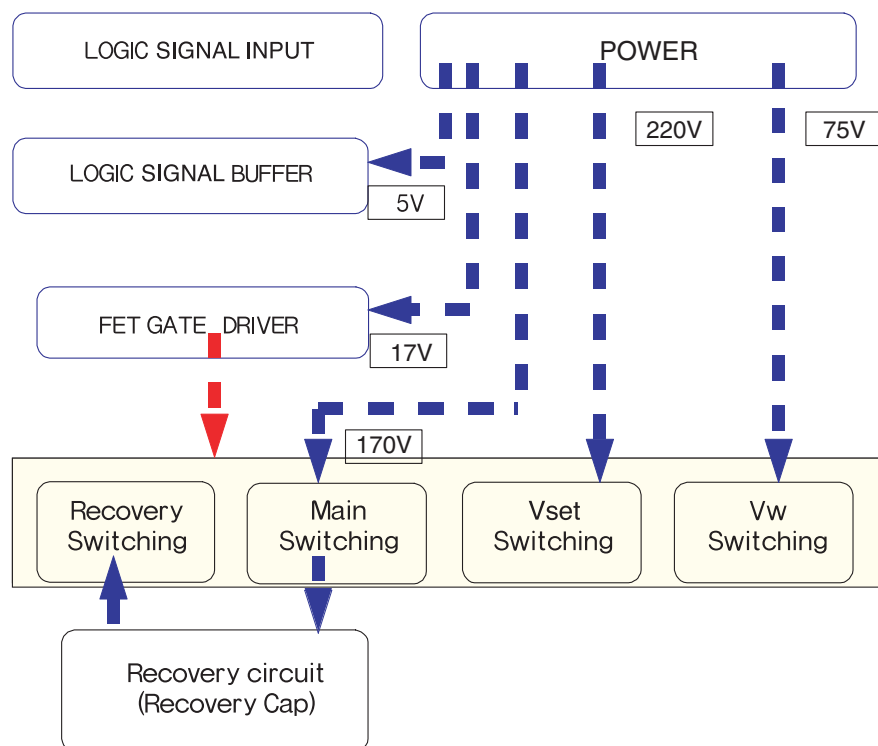
Y buffer board impresses scan pulse to Y electrodes, and consists of upper and lower sub-boards. In case of SD class, one board is equipped with 4 scan driver IC's (STMicroelectronics STV7617 with 64 or 65 outputs).

(4) COF

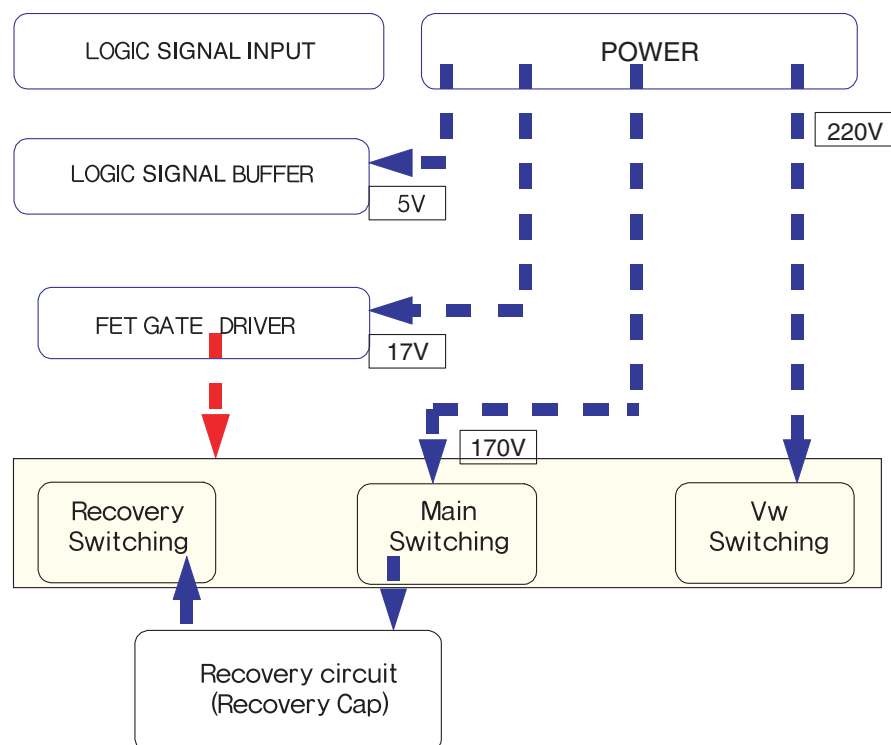
Impresses Va pulse on address electrodes in the address section and generates address discharge based on a difference between such Va pulse and scan pulse impressed on Y electrodes. It is in the form of COF, and a COF is equipped with 4 data drive IC's (STMicroelectronics STV7610A with 96 outputs). For a single scan, 7 COF's are required.

5-2-3(B) DRIVING BOARD'S BLOCK DIAGRAM

(1) Y



(2) X



➤ Components of driving board's operations

1. Power supply

1) Supplied from the power supply board

- For sustaining discharge: 180V;
- For logic signaling buffer: 5V; and
- For gate driver IC: 15V.

2) Generated by the internal DC/DC part

- For generating Vw pulse: 180V.

2. Logic signal

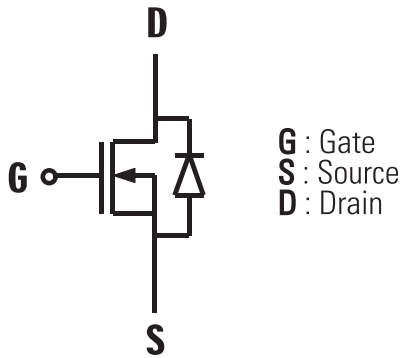
1) Supplied from the logic board

- Gate signals for FETs.

5-2-3(C) PRINCIPLES OF FET'S OPERATION AND HIGH VOLTAGE SWITCHING

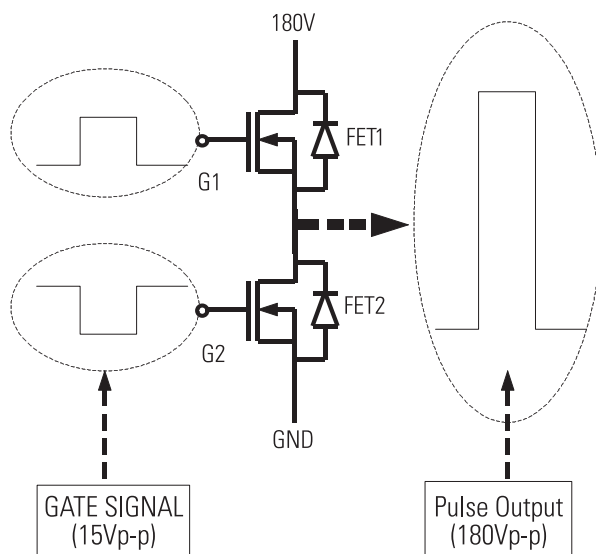
□ FET's operation principles

■ FET's operation principles



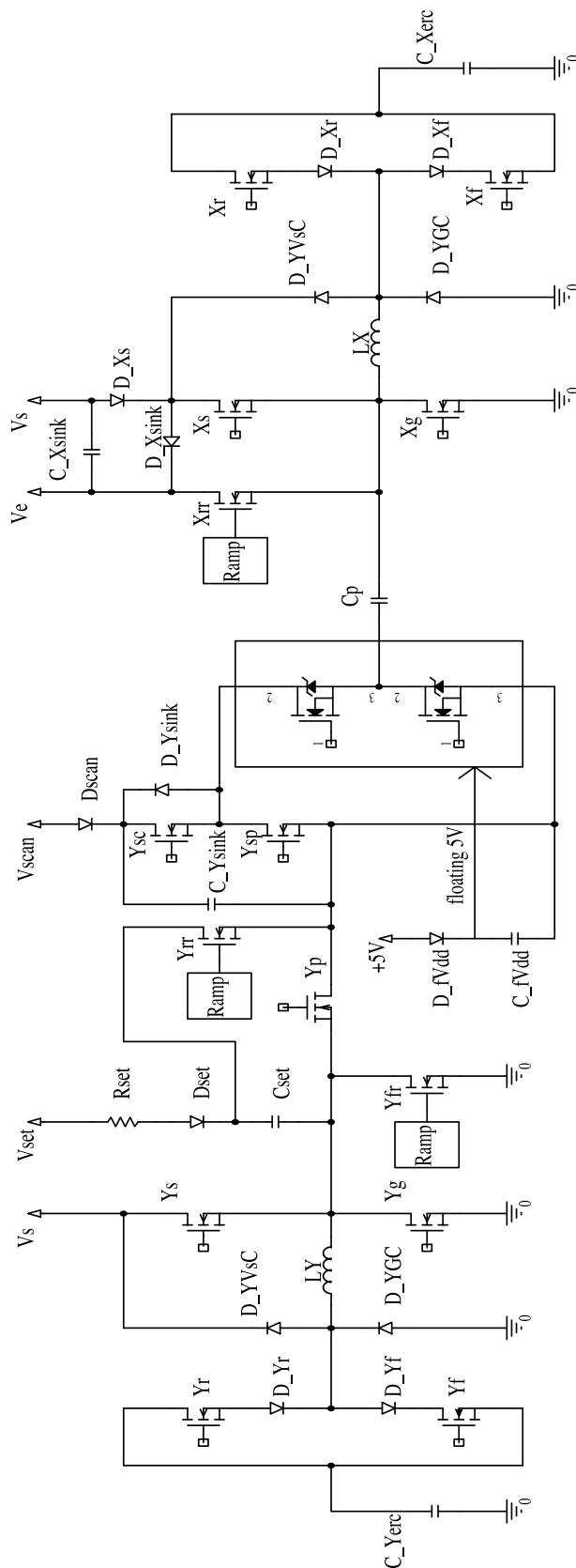
- (1) With signal impressed on the gate (Positive voltage), FET gets short-circuited (a conducting wire of zero (0) resistance); and
- (2) With no signal impressed on the gate (GND), FET gets open-circuited (a non-conducting wire of ∞ resistance).

□ FET's high voltage switching principles

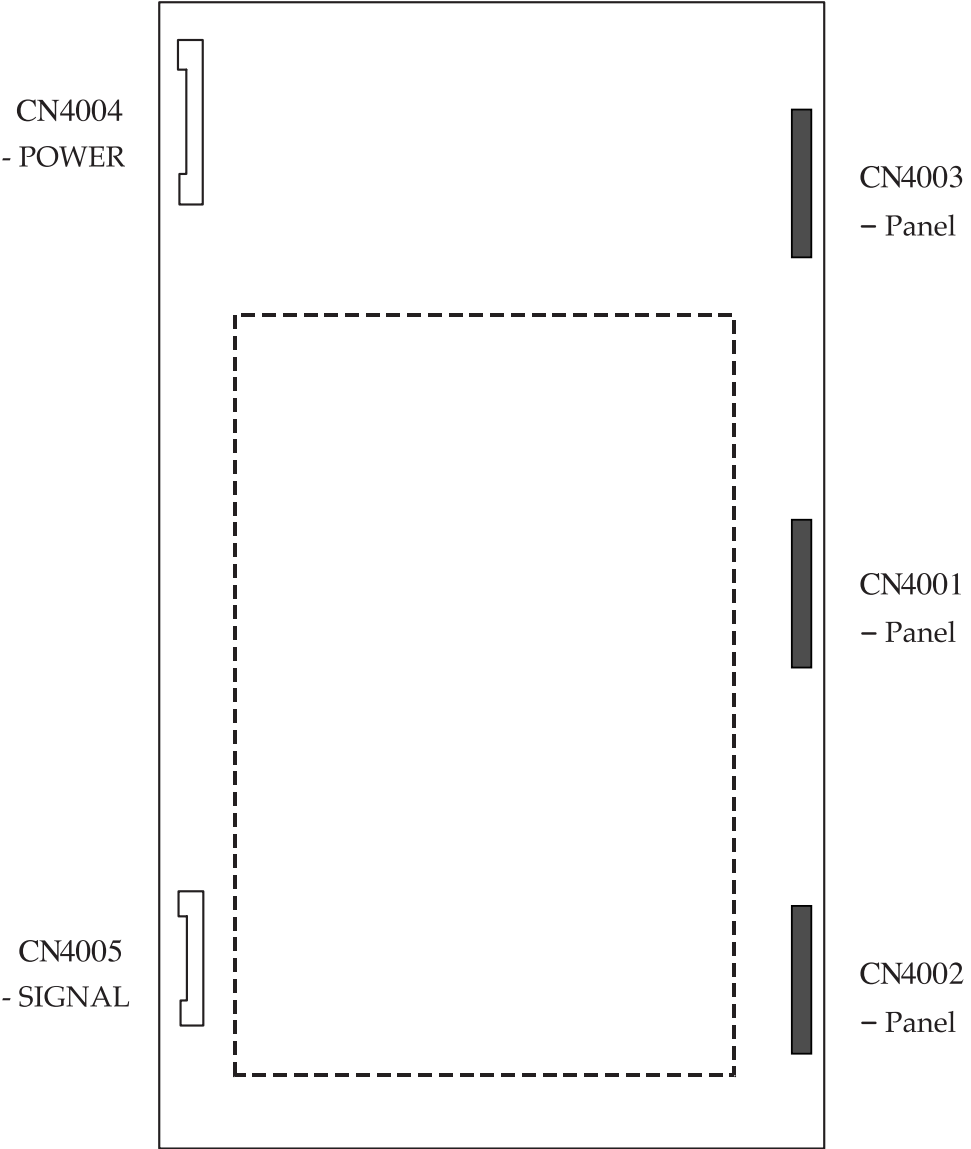


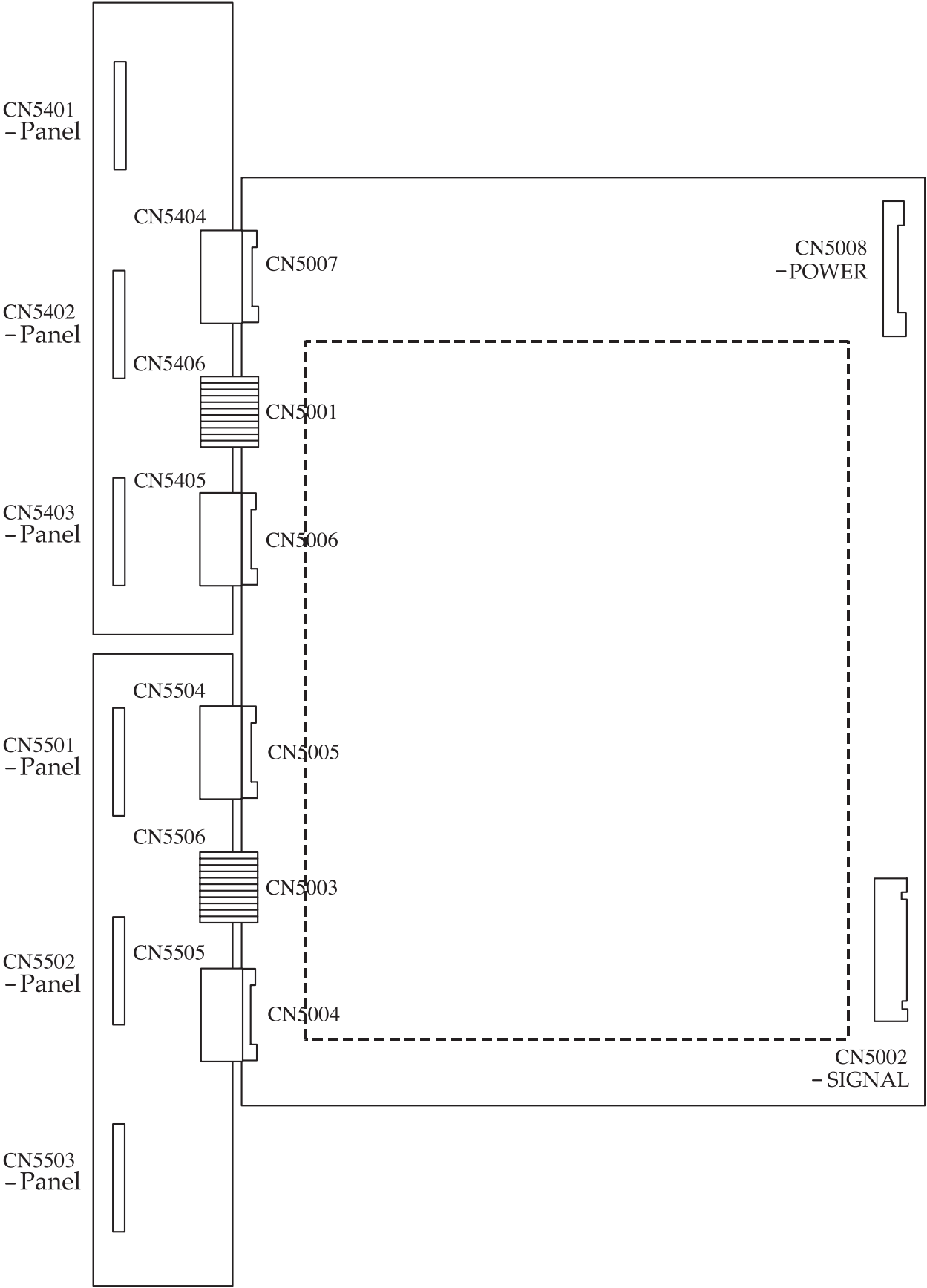
- (1) With no signal impressed on G1, FET1 gets open-circuited, and with signal impressed on G2, FET2 gets short-circuited, thereby causing GND to be outputted to output terminals.
- (2) With signal impressed on G1, FET1 gets short-circuited, and with no signal impressed on G2, FET2 gets open-circuited, thereby causing 180V to be outputted to output terminals.

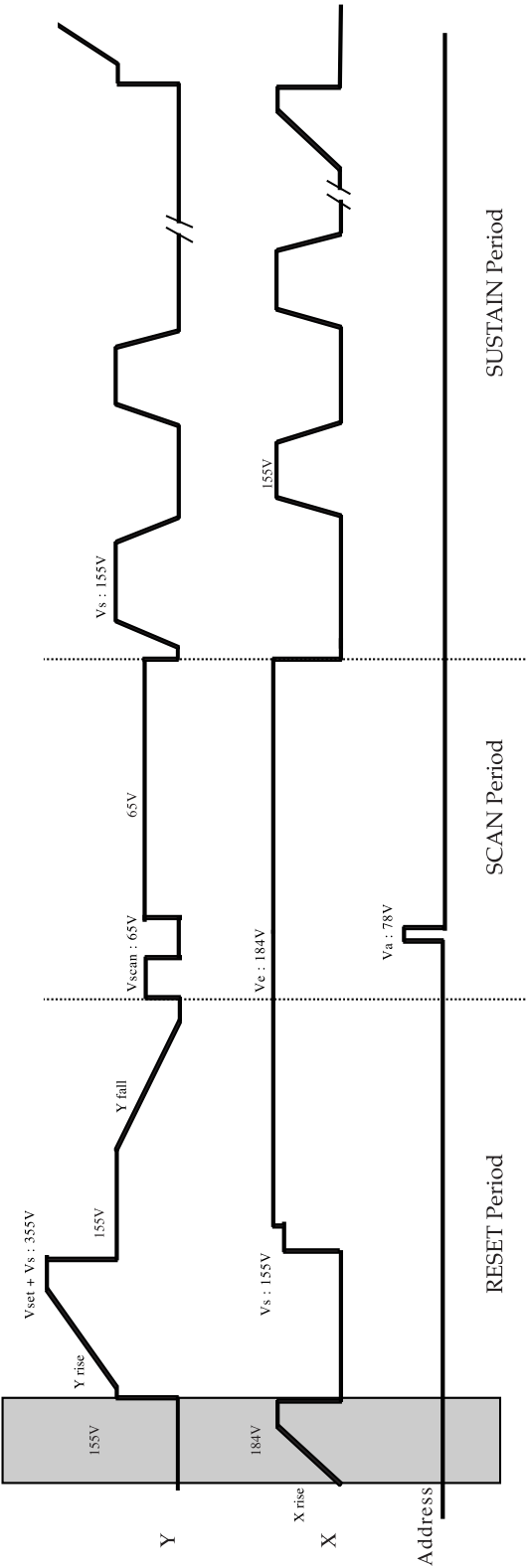
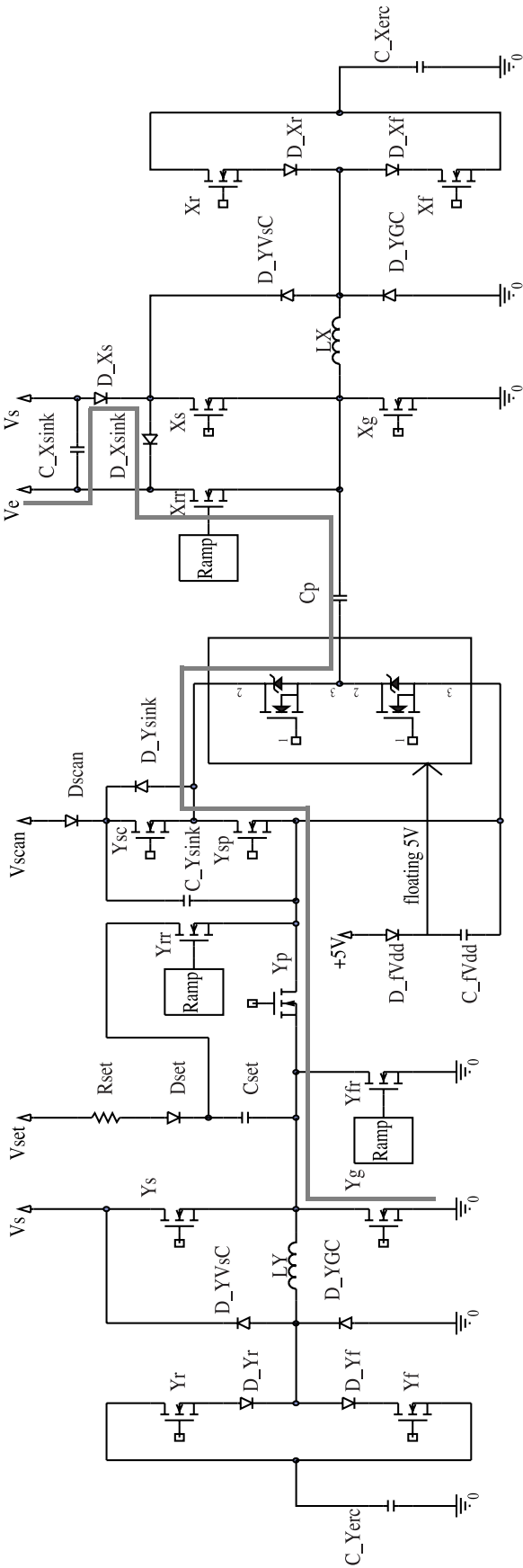
5-2-3 (D) DRIVER CIRCUIT DIAGRAM

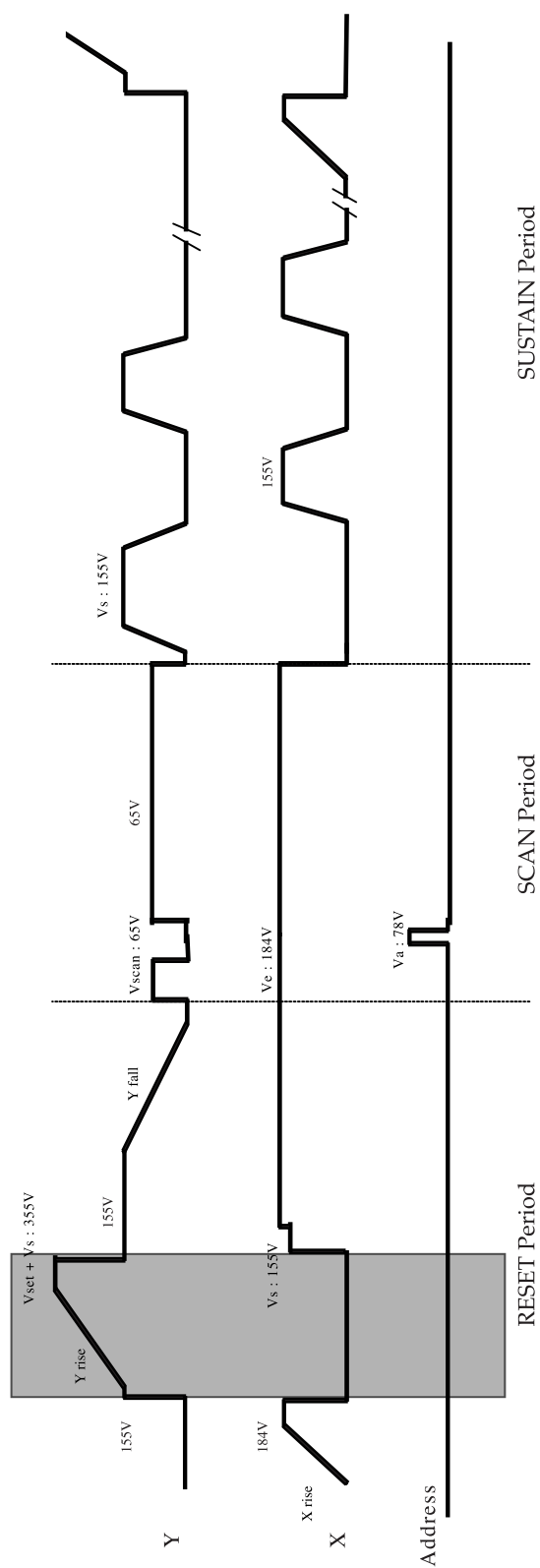
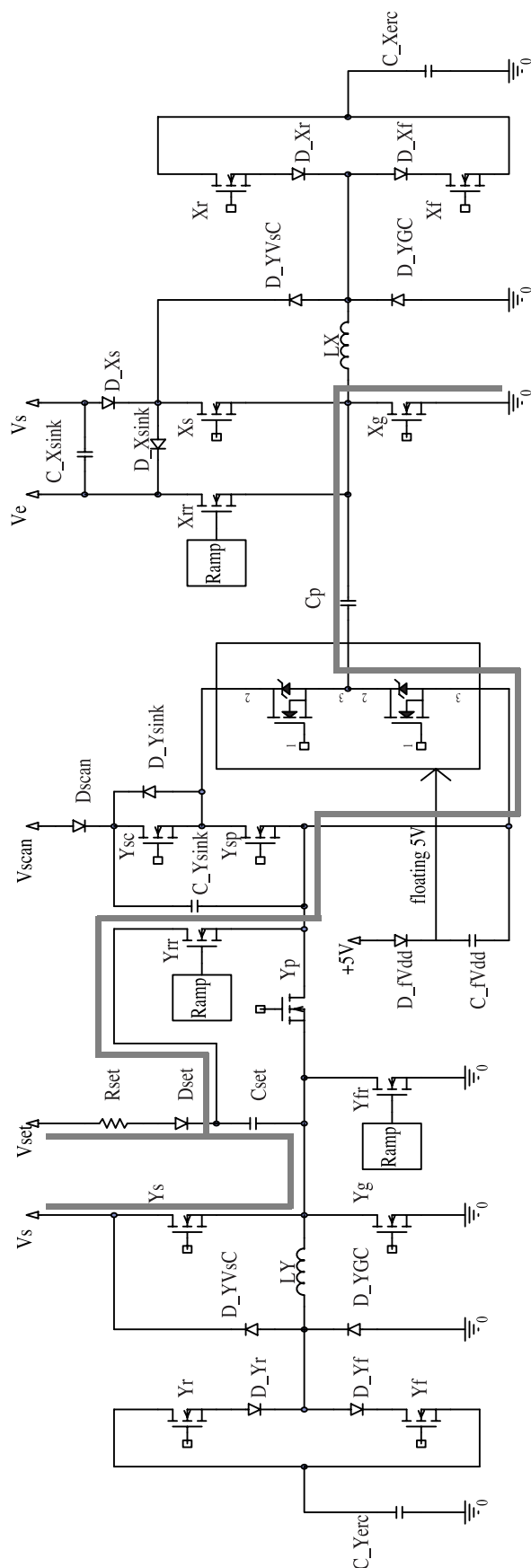


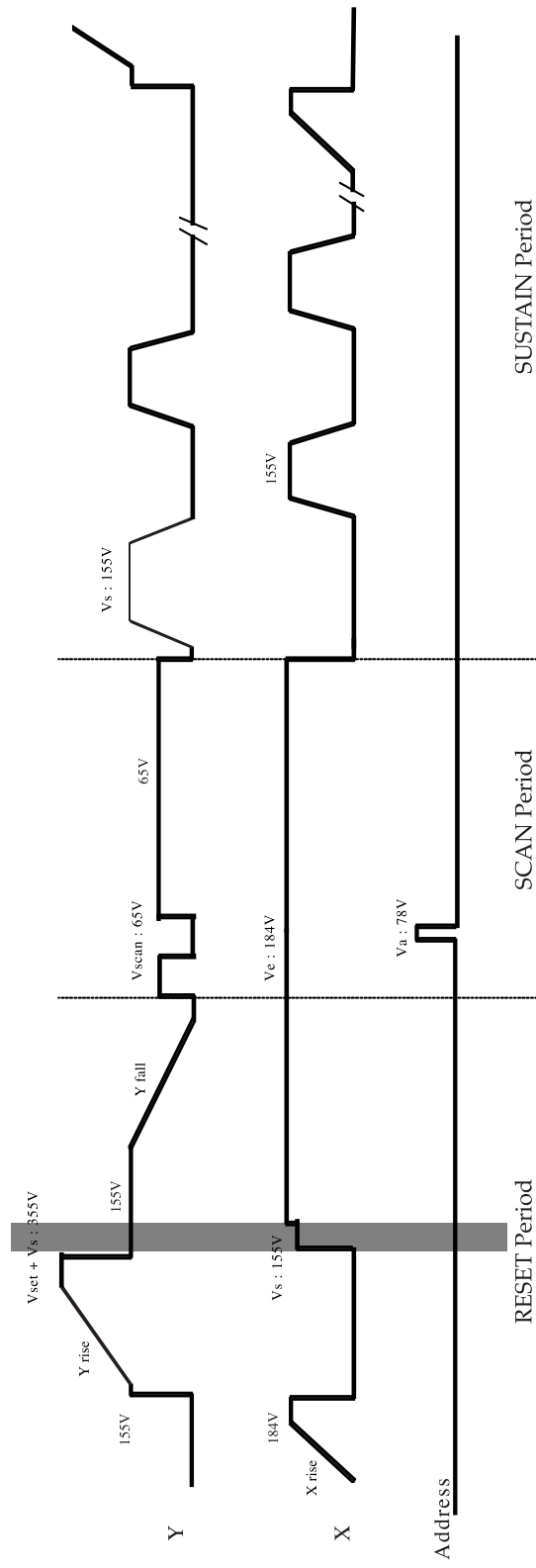
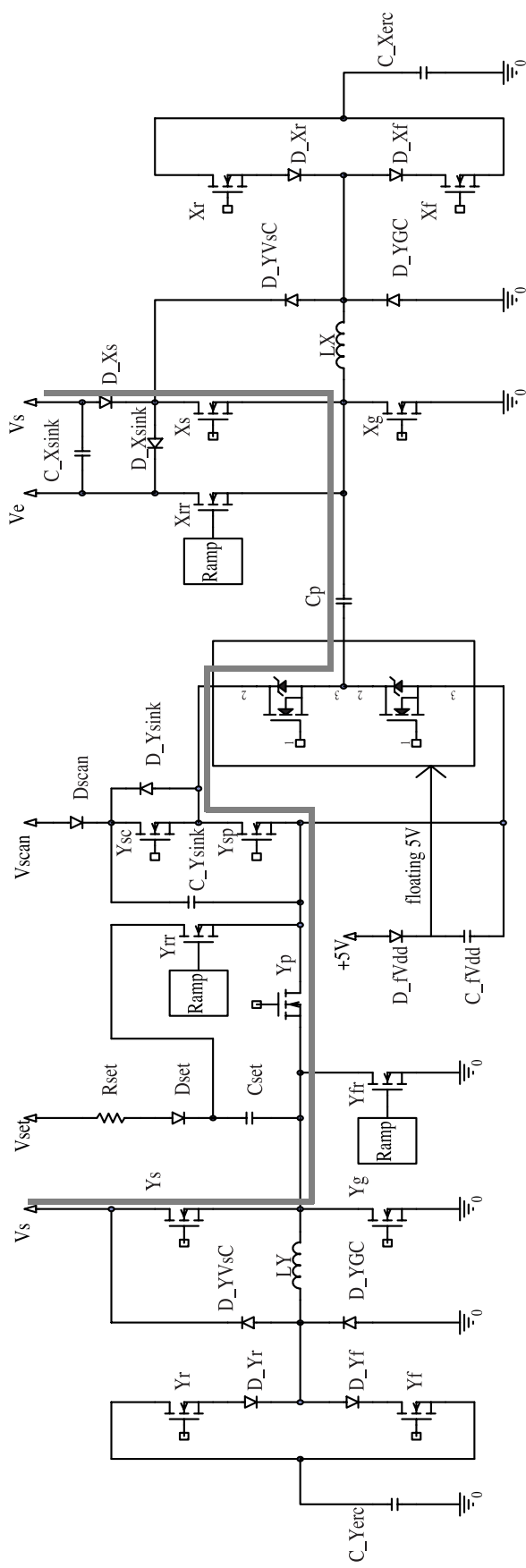
5-2-3(E) DRIVER BOARD CONNECTOR LAYOUT

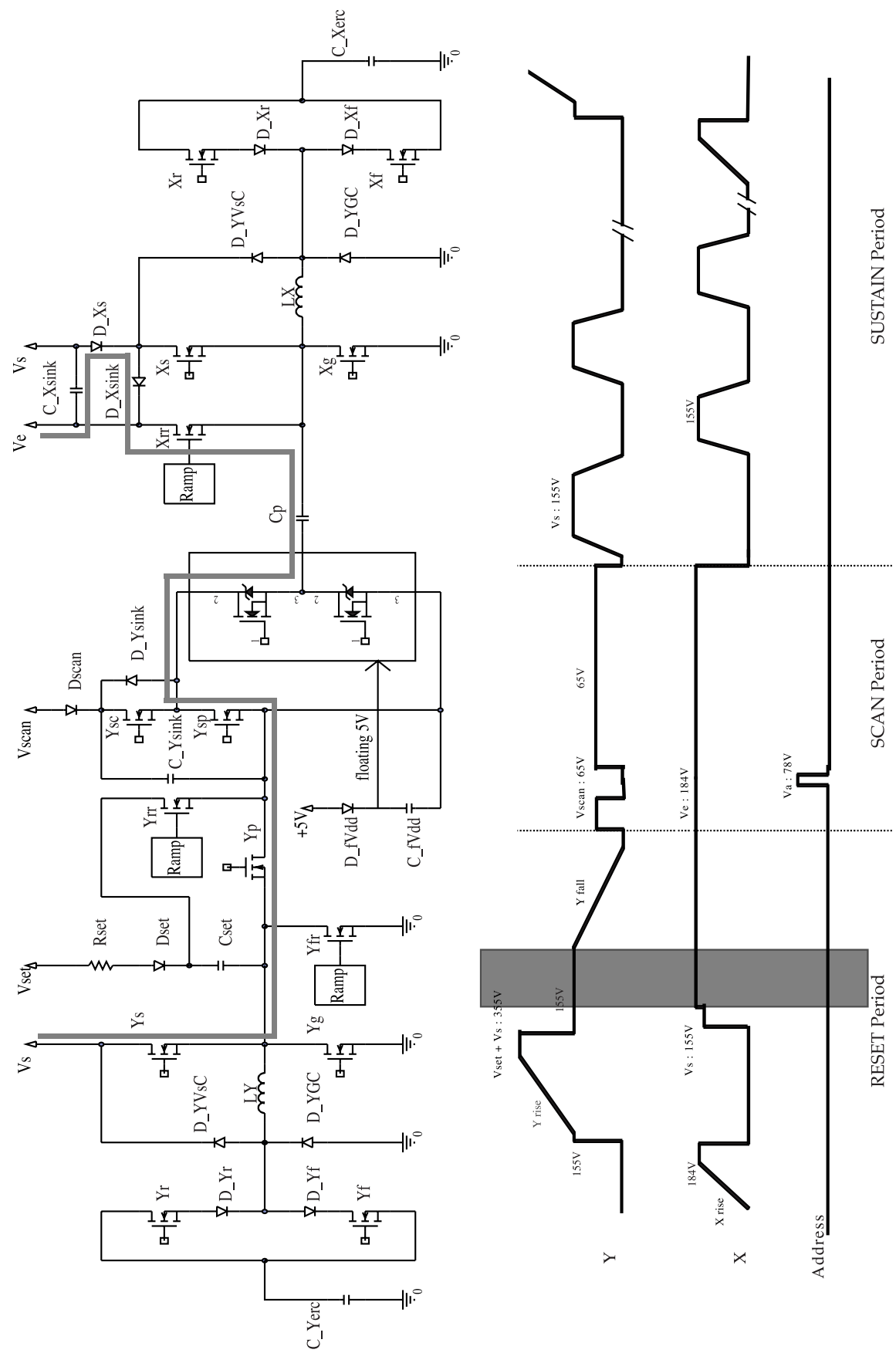


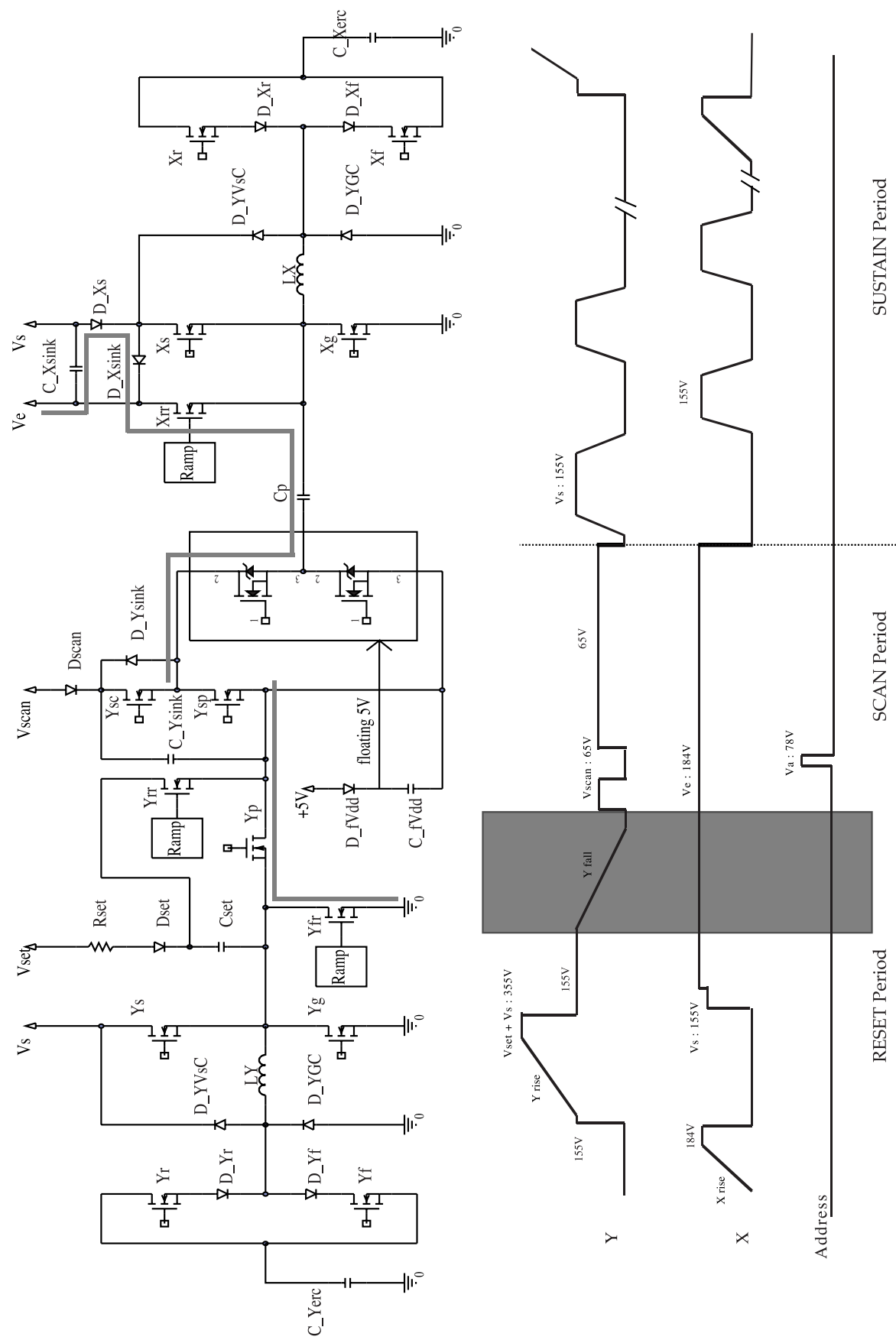


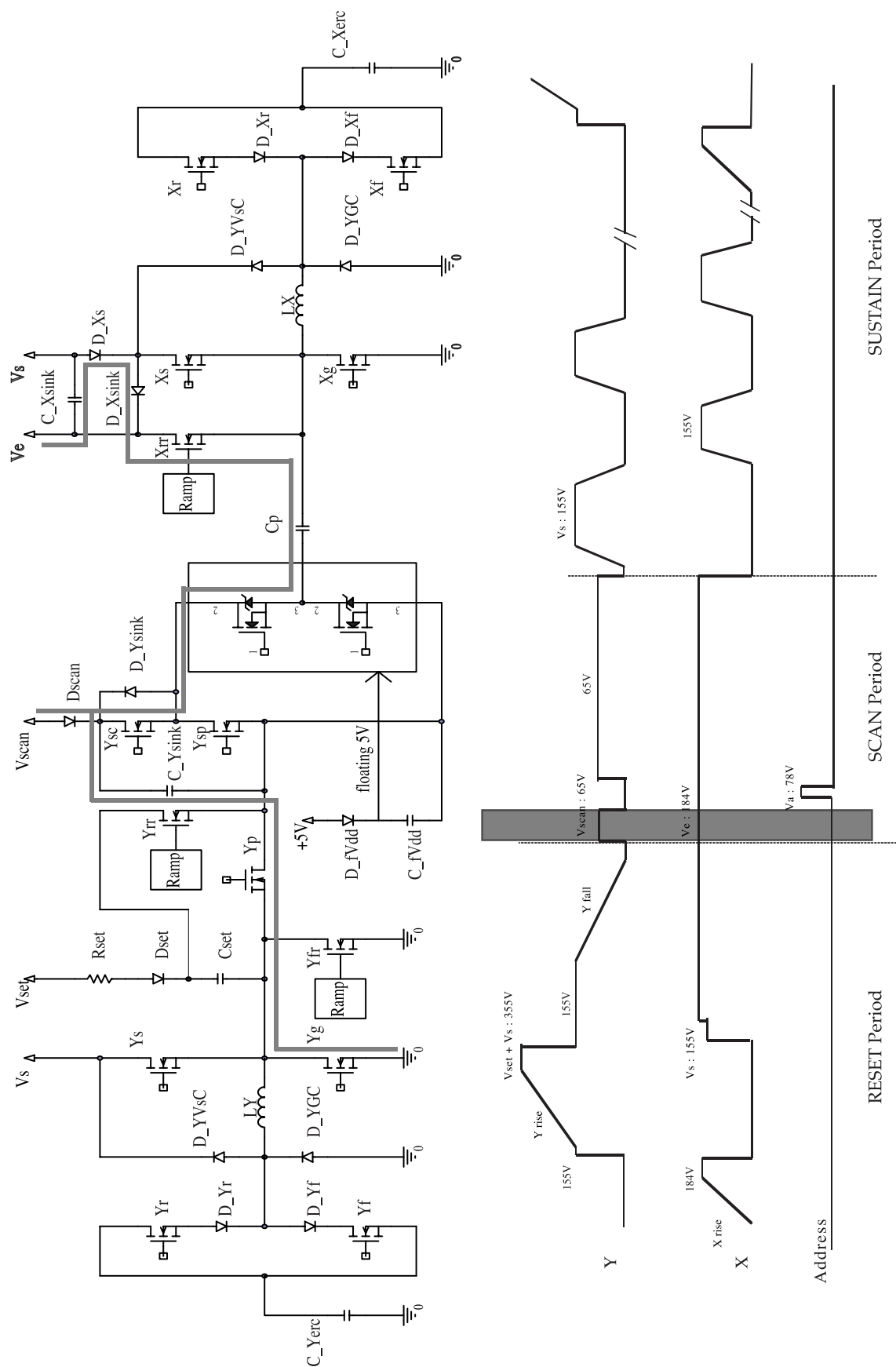


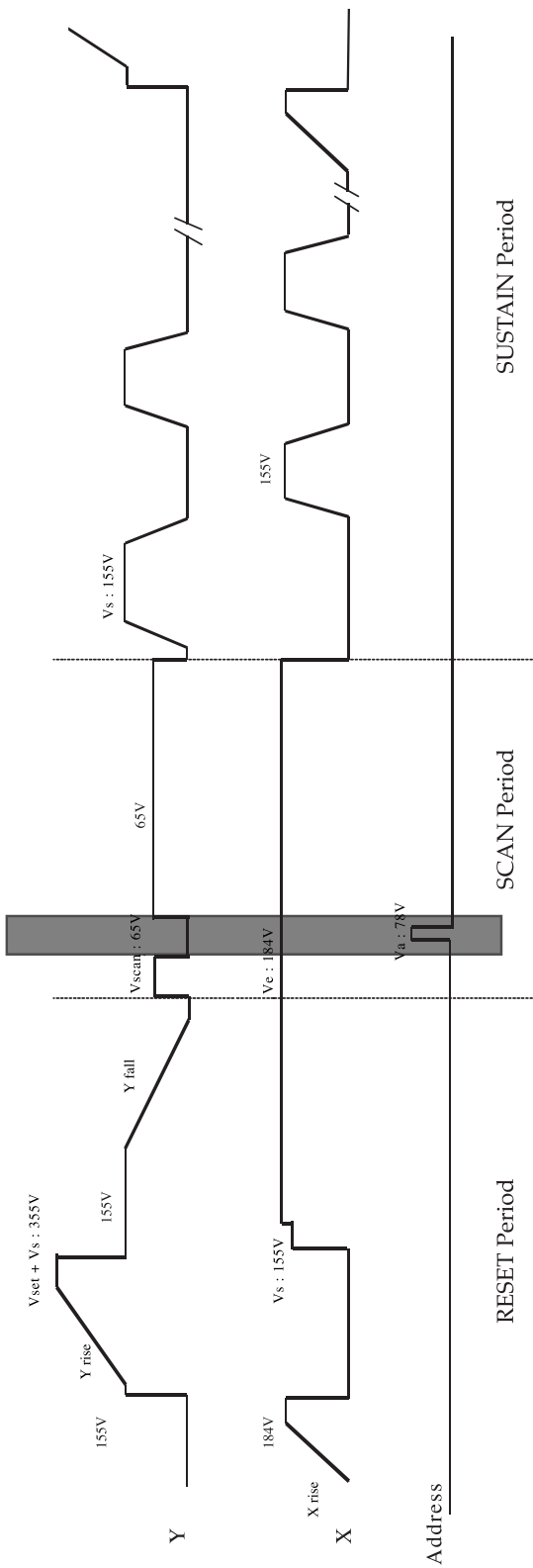
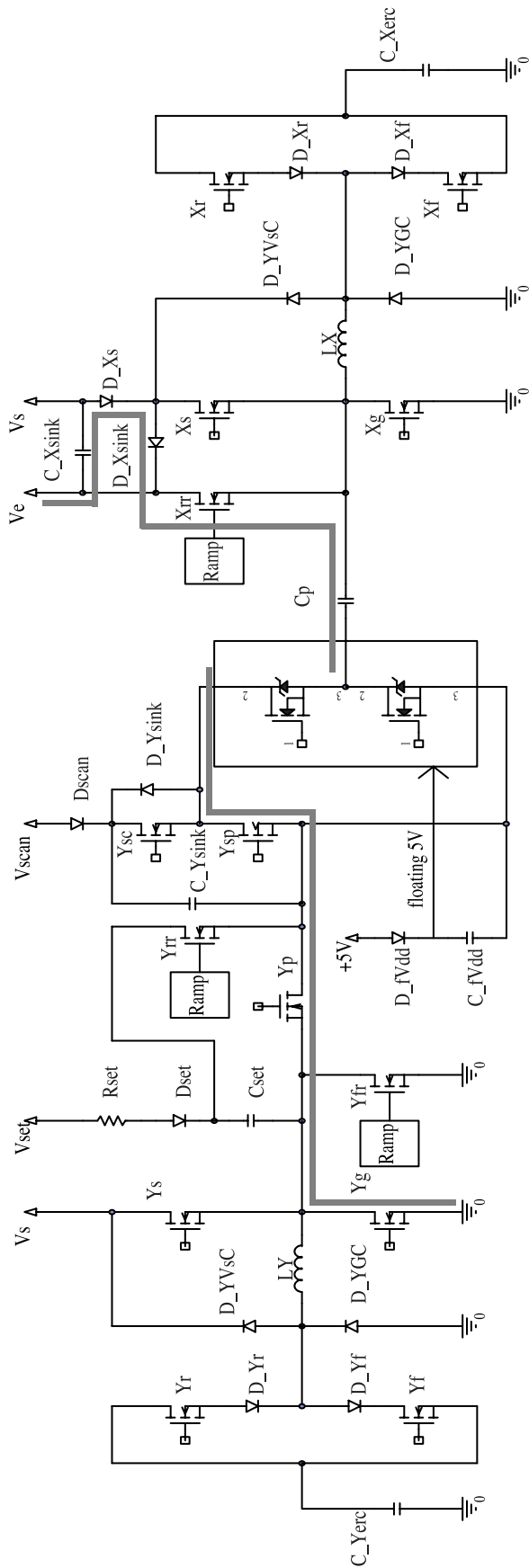


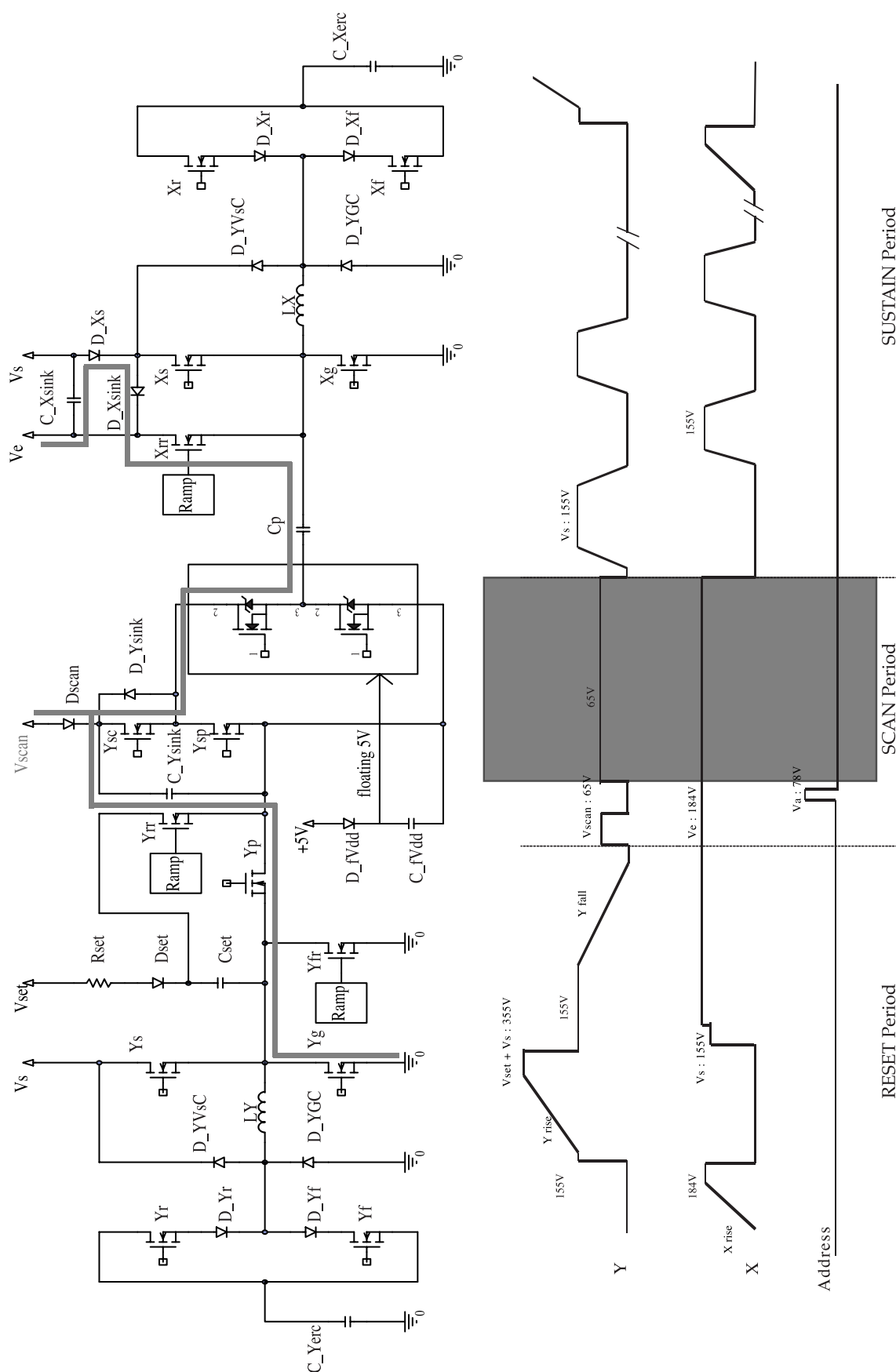


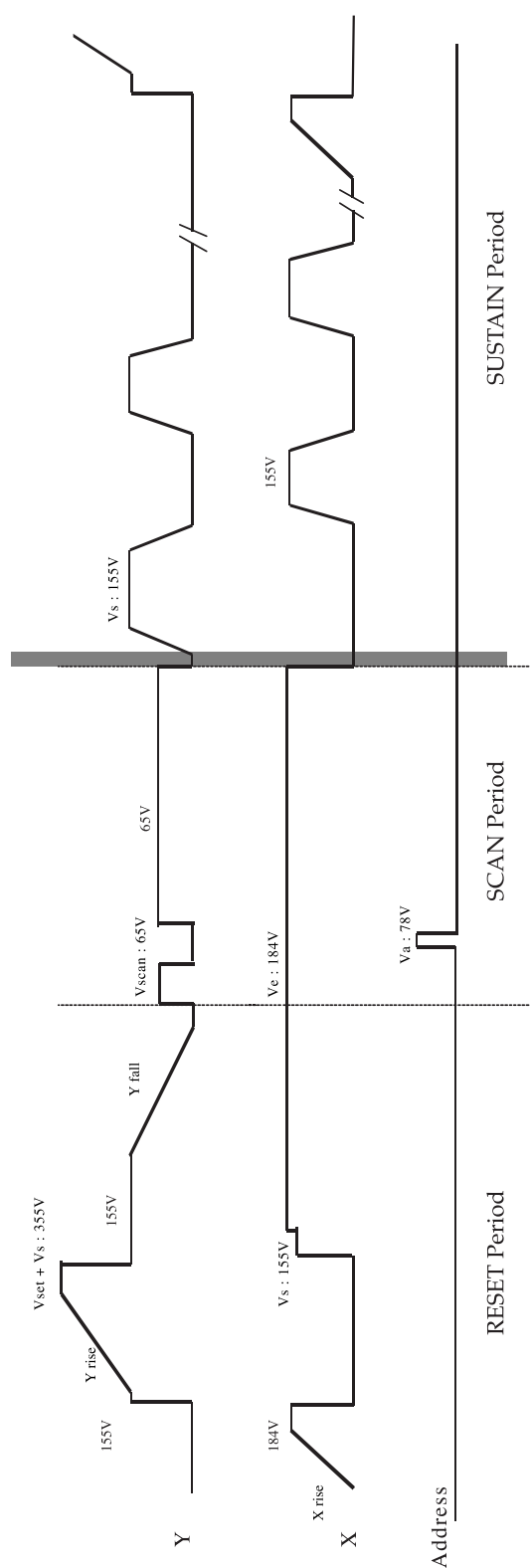
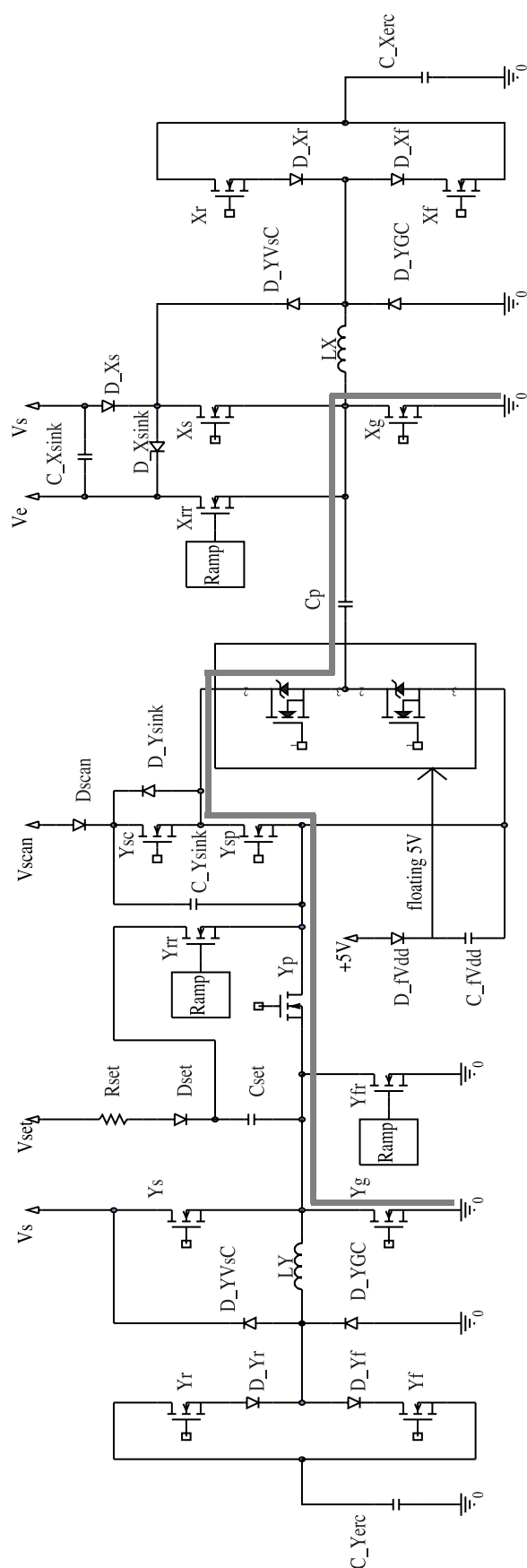


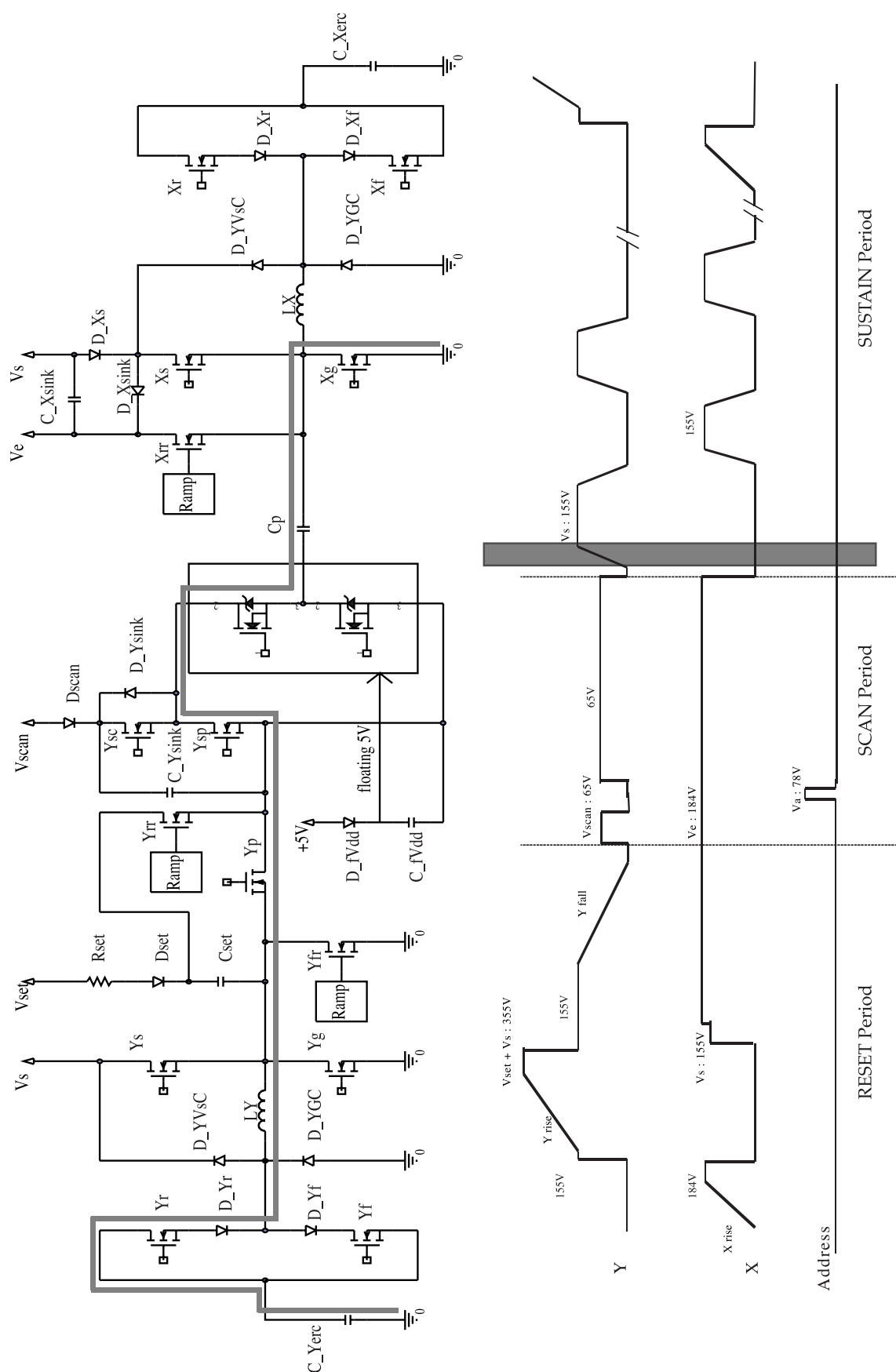


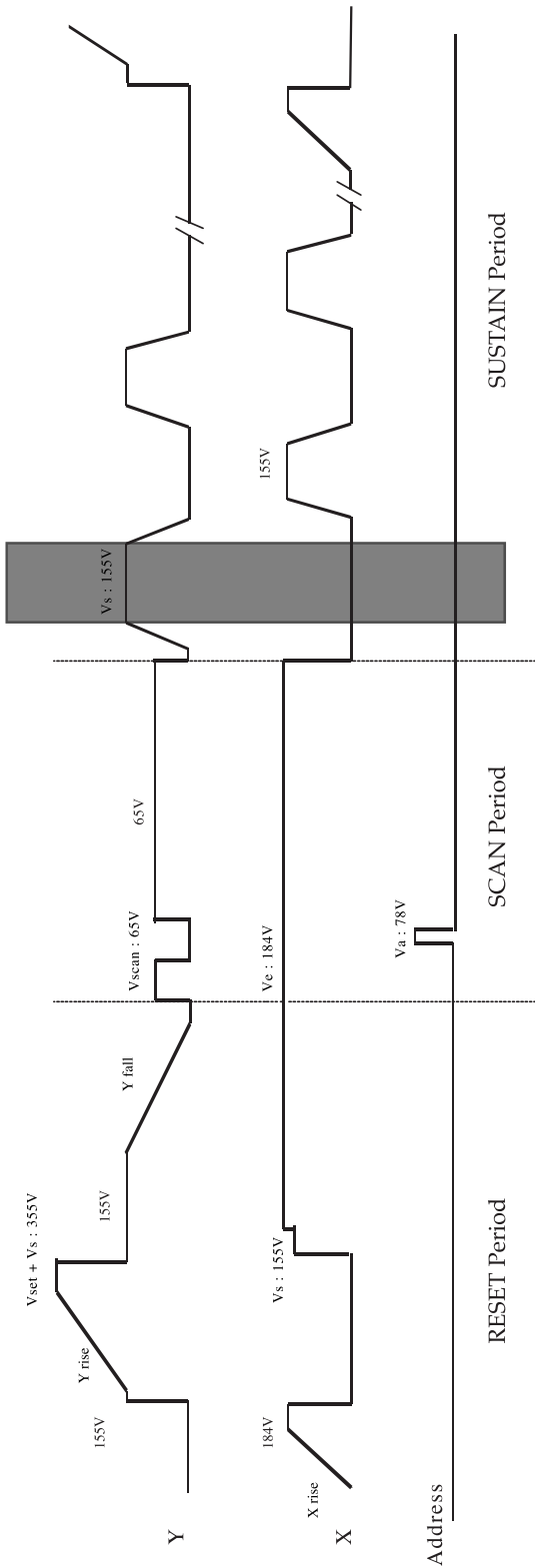
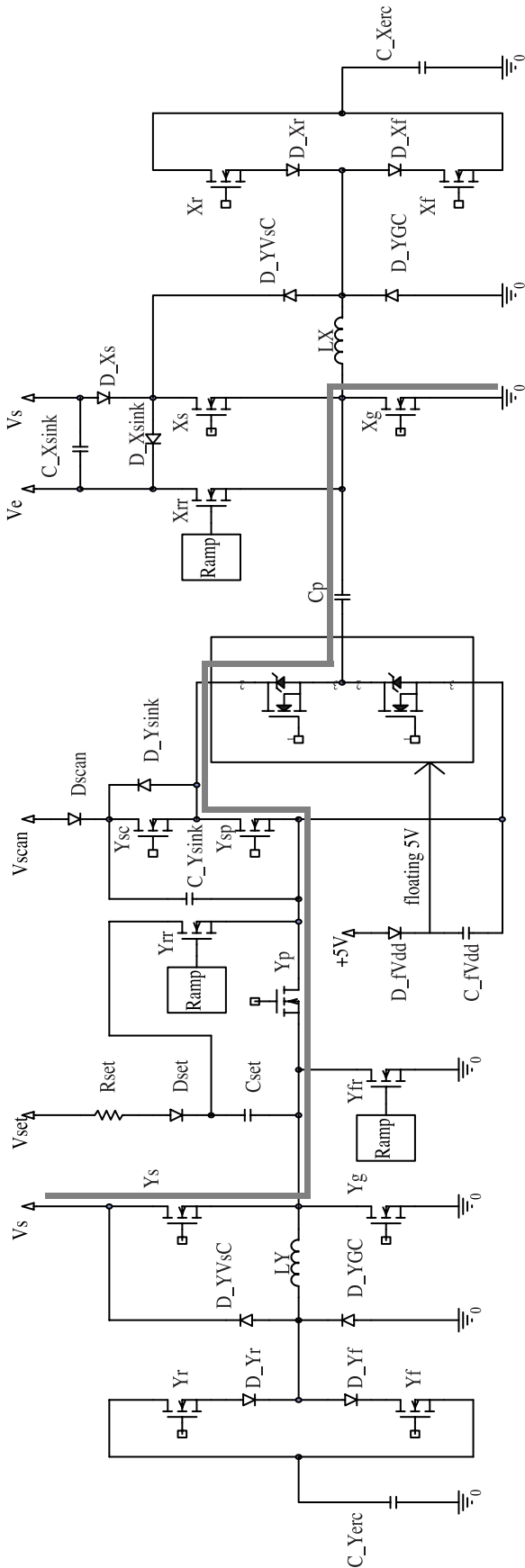


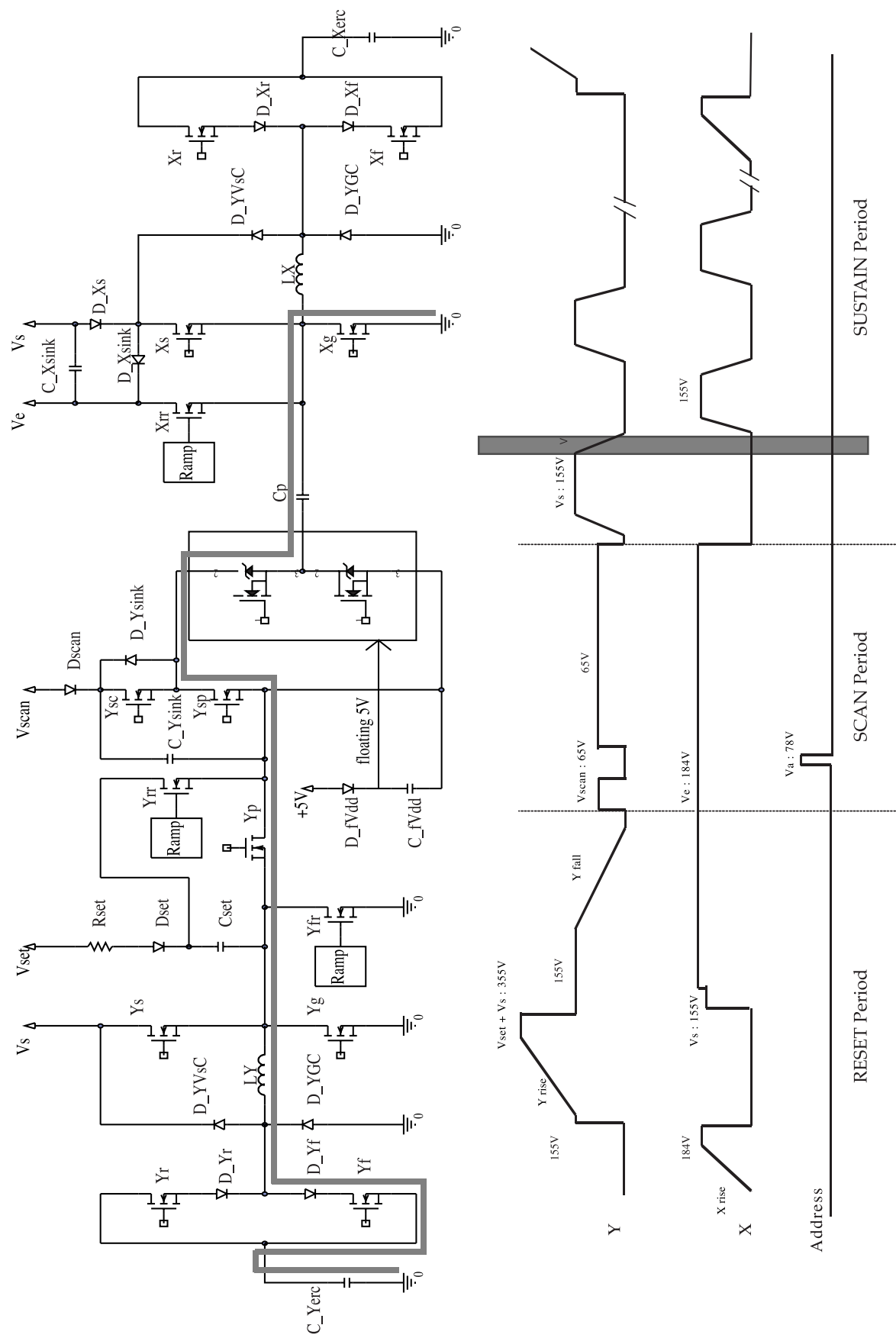






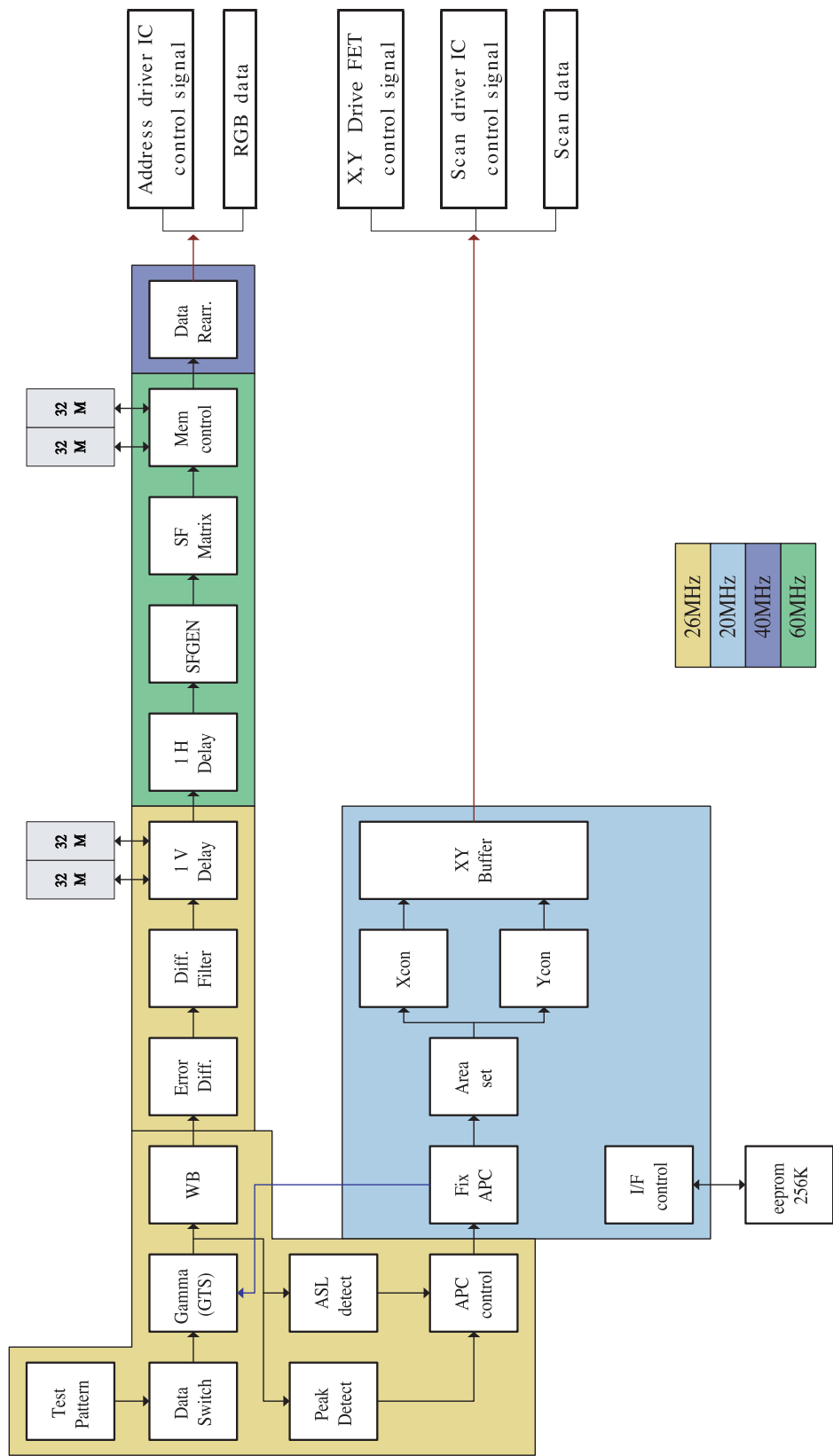






5-3 Logic part

5-3-1 Logic Board Block diagram

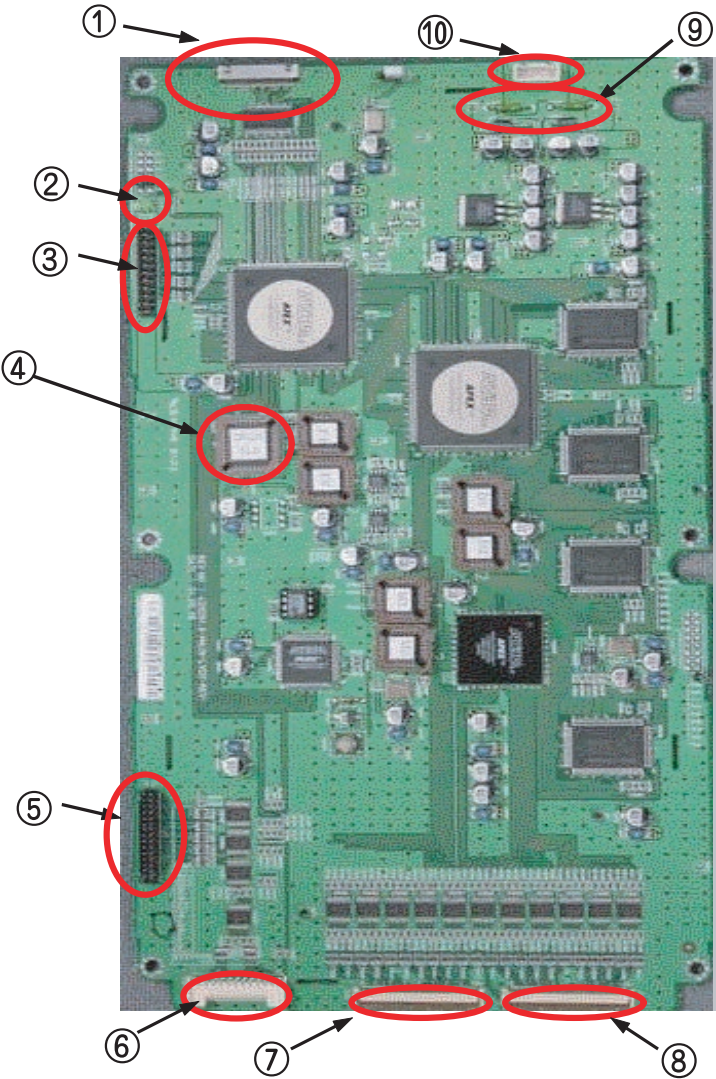


5-3-1(A) TDESCRIPTION OF LOGIC BOARD

The logic board consists of the logic main board and the buffer board. The logic main board processes video signal, generates, and output address driver output signal as well as XY drive signal. The buffer board stores address driver output signal, and sends the signal to the address driver IC (COF module).

Logic Board		Function
Login Main		- Video signal processing (W/L, Error diffusion, APC) - Outputs address drive control signal, and data signal to buffer board. - Outputs XY drive board control signal.
Buffer board	E Buffer board	Sends data and control signal to left-bottom COF
	F Buffer board	Sends data and control signal to right-bottom COF

5-3-1 (B) NAME AND DESCRIPTION OF MAJOR COMPONENTS OF LOGIC BOARD



No	Name	Function
1	LVDS Connector	Input connector to receive encoded RGB, H, V, DATAEN, and DCLK signal.
2	Operation LED	It shows Sync and clock are properly received by the logic board.
3	Key-Scan Connector	Connector to connect key scan board to check and adjust 256K data.
4	256k	EEPROM including gamma table, APC table, drive signal timing and other options
5	Y Connector	Connector to output Y drive board control signal
6	X Connector	Connector to output X drive board control signal
7	LE01 (Address Buffer Connector)	Connector to output address data, and control signal to the E and F buffer boards.
8	LE02 (Address Buffer Connector)	Connector to output address data, and control signal to the E and F buffer boards.
9	Power Fuse	Fuse connected to the power source line of the logic board.
10	Power Connector	Connector to connect the supply power (5V) with the logic board. drive board control signal.

5-3-1(C) WAVEFORMS IN NORMAL OPERATION

If the PDP unit and the logic board is in normal operation, the operation LED of Figure 1 would blink at about 1 second interval.

If the unit is out of order, check the status of the operation LED through eye-inspection first. If the behavior of the operation LED is different from that of normal state, you have to replace the board. To check trouble on the board, the following logic board test procedures described below.

□ 42" SD s1.0 logic main board T/S

Required test equipment: : - Oscilloscope (digital 400 MHz 3 channel or more)
 - Multi meter

Other equipment: : - DC power supply (5V: 1EA)
 - Sub-PCB ASS'Y for JIG: 1 EA

- (1) First, perform eye-inspection and short circuit inspection for the power stage of the logic board to examine. Then, perform the following examinations on the board in order if no problem was found.
- (2) Replace IC2017(256K EEPROM) of the logic board with Test EERPOM. Change the clock setting of the logic board to internal referring to the configuration procedures described below.
 ※ If there is no available Test EEPROM, you can use PG 00 for Windows NT systems, or PG 40 for NT/PAL compatible systems by setting address 20 to 81, 22 to 00, 23 to 00, and 70 to 01.
- (3) Connect power(5V) to LD1, and check that LED(LD2000) on the left top of the board blinks at about 1 second interval.
- (4) If the logic board is out of order, the LED would blink too fast or not be lighted on.
- (5) If no problem was found in the above examination, connect sub-PCB for logic output examination, measure output waveform, and compare the waveform with the appended waveform of normal state. Record either OK or NG after examination.
- (6) Check drive Y s/w, drive X s/w and address signal in order.
- (7) Set probe 1 of oscilloscope to trigger signal, and connect it to the TP31 of the logic board.
- (8) Set oscilloscope to 2ms/div. After adjusting probe 2 to 5V/div, check output signal.
- (9) After T/S, turn off the power supply, and disconnect connector.
- (10) Record the result on the examination sheet (either OK or NG).

❑ Jumper settings to select internal or external clock

On the top of the logic main board, there is option jumper (CN01) that allows selecting internal/external clock. While T/S, set it to internal clock as the following figure shows.

※ It is set to external clock in normal. Set it to internal clock while examination, and set it to external clock again after examination.

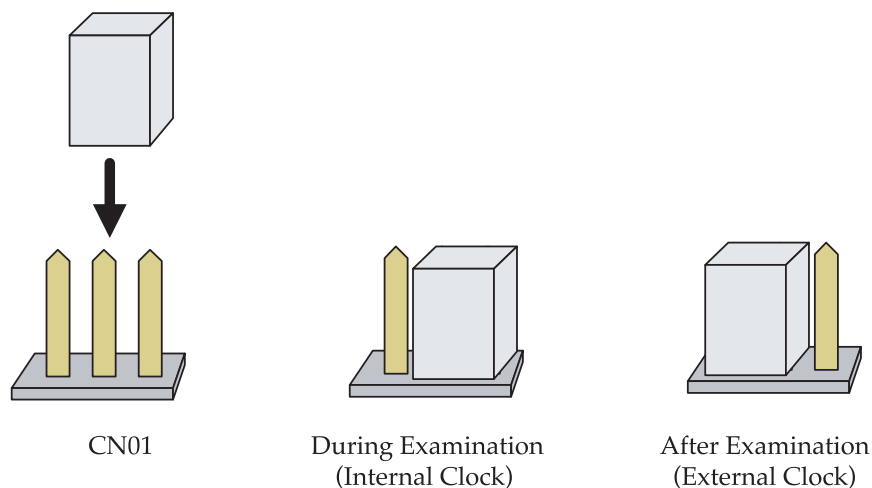


Figure 1. Jumper Settings to Select Internal / External Clock Signal

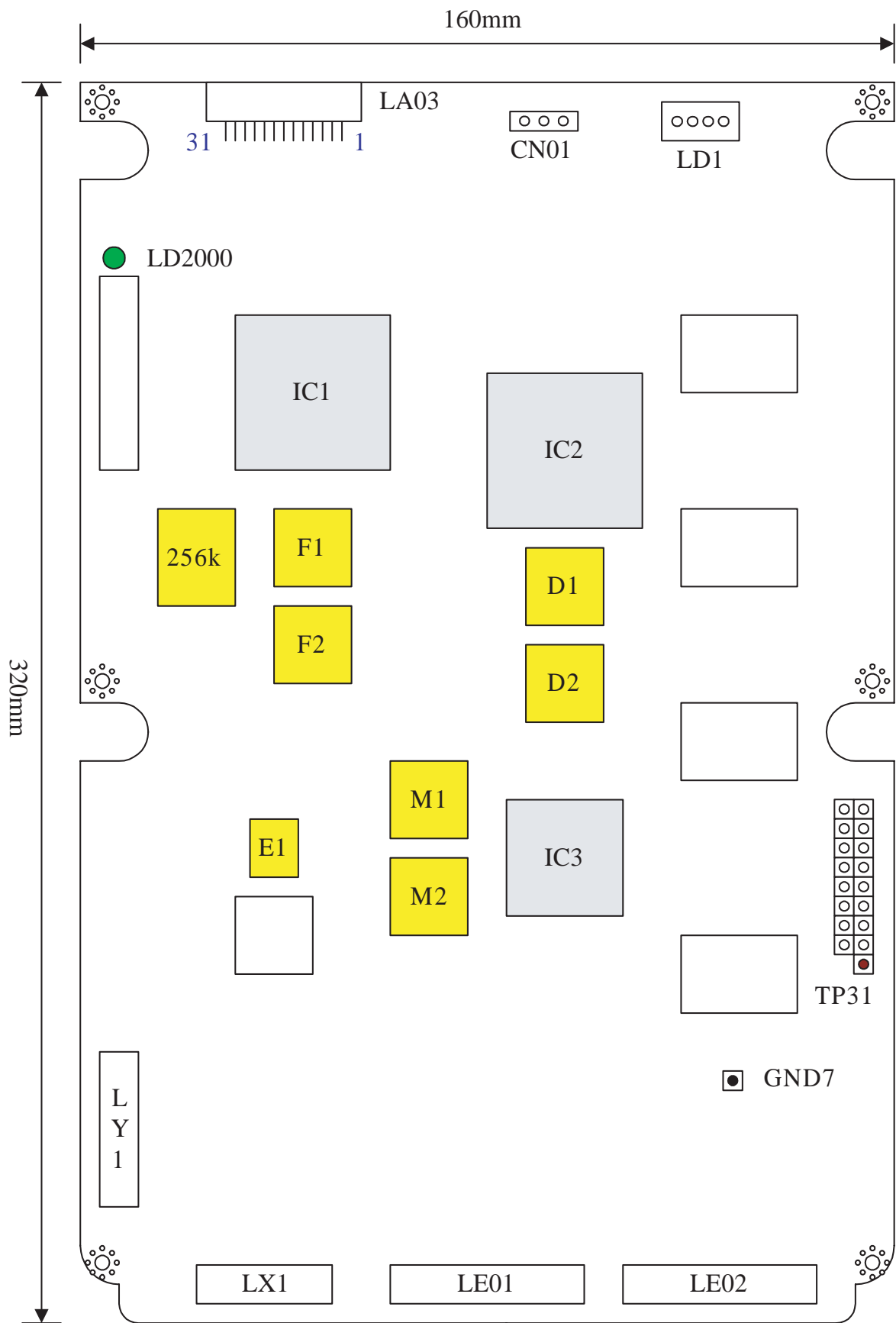


Figure 2. Layout of 42" Signal Logic Main Board.

(1) Checking Y S /W

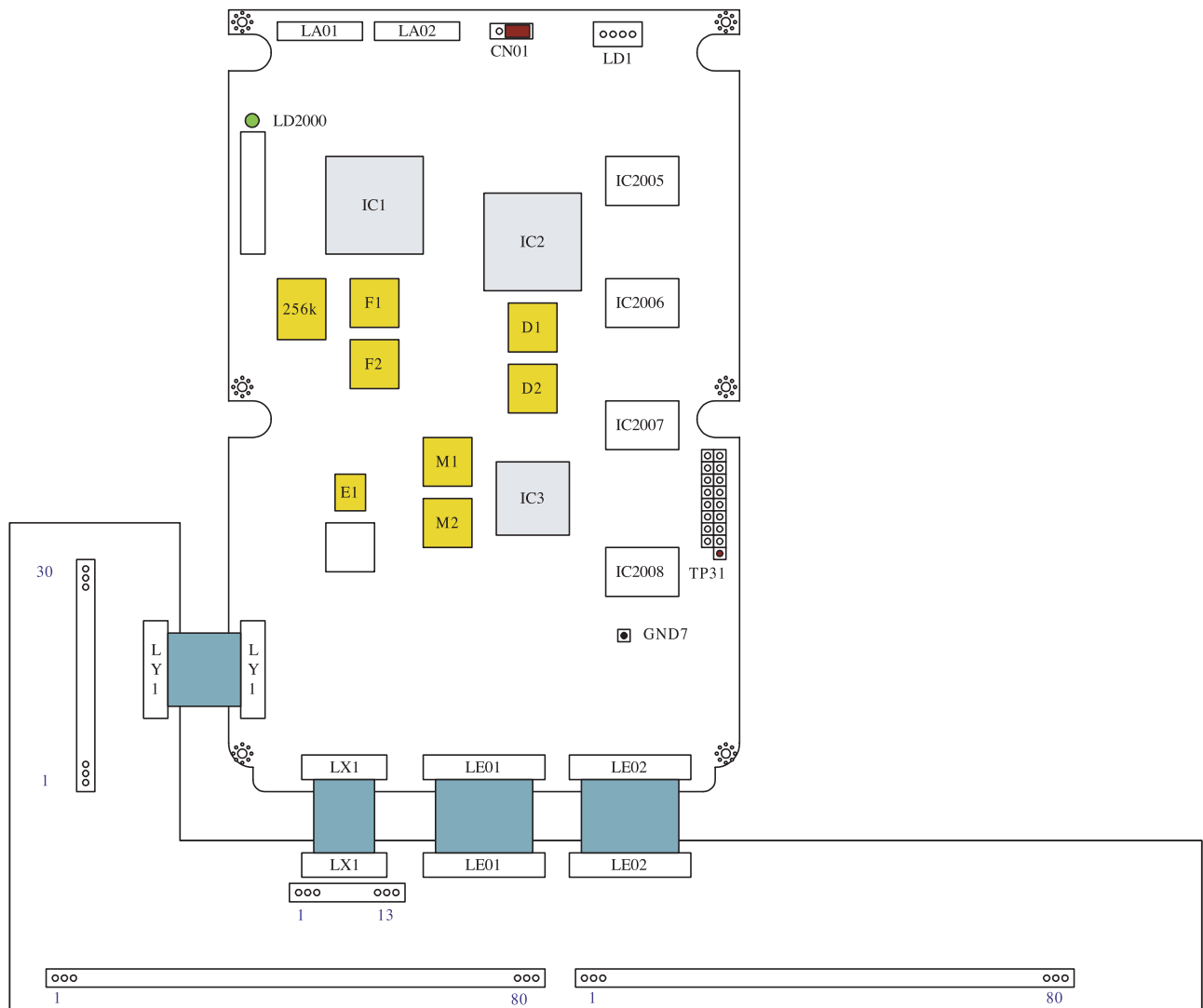


Figure 3. Connecting The Logic Main Board and The Test JIG Board

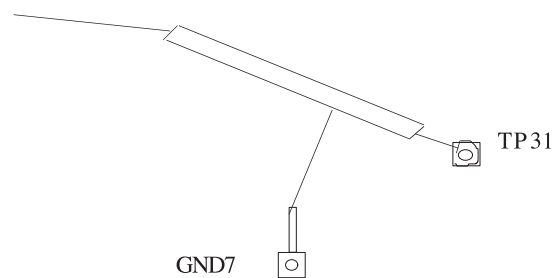
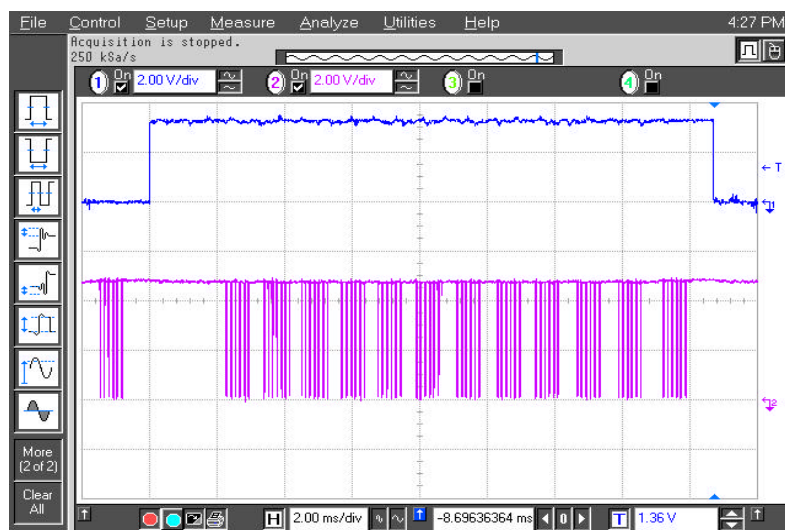
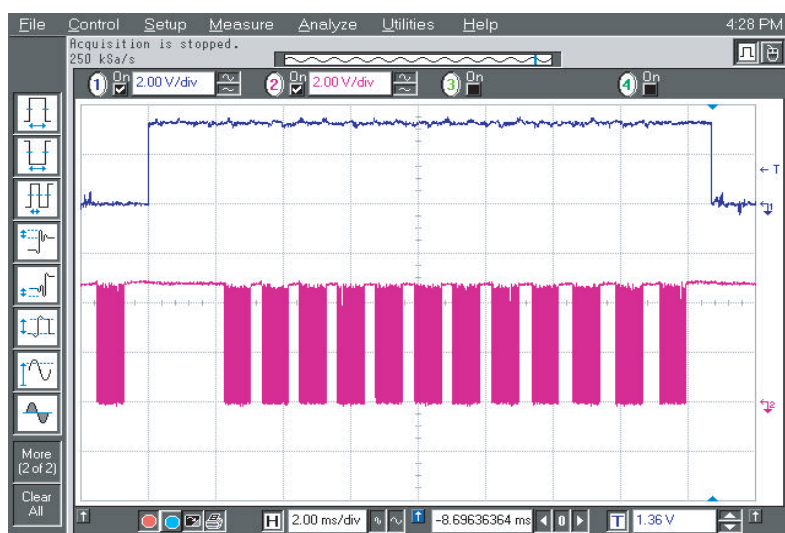


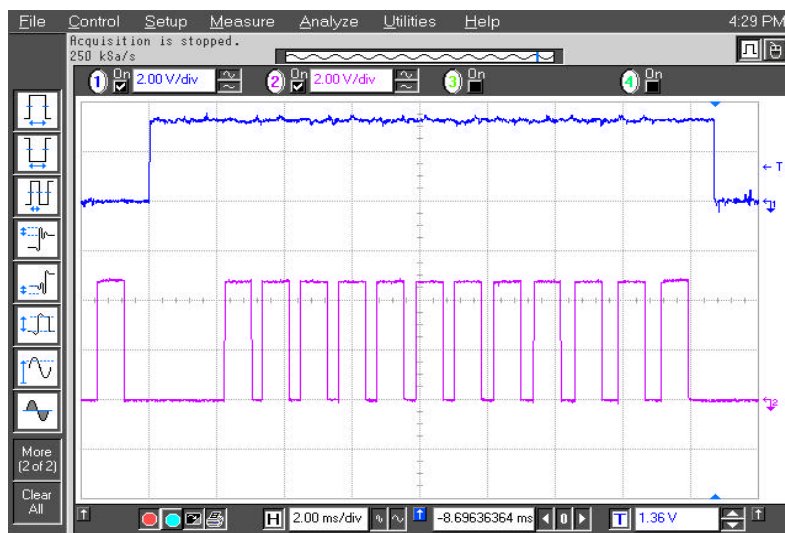
Figure 4. Connecting Oscilloscope Probe 1 (Trigger)



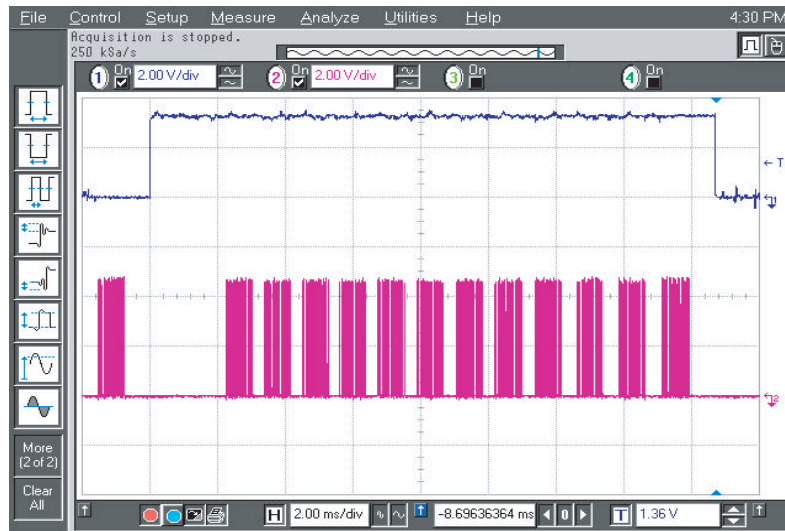
① Connect Probe 2 to LY1 30 of The JIG Board (8 (LE-Y) of The Logic Main Board F2016).



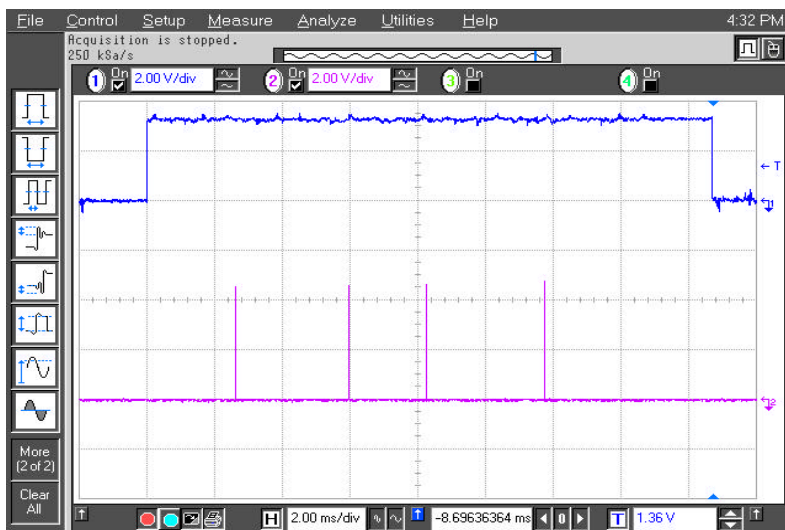
② Connect Probe 2 to LY1 28 of The JIG Board (7 (STB_Y) of The Logic Main Board F2016).



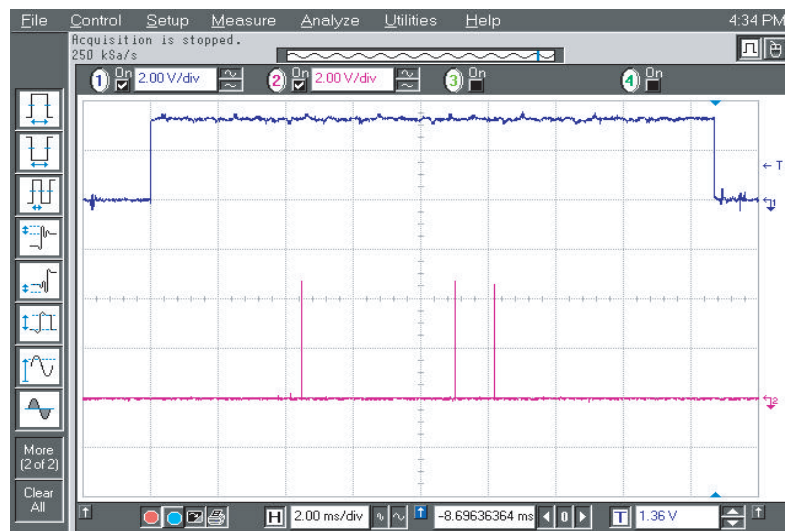
③ Connect Probe 2 to LY1 25 of The JIG Board (6 (TCS_Y) of The Logic Main Board F2016).



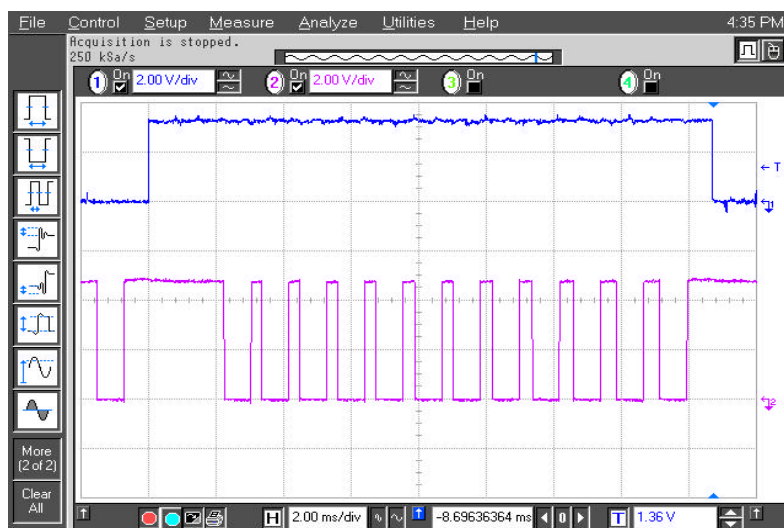
④ Connect Probe 2 to LY1 24 of The JIG Board (5 (CLK_Y) of The Logic Main Board F2016).



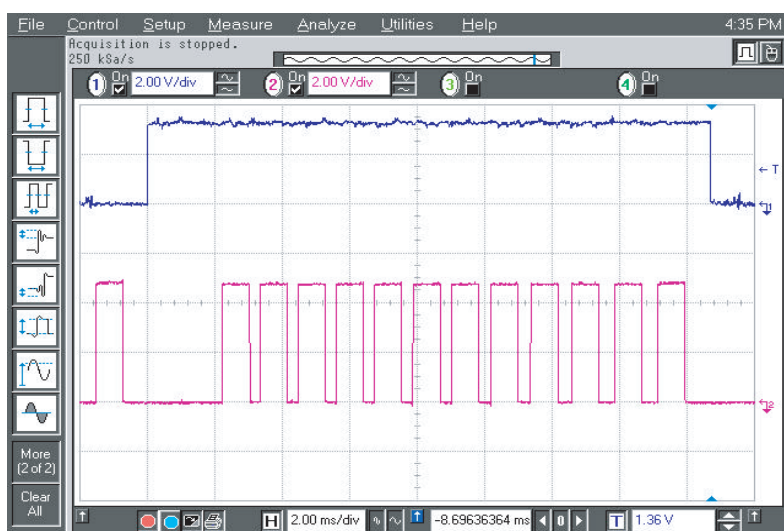
⑤ Connect Probe 2 to LY1 21 of The JIG Board (8 (SIB) of The Logic Main Board F2016).



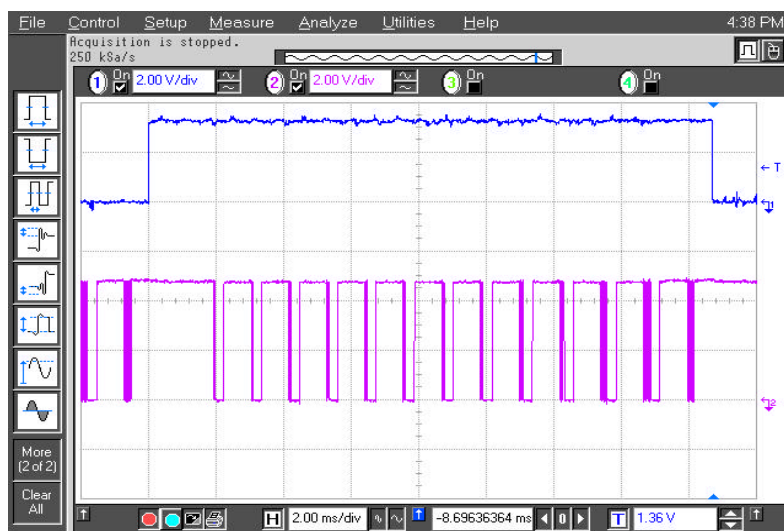
⑥ Connect Probe 2 to LY1 20 of The JIG Board (7 (SIA) of The Logic Main Board F2016).



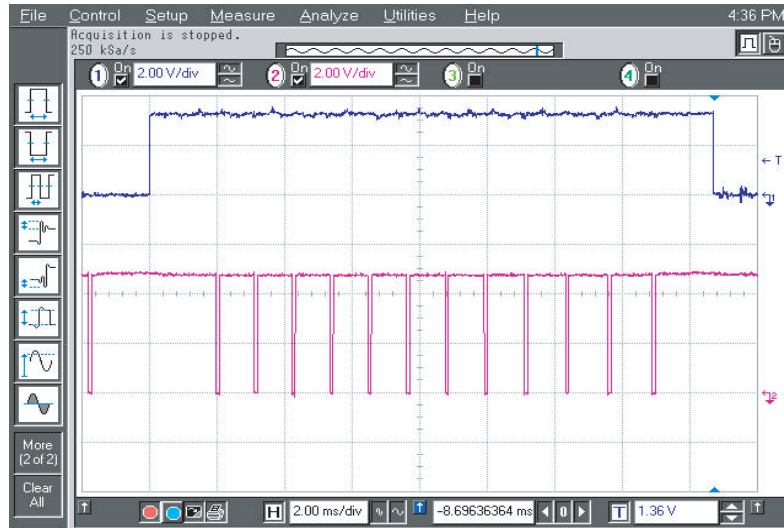
⑦ Connect Probe 2 to LY1 14 of The JIG Board (5 (YSP) of The Logic Main Board F2016).



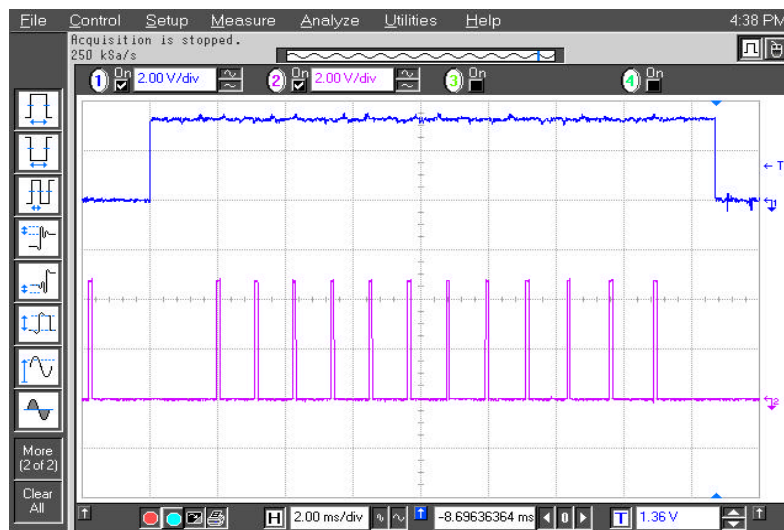
⑧ Connect Probe 2 to LY1 13 of The JIG Board (6 (YSC) of The Logic Main Board F2016).



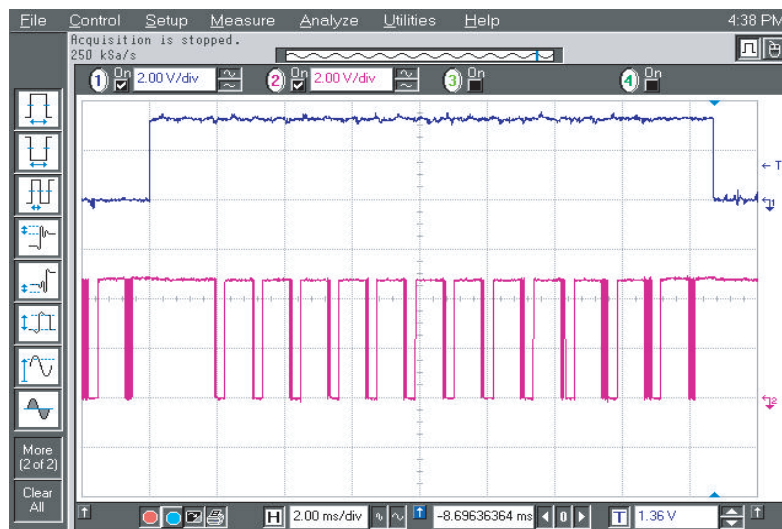
⑨ Connect Probe 2 to LY1 10 of The JIG Board (7 (YER) of The Logic Main Board F2016).



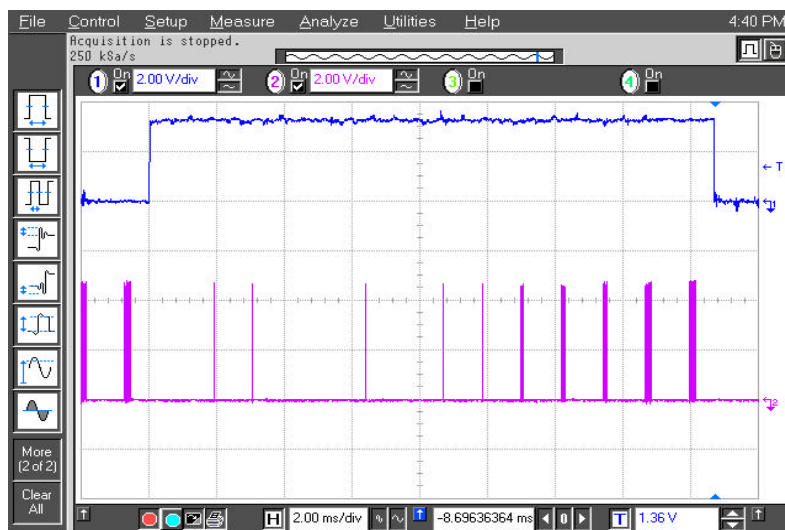
⑩ Connect Probe 2 to LY1 9 of The JIG Board (8 (YP) of The Logic Main Board F2016).



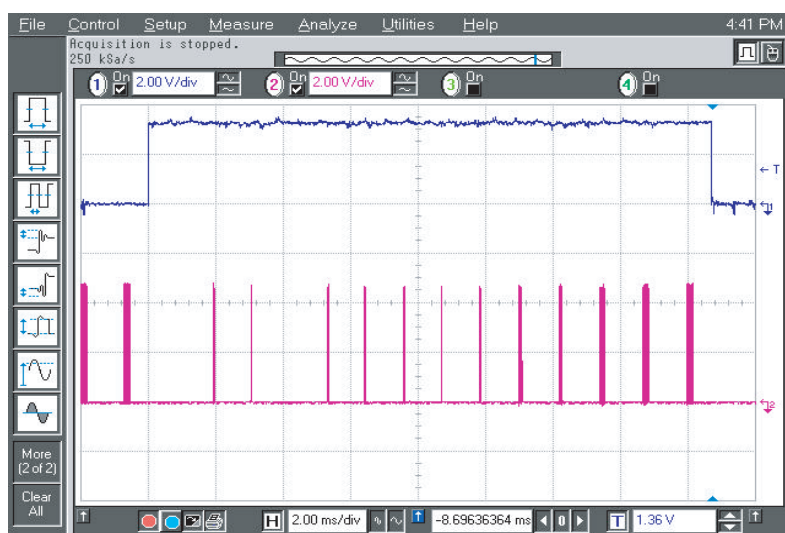
⑪ Connect Probe 2 to LY1 8 of The JIG Board (6 (YRR) of The Logic Main Board F2016).



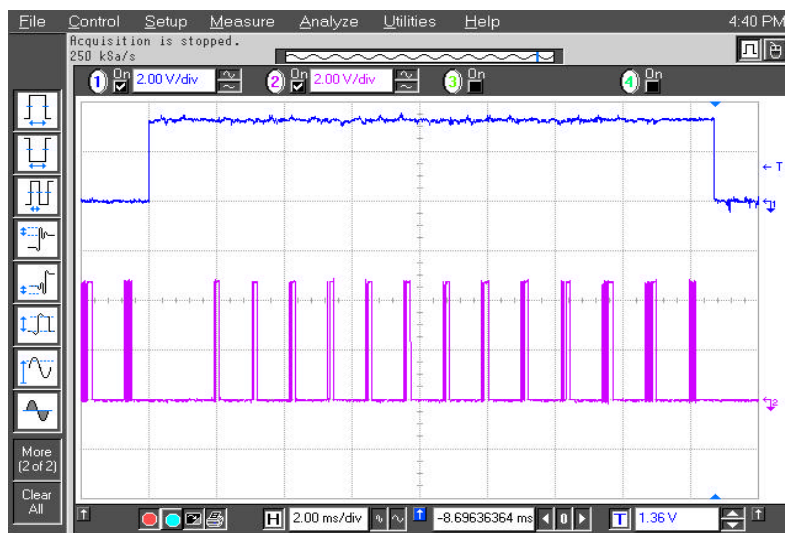
⑫ Connect Probe 2 to LY1 5 of The JIG Board (5 (YG) of The Logic Main Board F2016).



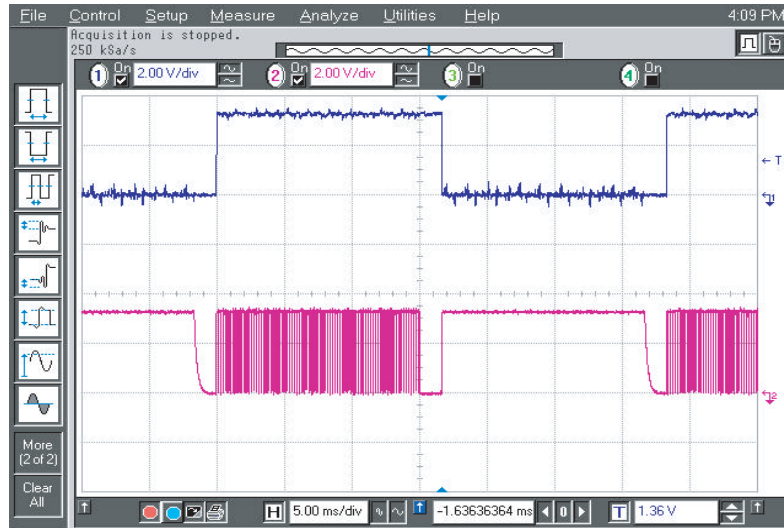
⑬ Connect Probe 2 to LY1 4 of The JIG Board (8 (YF) of The Logic Main Board F2016).



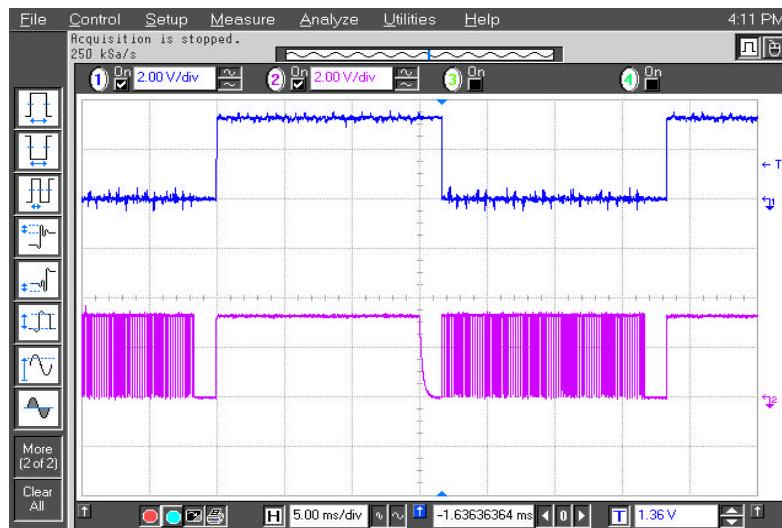
⑭ Connect Probe 2 to LY1 2 of The JIG Board (6 (YR) of The Logic Main Board F2016).



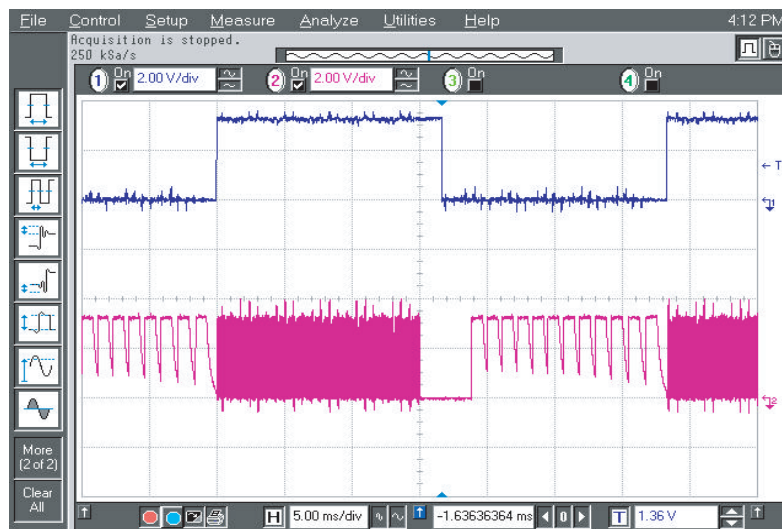
⑮ Connect Probe 2 to LY1 1 of The JIG Board (5 (YS) of The Logic Main Board F2016).



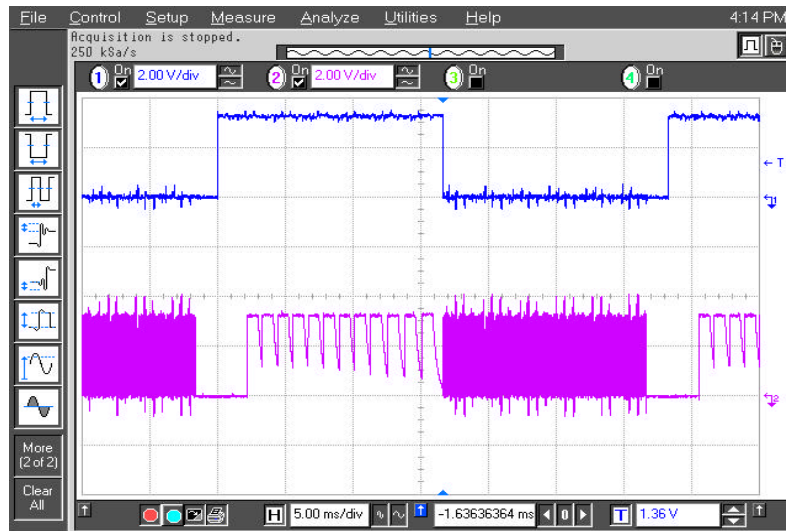
⑩ Connect Probe 2 to 1 and 72 of IC2005, and Check The Following Waveform Shows at Oscilloscope.



⑪ Connect Probe 2 to 1 and 72 of IC2006, and Check The Following Waveform Shows at Oscilloscope.

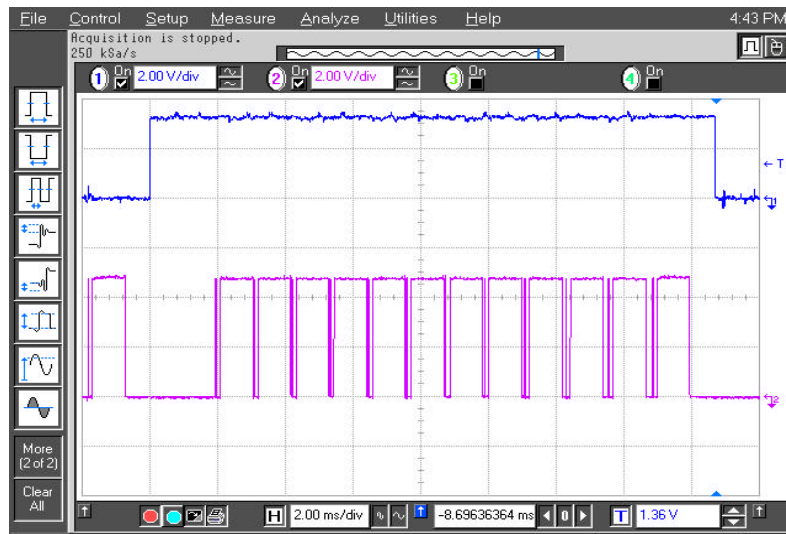


⑫ Connect Probe 2 to 1 and 81 of IC2007, and Check The Following Waveform Shows at Oscilloscope.

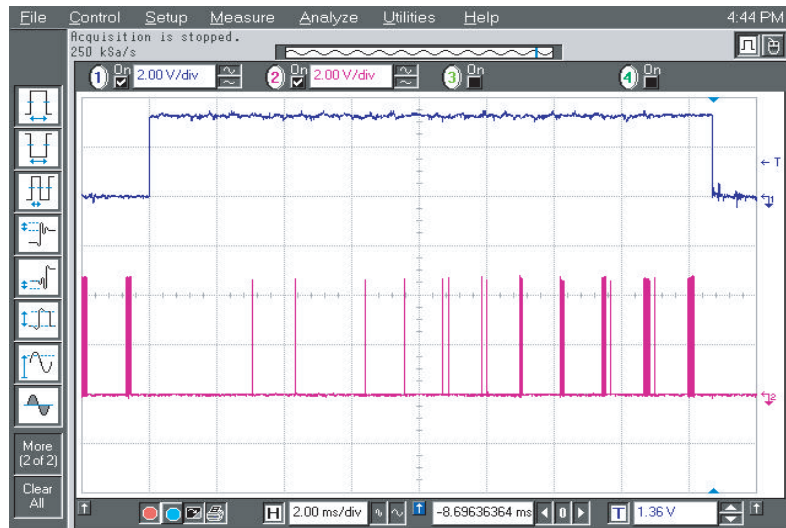


- ⑩ Connect Probe 2 to 1 and 81 of IC2008, and Check The Following Waveform Shows at Oscilloscope.

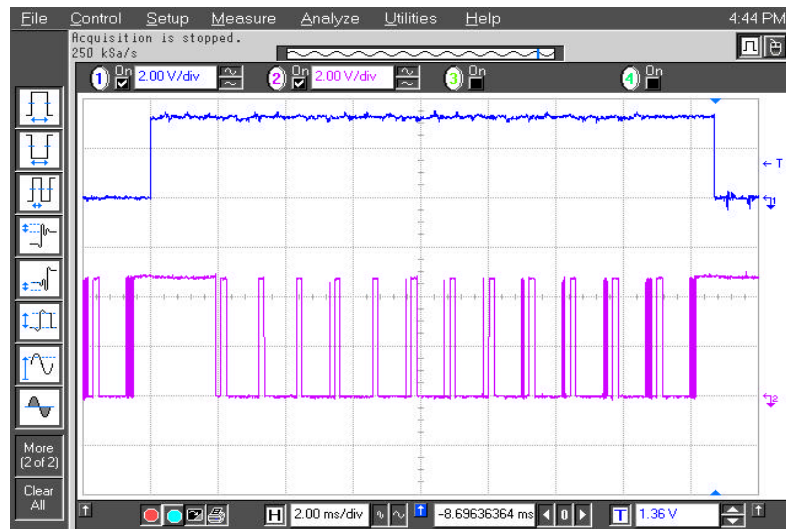
(1) Checking X S /W



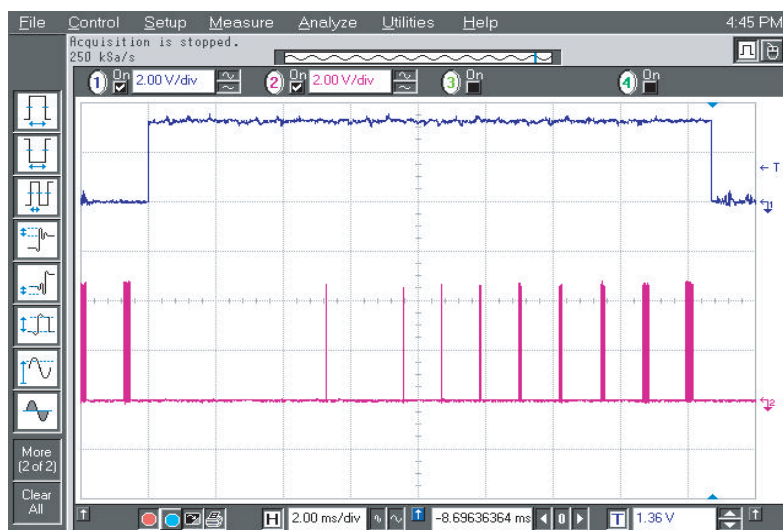
① Connect Probe 2 to LX1 2 of The JIG Board (6 (XRR) of The Logic Main Board F2016).



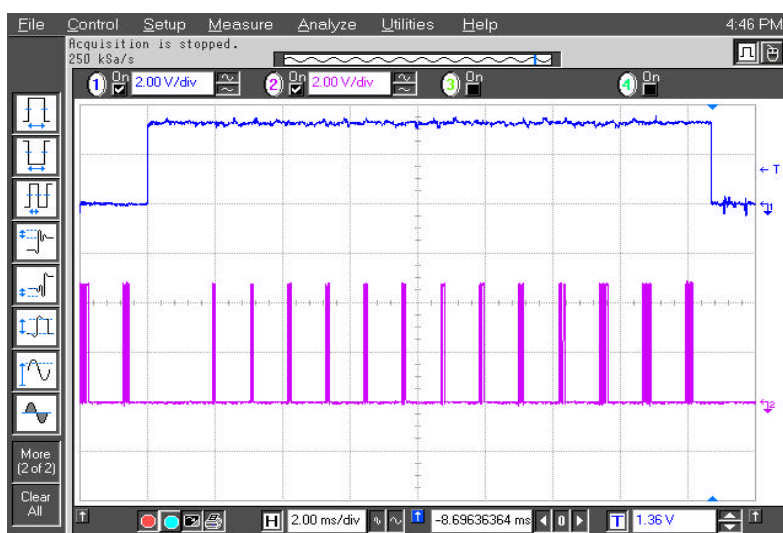
② Connect Probe 2 to LX1 4 of The JIG Board (7 (XR) of The Logic Main Board F2016).



③ Connect Probe 2 to LX1 6 of The JIG Board (8 (XS) of The Logic Main Board F2016).



④ Connect Probe 2 to LX1 8 of The JIG Board (5 (XF) of The Logic Main Board F2016).



⑤ Connect Probe 2 to LX1 10 of The JIG Board (6 (XG) of The Logic Main Board F2016).

■ 42"SD logic buffer board T/S

Required test equipment : -.Oscilloscope (digital 400 MHz 2 channel or more)

Other equipment : -.DC power supply (5V : 1EA)
 -.Multi meter
 -.Logic board : 1EA
 -.Sub-PCB ASS'Y for JIG: 1 EA

- (1) First, perform eye-inspection and short circuit inspection for the power stage of the logic board to examine. Then, perform the following examinations on the board in order if no problem was found.
- (2) If no problem was found in step ④, connect buffer board as Figure 5 shows, connect sub-PCB for COF data check and replace 256K EEPROM with Test EERPOM for the logic board to output full-white pattern.
- (3) Supply 5V to the logic board, and check that the LED on the left-top of the board blinks at about 1 second interval. If no problem is found, measure the output waveform of sub-PCB, and compare it with that of normal state.
- (4) Check EC1, EC2, EC3, EC4, FC5, FC6, and FC7 in order. You can only examine doubtful waveform selectively.
- (5) Set probe 1 of oscilloscope to trigger signal, and connect it to the TP31 of the logic board.
- (6) Set oscilloscope to 2ms/div. After adjusting probe 2 to 5V/div, check output signal zooming important points.
- (7) Appended waveform is for full-white input pattern. Output waveform when each of R, G and B pattern is supplied individually is summarized in the following table.

※ For short check, it would be better to test waveform in the order of R, G and B pattern.

	Output waveform for the applied pattern			
	Full-white	R	G	B
Control signal output of sub-PCB for COF data check	The same as the attached waveform			
R, B, G data signal output of sub-PCB for COF data check	The output waveforms of all of the R, G, B TP's are the same as the attached waveform.	The output waveforms of all of the R0, R1 TP's are the same as the attached waveform.	The output waveforms of all of the G0, G1 TP's are the same as the attached waveform.	The output waveforms of all of the B0, B1 TP's are the same as the attached waveform.

R0(TP13,TP49), R1(TP16,TP52), G0(TP14,TP50), G1(TP17,TP53),
 B0(TP15,TP51), and B1(TP18,TP54) in The JIG Board

- (8) After T/S, turn off the power supply, and disconnect the connector. Record the result on the examination sheet.

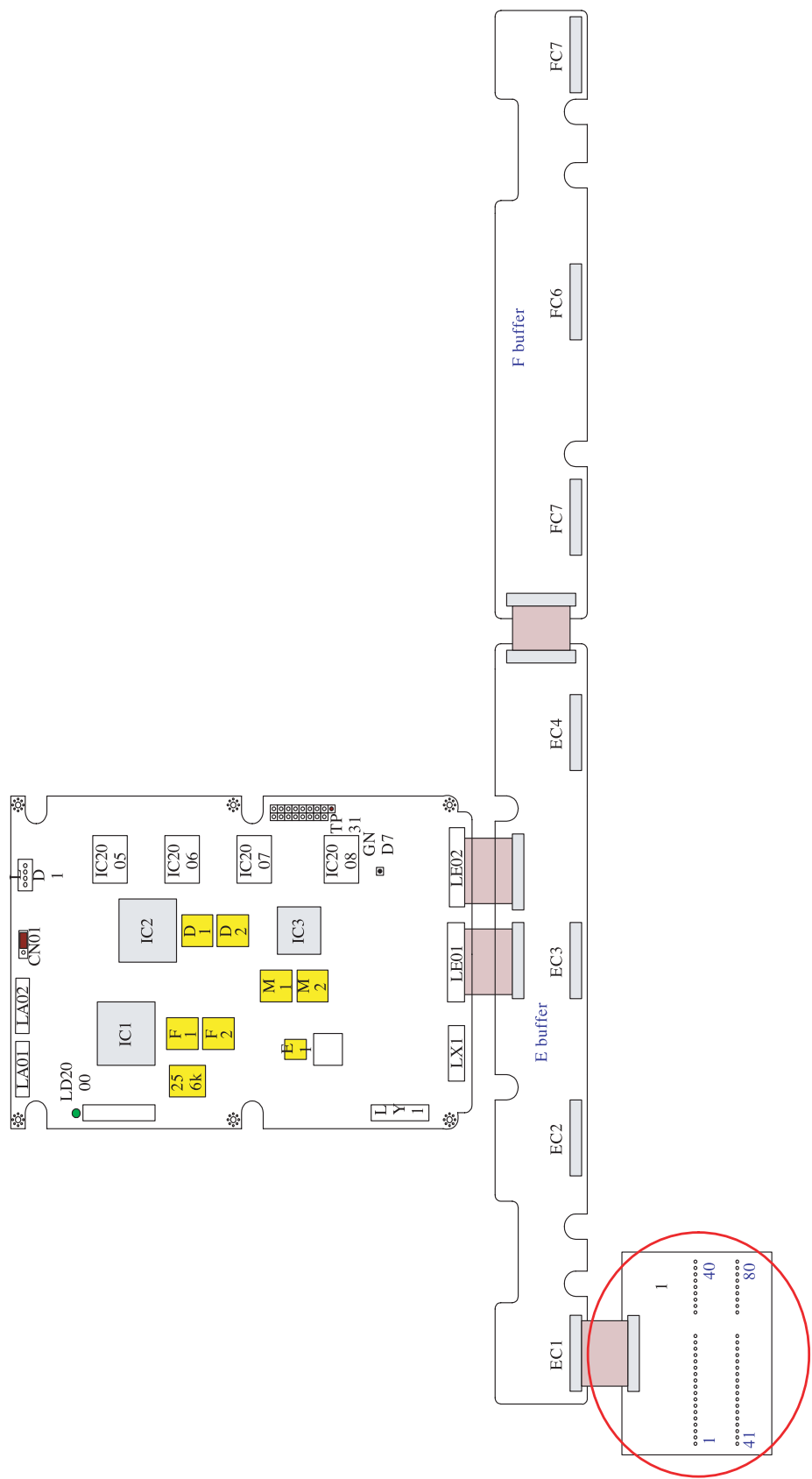
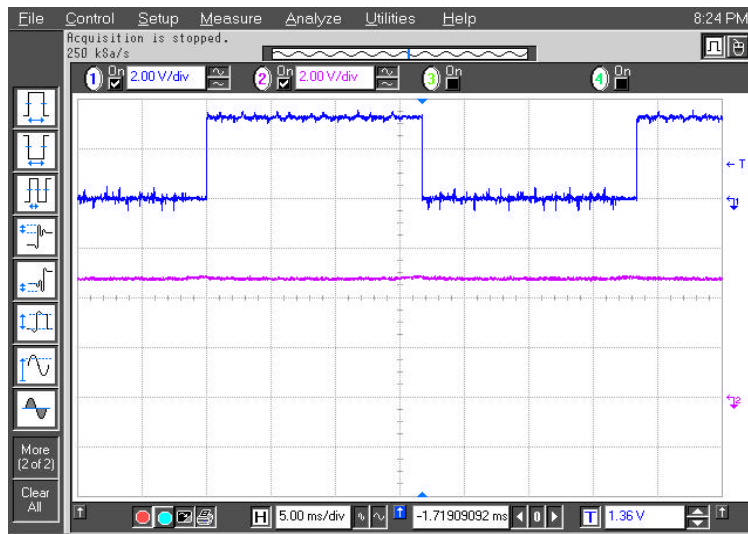
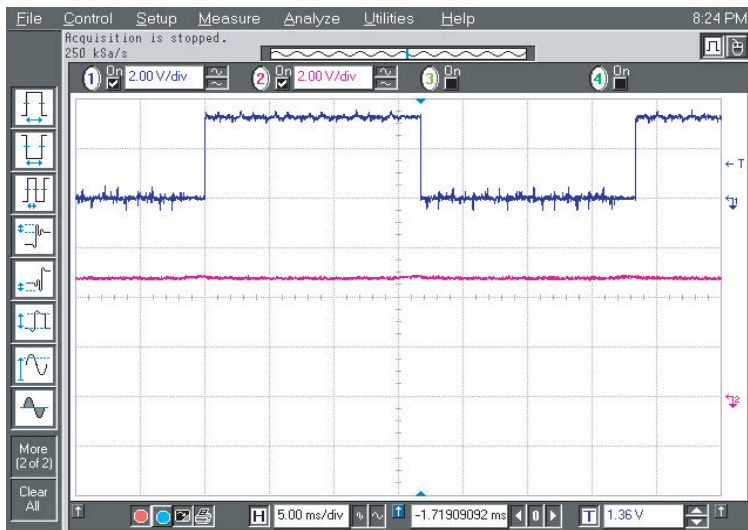


Figure 5. 42” Single logic buffer

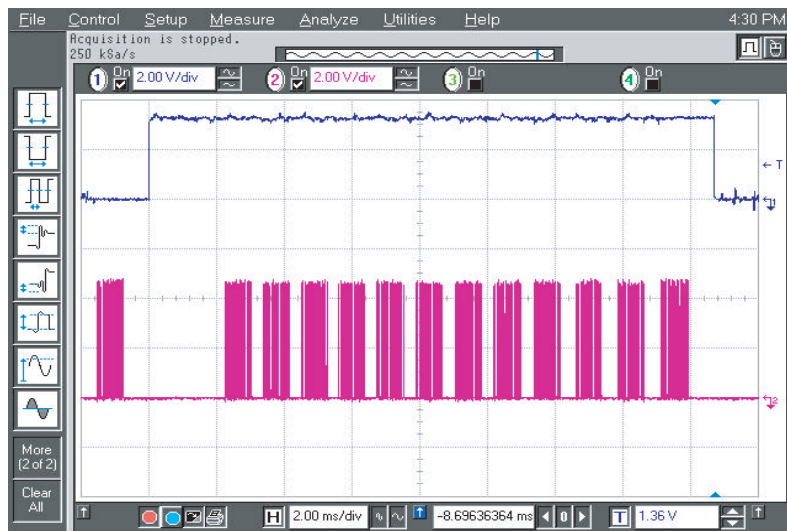
(3) Checking buffer data



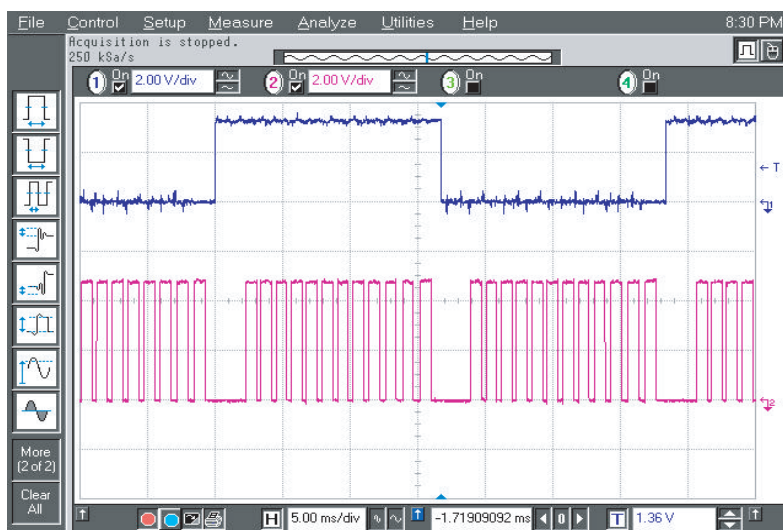
① TP 13 ~ 18, 49 ~ 54 of The Test JIG Board



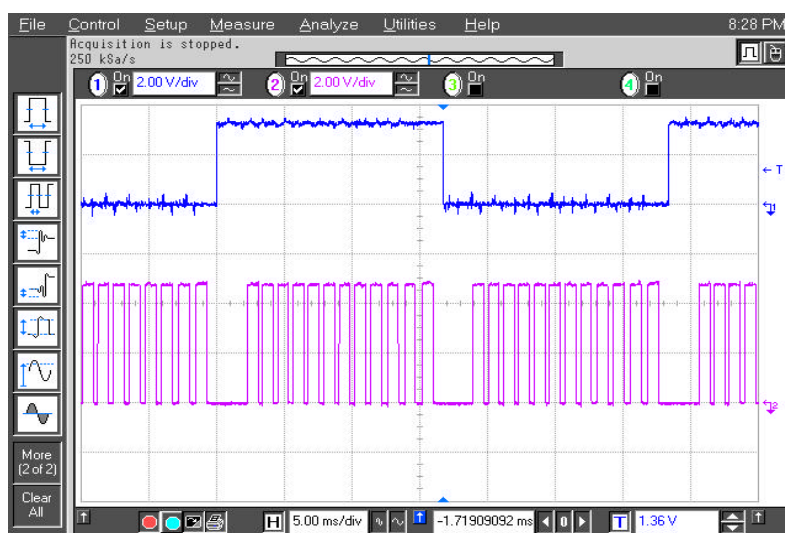
② 21, 57 of The Test JIG Board



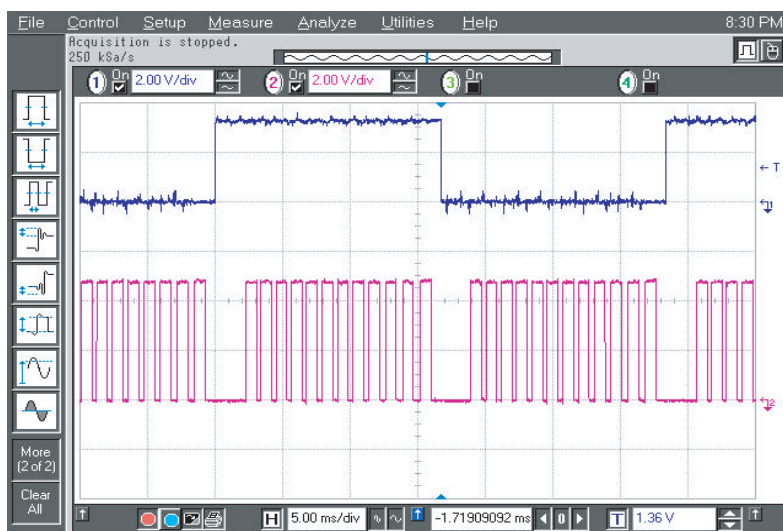
③ 24, 31, 60, 67 of The Test JIG Board



④ TP 25, 32, 61, 68 of The Test JIG Board



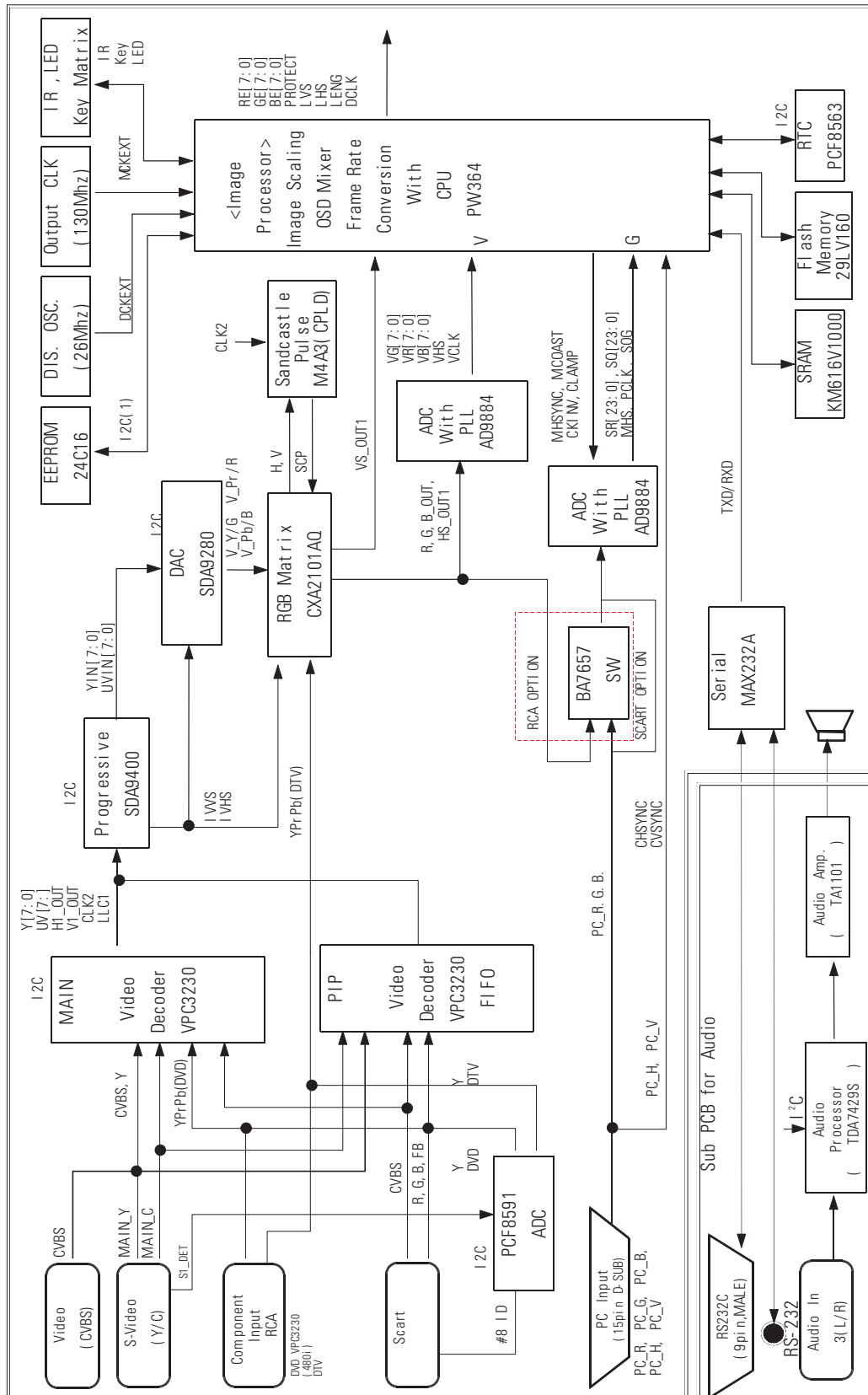
⑤ TP 19, 26, 55, 62 of The Test JIG Board



⑥ TP 20, 27, 56, 63 of The Test JIG Board

5-4 Block Diagram

5-4-1 42" Monitor Scaler Block Diagram



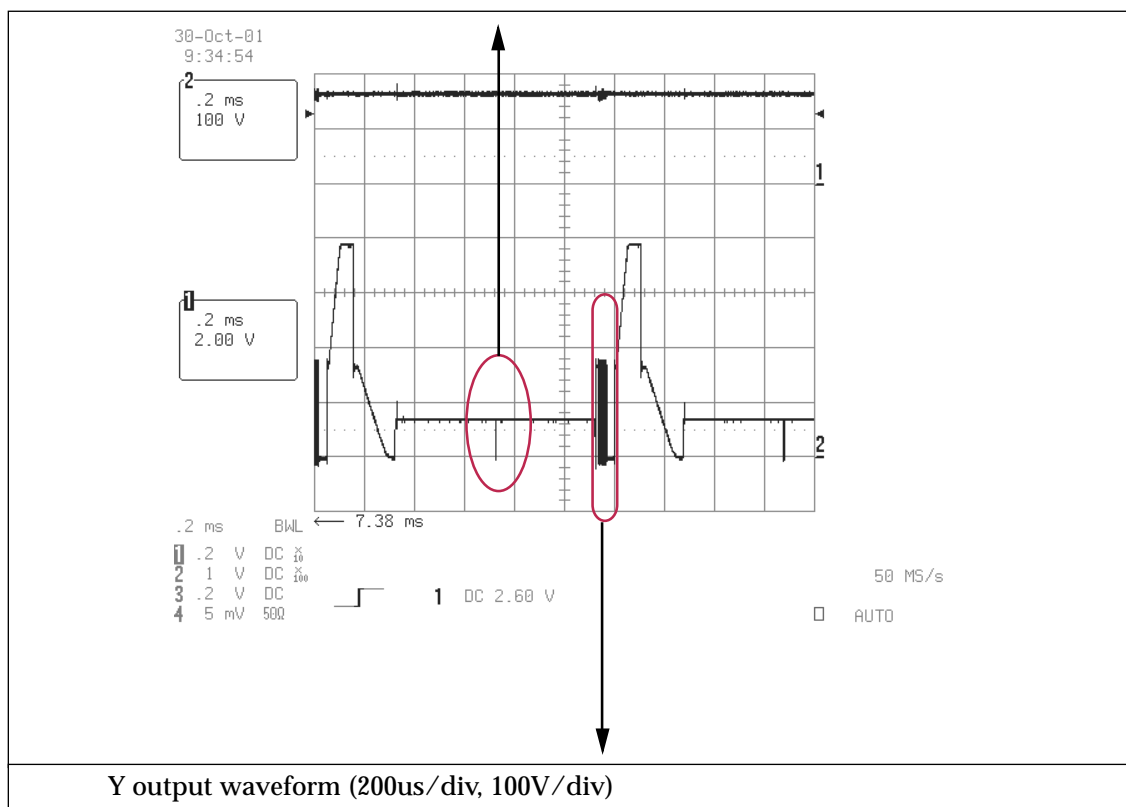
5-5 Major In/Out Signal Waveforms and Voltages of the Unit

5-5-1 In/Out Waveforms

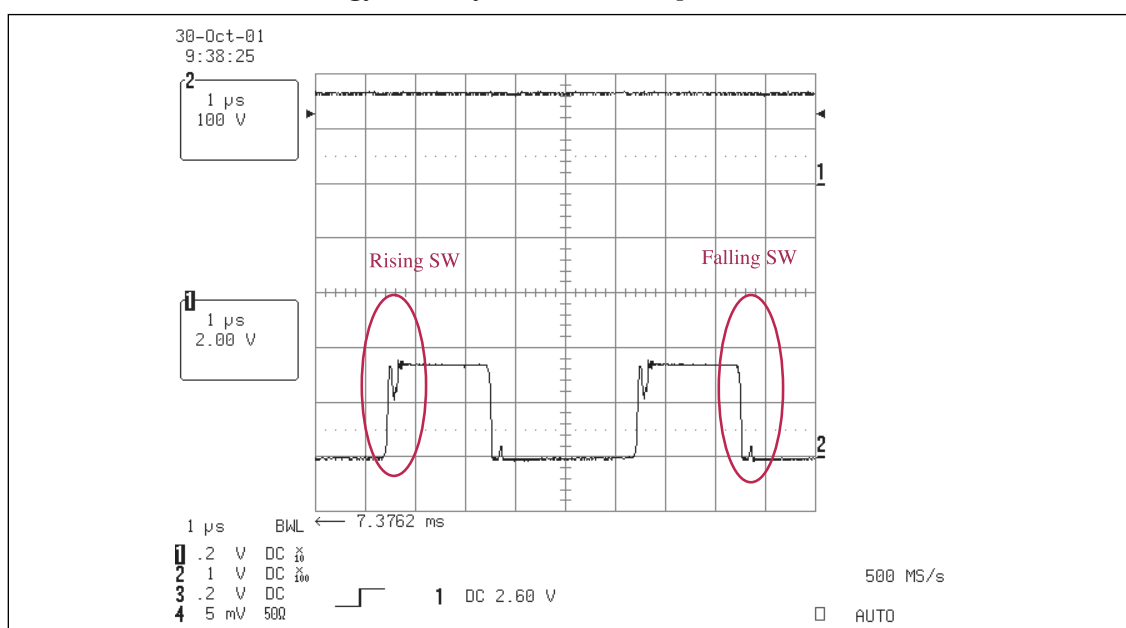
□ Y output waveform

- It is the waveform when it is not connected to the panel.

* You should check that a single scan waveform is outputted!!!

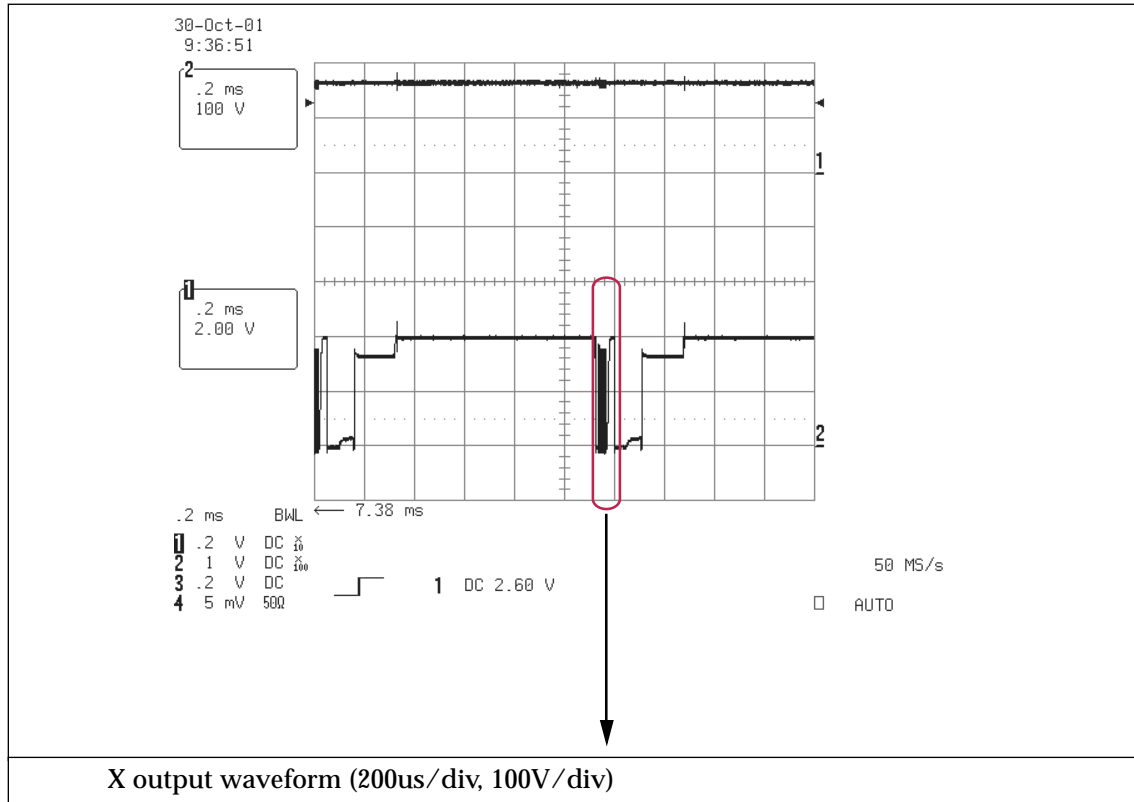


* You should check that energy recovery software is in operation!!!

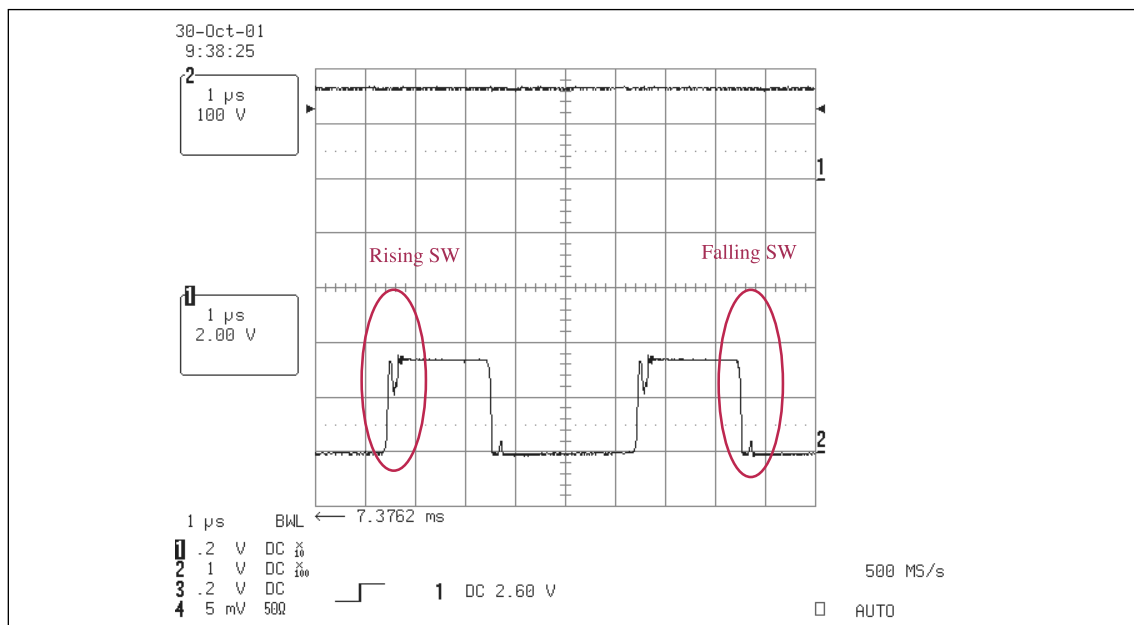


❑ X output waveform

- It is the waveform when it is not connected to the panel.

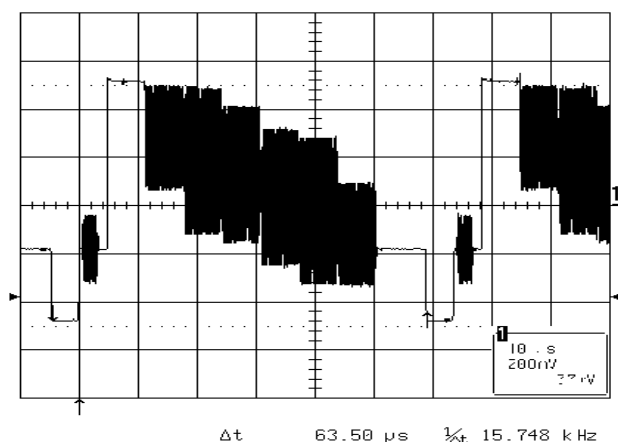


* You should check that energy recovery software is in operation!!!

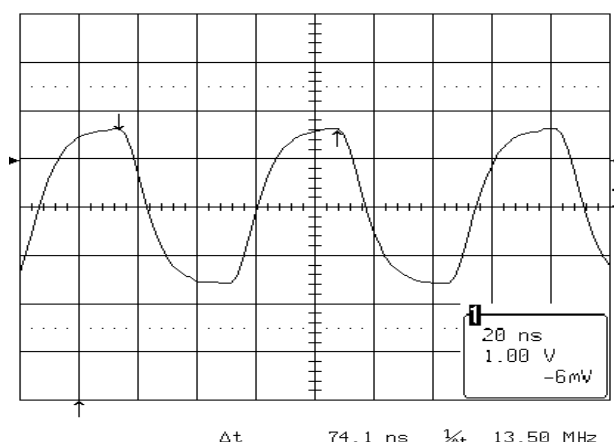


5-6 Main I/O signal pules and voltages

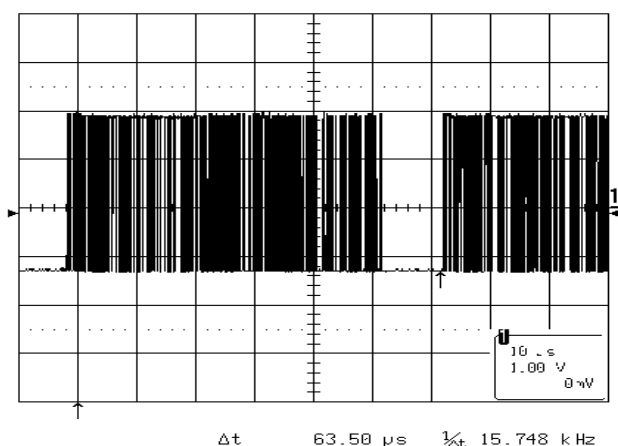
5-6-1 Signal Pulses of Image Board(Input Signal Conditions : 7 Color bar)



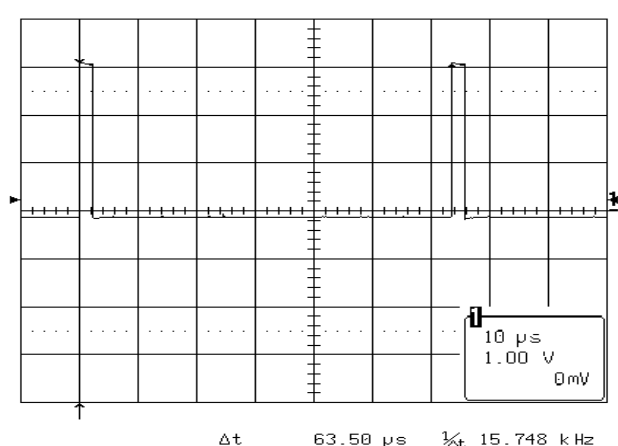
* C203 VIDEO INPUT(CVBS Input)



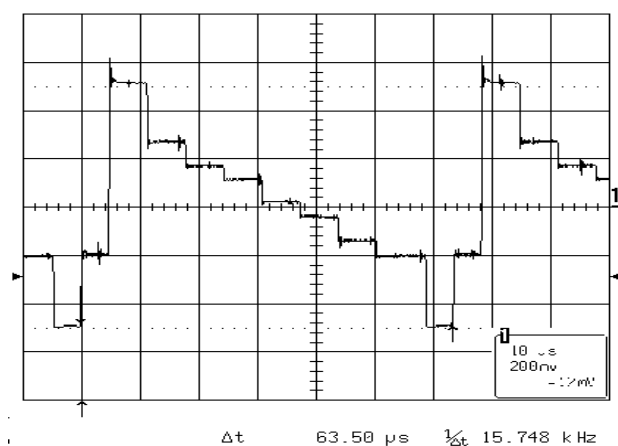
* IC201 (VPC3230 MAIN) PIN28 LLC1_OUT



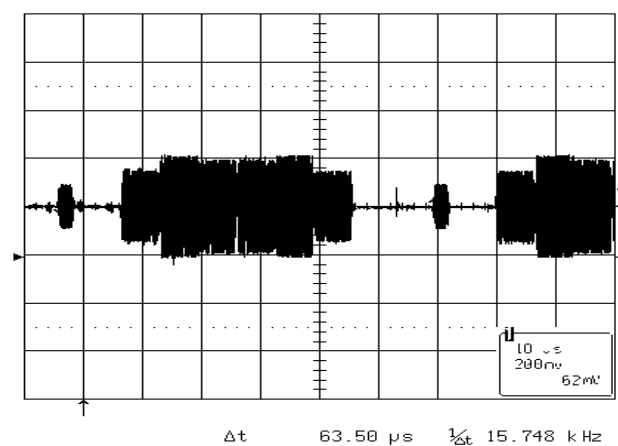
* IC201(VPC3230 MAIN) PIN40 Yo_OUT



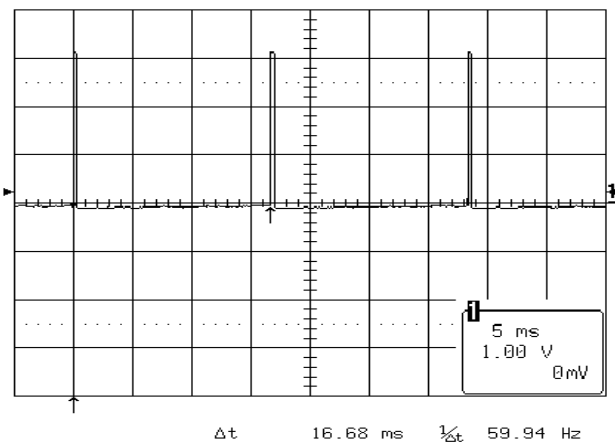
* IC201(VPC3230 MAIN) PIN56 HS_OUT



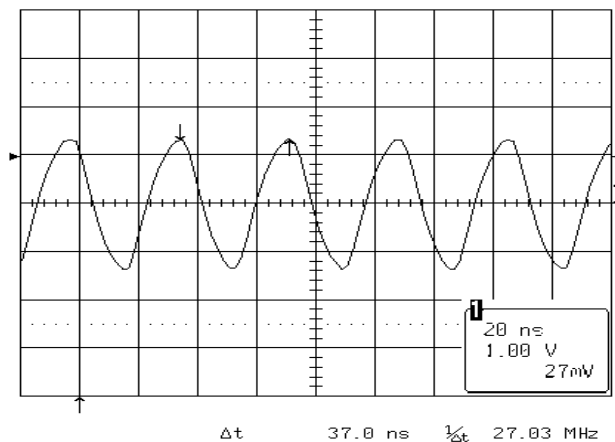
* IC201 (VPC3230 MAIN) PIN74 Y_IN



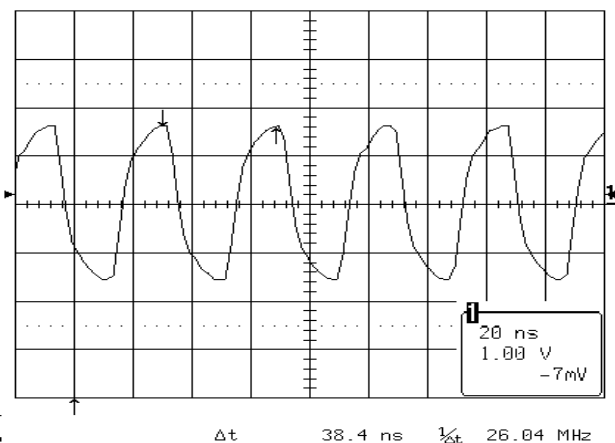
* IC201 (VPC3230 MAIN) PIN72 C_IN



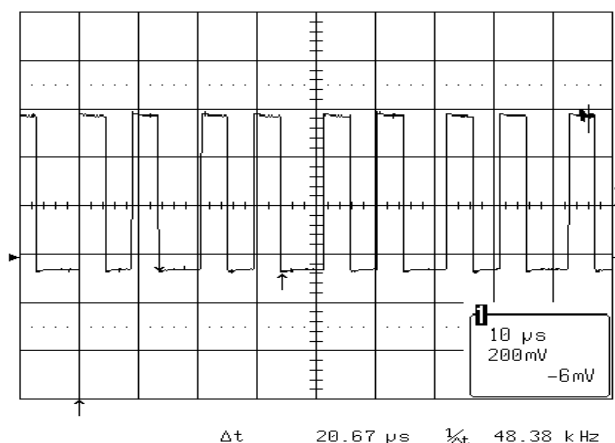
* IC201(VPC3230 MAIN) PIN57 VS_OUT



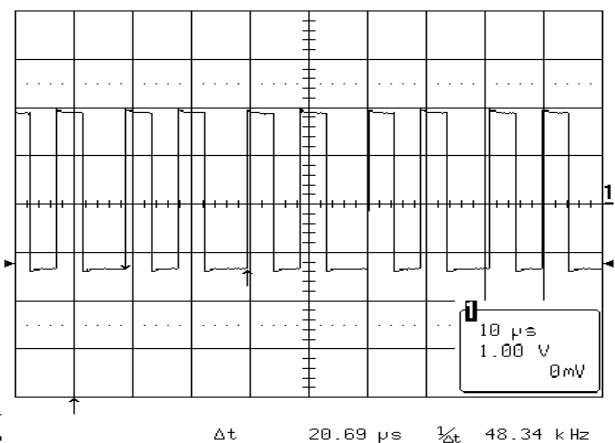
* IC201(VPC3230 MAIN) PIN27 LLC2_OUT



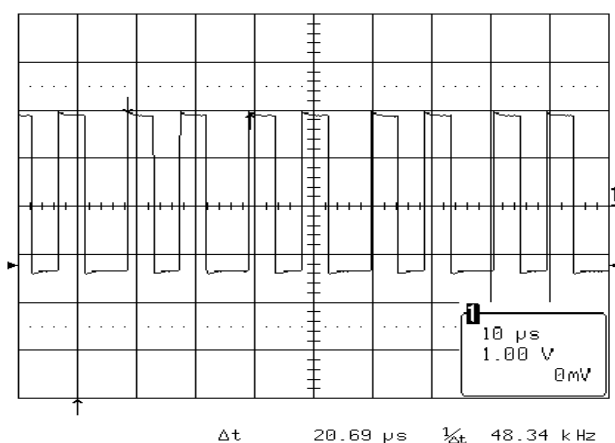
* IC301(PW364) PIN:AD13 DCLK_OUT



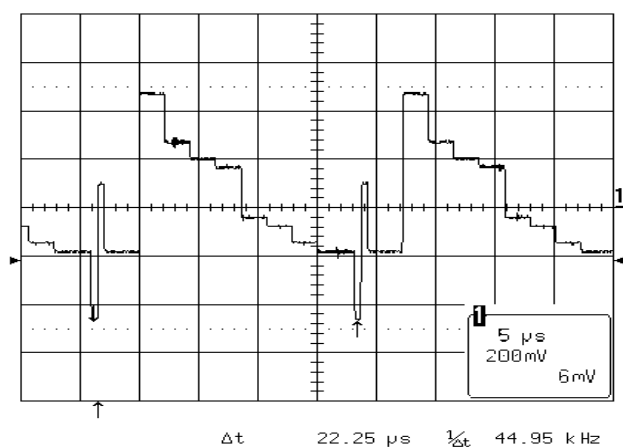
* IC801(AD9884) PIN7 R_IN



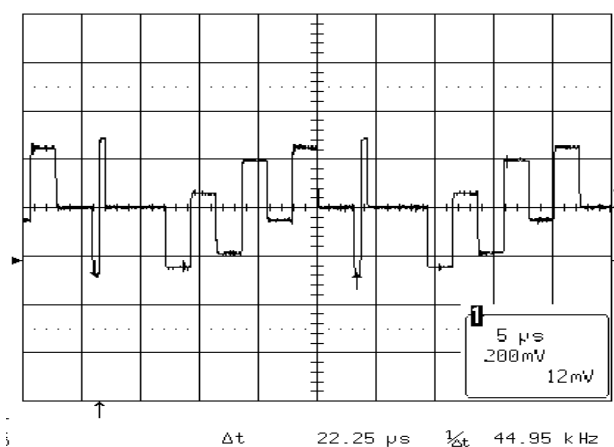
* IC801(AD9884) PIN95 ROUT_ODD



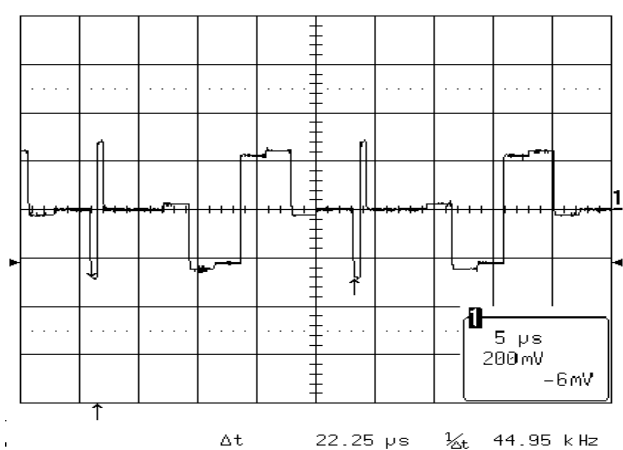
* IC801(AD9884) PIN105 ROUT_EVEN



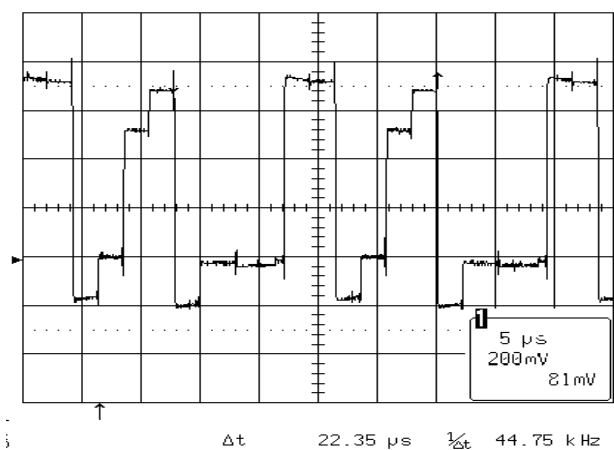
* IC402 (CXA2101AQ) PIN5 DTV.Y_IN



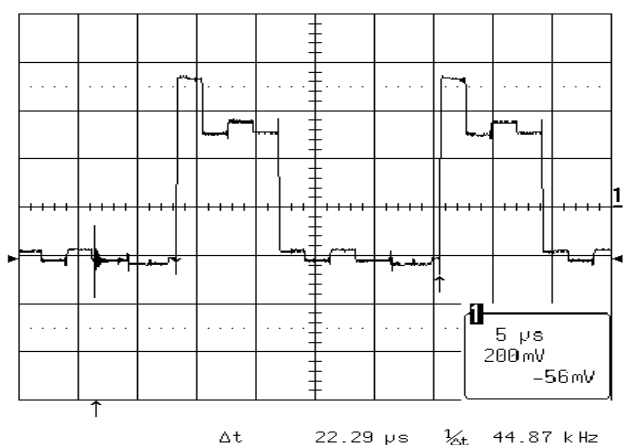
* IC402 (CXA2101AQ) PIN4 DTV.Pb_IN



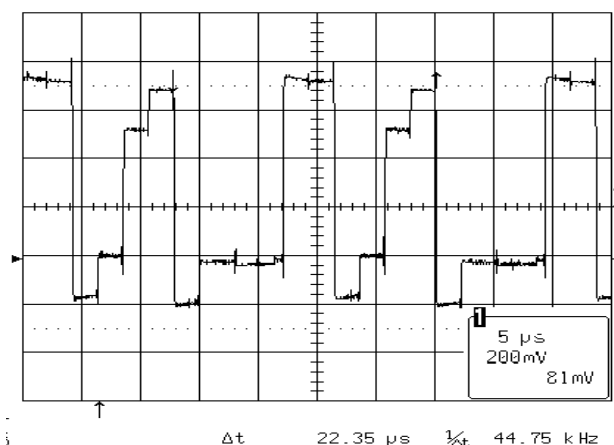
* IC402 (CXA2101AQ) PIN3 DTV.Pr_IN



* IC402 (CXA2101AQ) PIN35 DTV.R_OUT



* IC402 (CXA2101AQ) PIN37 DTV.G_OUT

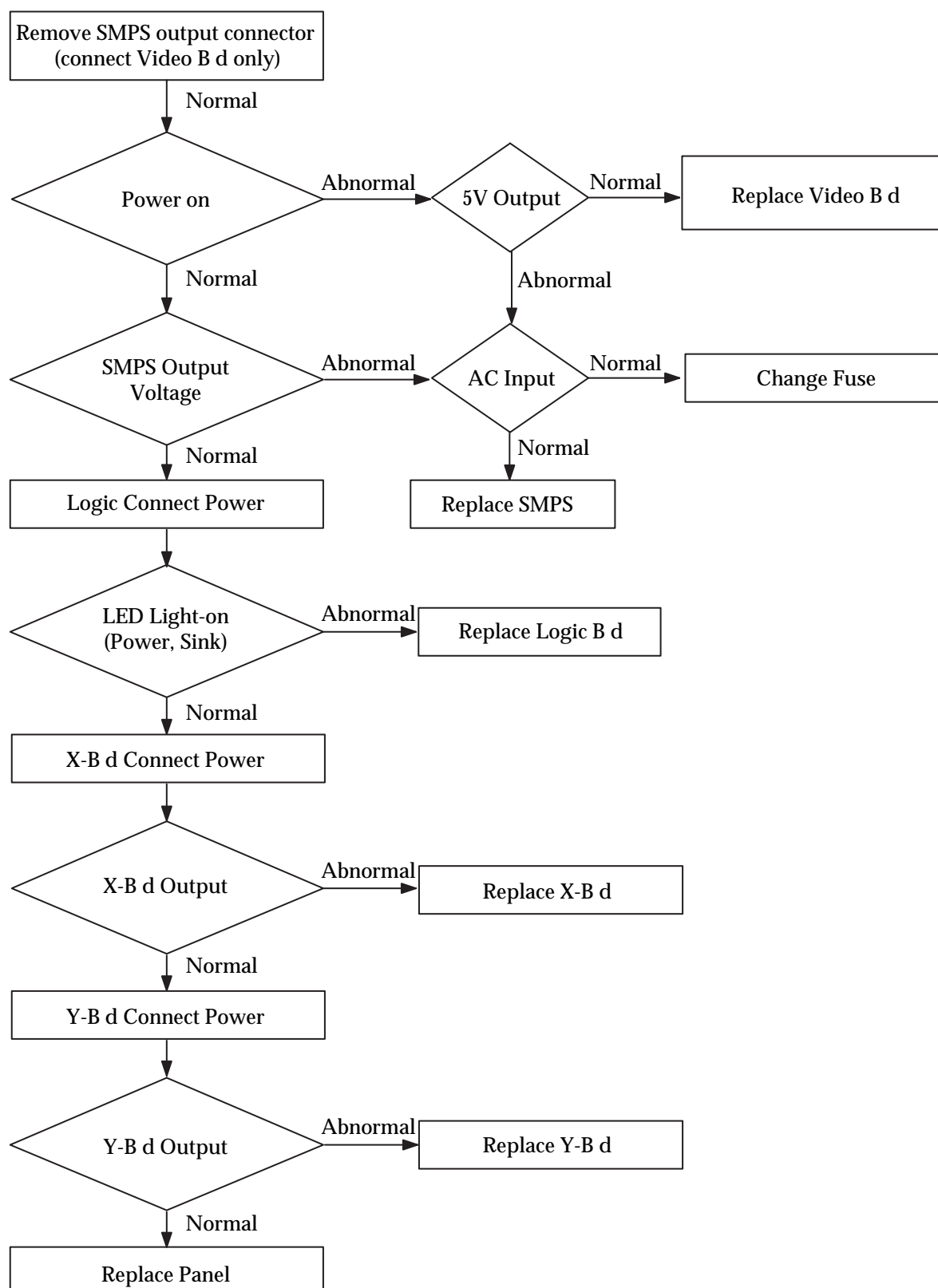


* IC402 (CXA2101AQ) PIN39 DTV.B_OUT

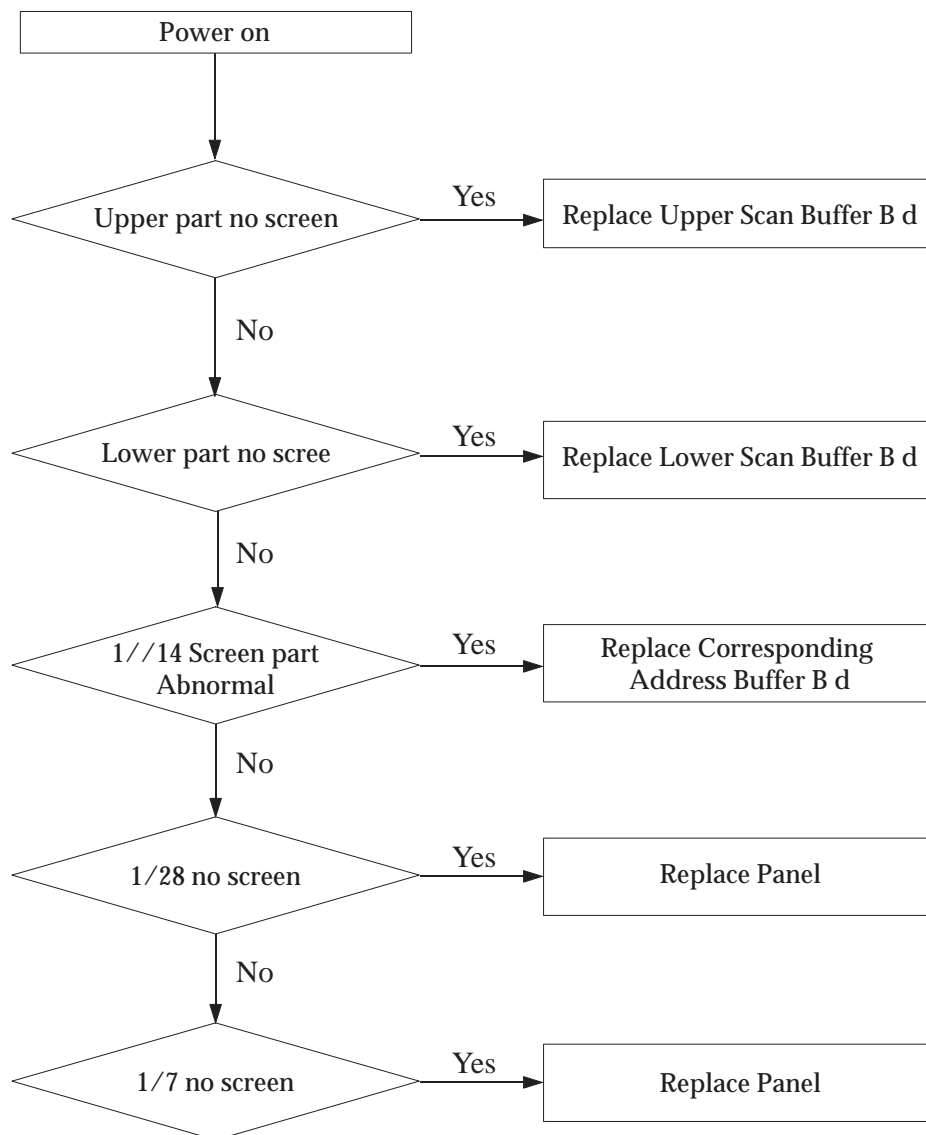
MEMO

6. Troubleshooting

6-1 Entirely no screen



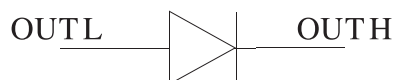
6-2 Partly no screen



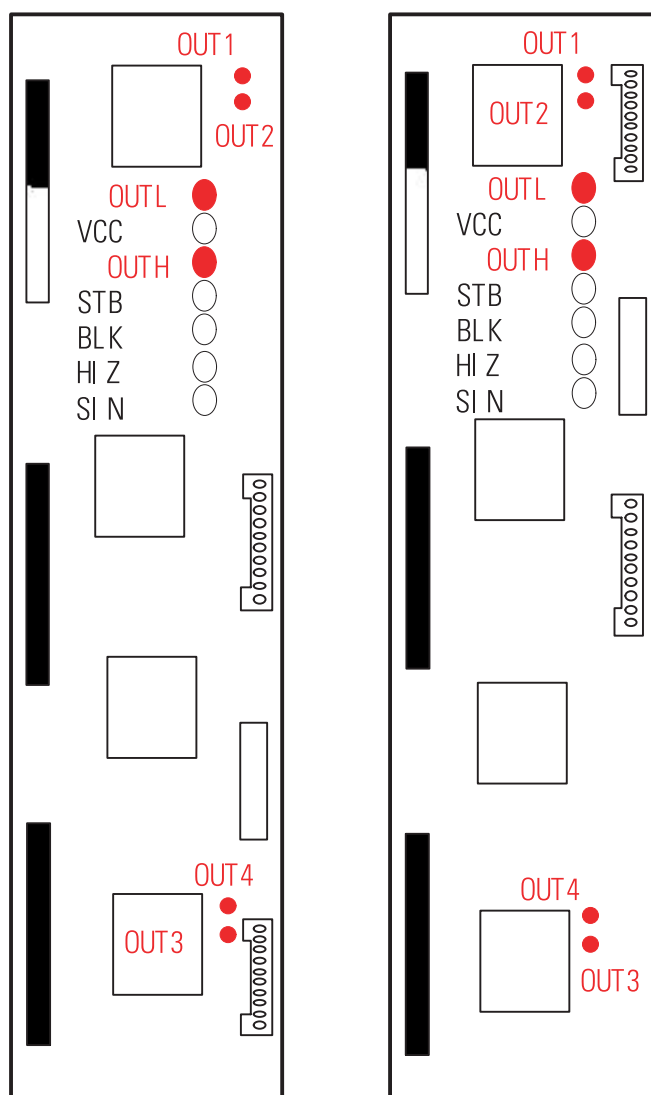
6-3 Checking the Board (Unit)

6-3-1 Y buffer

- To check the main board, you have to check the Y buffer first.
- After separating Y Main and Y buffer board,
- Check the Diode between OUTL and OUTH, and make sure that the forward voltage drop is between 0.4 and 0.5V.

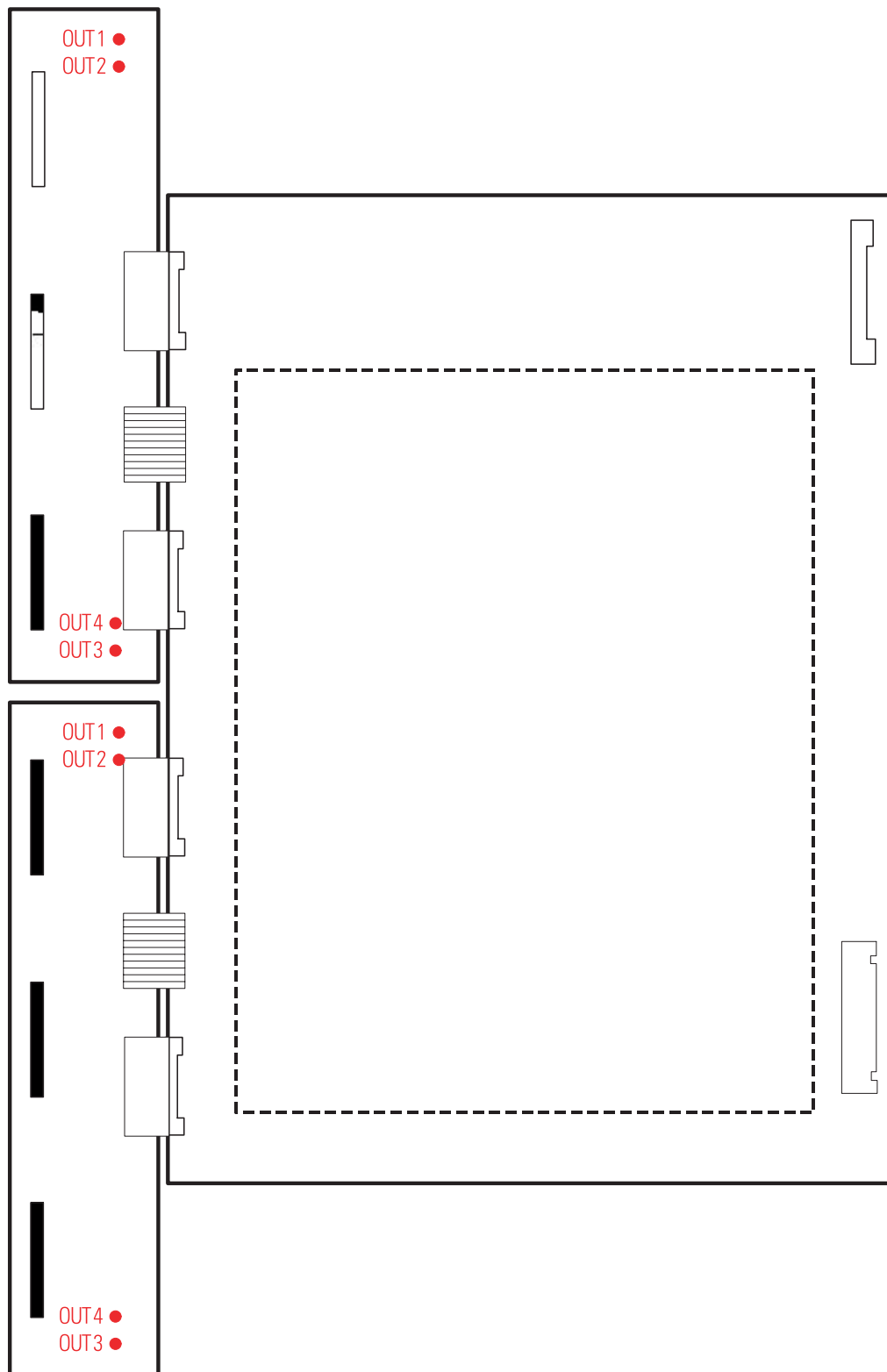


- Check that the resistance between the two terminals is more than several kW.



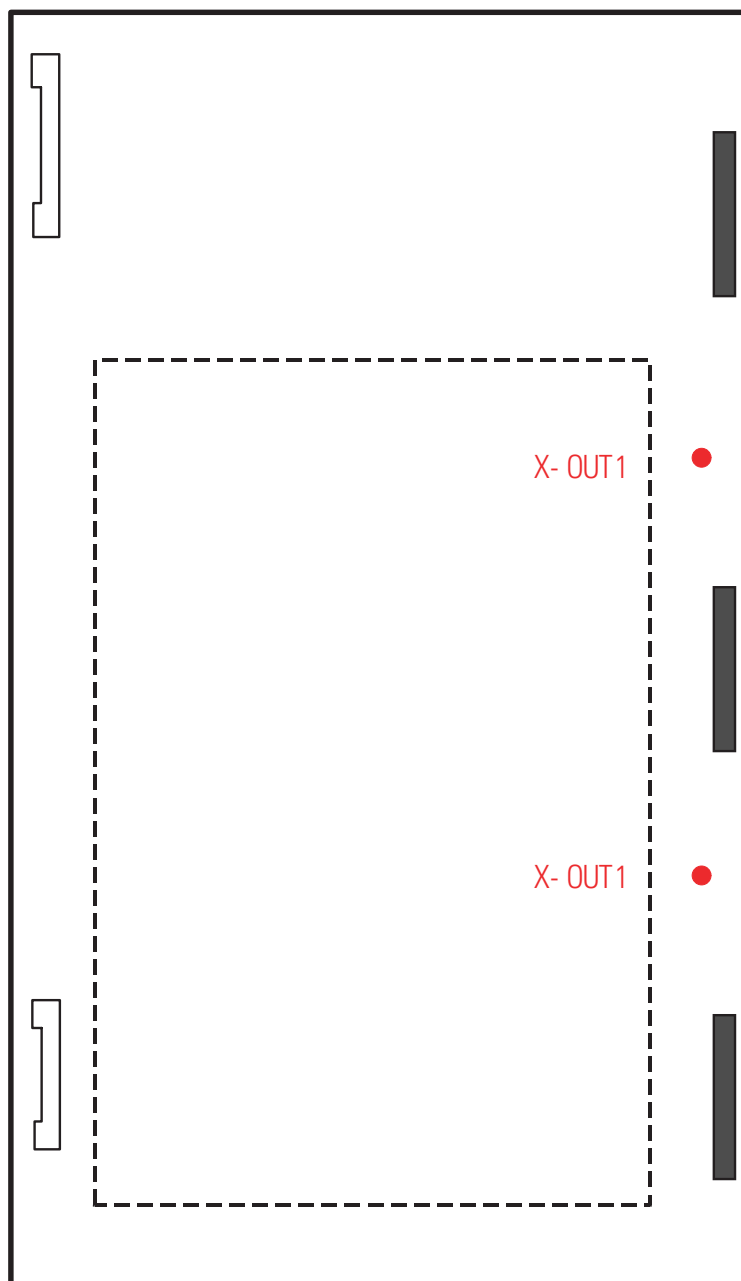
6-3-2 Y Main

- After connecting Y main and Y buffer board, check that one of the output waveforms from OUT 1, 2, 3 or 4 is the same as that of the appendix 1 when power is supplied.



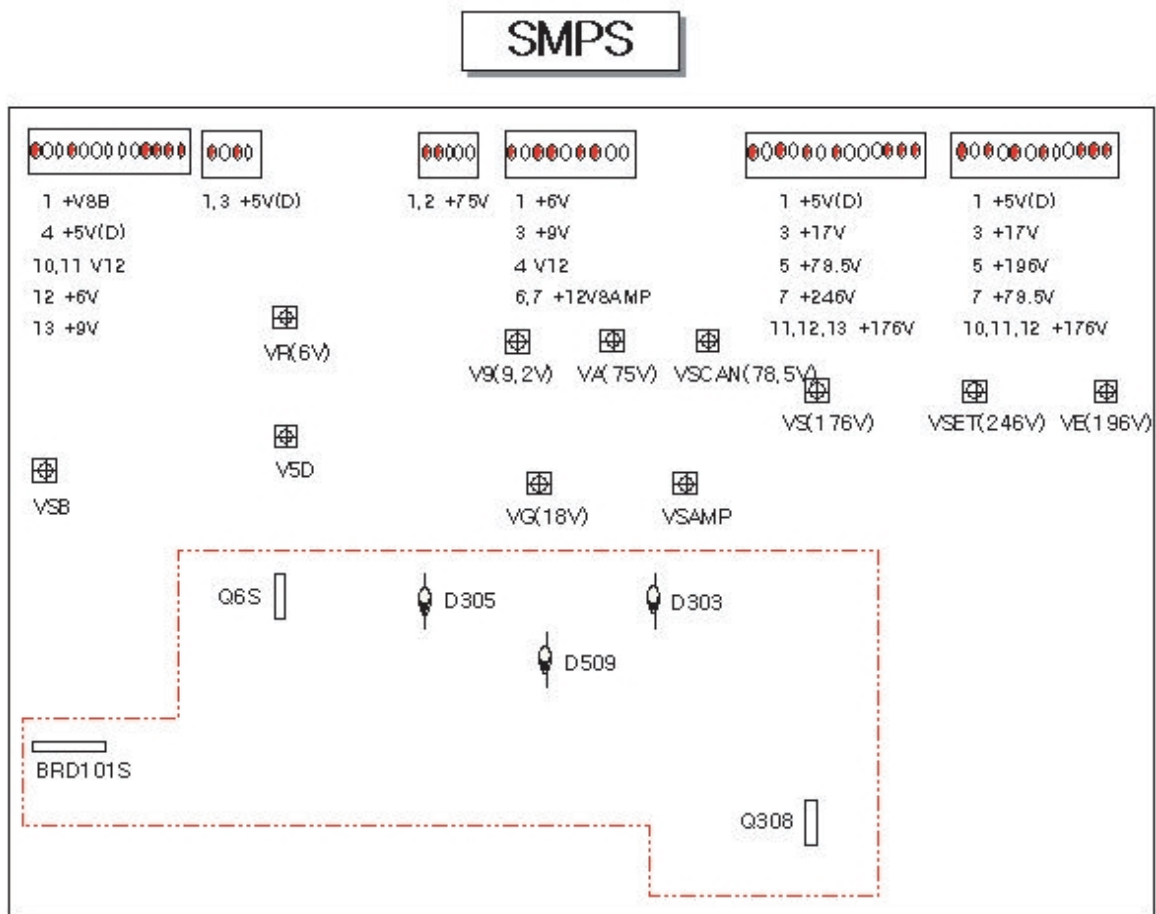
6-3-3 X Board

- Check that one of the output waveforms from X-OUT 1 or 2 is the same as that of the appendix 2 when power is supplied.



6-3-4 SMPS

- Check output voltage.
- If output voltage is not detected, check the following lists:
 - (1) Check fuse
 - (2) In case of +5V(D), check that D305 is short
 - (3) In case of VSAMP, check that D506 is short
 - (4) In case of VA, check that D303 is short
 - (5) In case of VS, check that pin 2 and 3 of Q303 are short
 - (6) In case of Q6S, check that pin 2 and 3 are short
 - (7) Check that BRD101S is short



6-3-5 Scaler Borad

1. PW364 Input Clock

(1) MCKEXT

Check IC406(IC502) pin 5.

Power on : MCKEXT = 97.5MHz

Standby : MCKEXT = 48.75MHz

(2) MCKEXT, DCKEXT

Check IC407(ICS502) pin 25. DCKEXT = 65MHz

(3) VCLK

Check IC203(SDA9400) pin 26. VCLK = 27MHz

(4) GCLK

Check IC401(AD9884) pin 115(TP404).

GCLK is differently seen according to PC input signal format(VGA, SVGA, XGA)

GCLK = 15MHz ~ 50MHz(This value is apparently half of the clock frequency of the relevant PC input signal format.

2. VPC3230

- Check power is supplied(5V, 3.3V).
- Check Reset(pin 15) is high.
- Check I²C-bus(pins 13, 14)
- Check the signal input to Y signal(pin73), C signal(pin 71), PLL DVD-Y signal (pin 72).
- Check the output clocks LLC1(pin 28), LLC2(pin 27). (LLC1 = 13.5MHz, LLC2 = 27MHz)
- Check the output H sync(pin 56) and check V sync(pin 57) is output.
- Check output digital data.

3. SDA9400

- Check power is supplied(3.3V).
- Check Reset(pin 30) is high.
- Check I²C-bus(pins 20, 21)
- Check clock is input.(pins 28, 54 : 27MHz. pin 29 : 13.5MHz)
- Check digital data input.
- Check the input H sync (pin 23) = 15.75MHz, V sync (pin 22) = 60Hz
- Check digital data input.
- Check the output H sync (pin 60) = 31.5KHz, V sync (pin 61) = 60Hz, VCLK (pin 26) = 27MHz

4. AD9884(IC101)

- Check power is supplied(3.3V)
- Check I²C-bus(pins 29, 30)
- Check PC signal, HD-component signal is input.
- Check the input signal GREF (pin 40). The GREF signal applies to a fixed form of the input H sync signal.
- Check the output signal GFBK (pin 117). The GFBK signal applies to a fixed form of PLLD H sync signal.
- Check the output signal GCLK (pin 115). The GCLK is differently seen according to the PC input signal format(VGA, SVGA, XGA).
GCLK = 15MHz ~ 50MHz This value is apparently half of the clock frequency of the relevant PC input signal format.
- Check digital data output.

5. AD9884(IC801)

- Check power is supplied(3.3V).
- Check I²C-bus(pins 29, 30)
- Check Video signal is input.
- Check the input signal 2HS (pin 40 or TP406)
- Check the output signal VHS (pin 117 or TP409)
- Check the output signal VCLK (pin 115 or TP408)
- Check digital data input.

6. PW364 Reset

- When the Reset switch is pressed. if OTP01(29LV160T) pin 28(TP151) undergoes transition. PW364 operates and OTP01 also does. Unless transition happens, it means PW364 is not operating.

7. PW364 Communication

- Operate the PC hyper terminal Settings are as follows :

Model Selection : Direct connect to com1

No. of Bit per second : 57600

Data Bit : 8

Parity : None

Stop Bit : 1

Flow Control : None

- Whenever the Reset switch is pressed, the following is displayed on the PC hyper terminal screen.

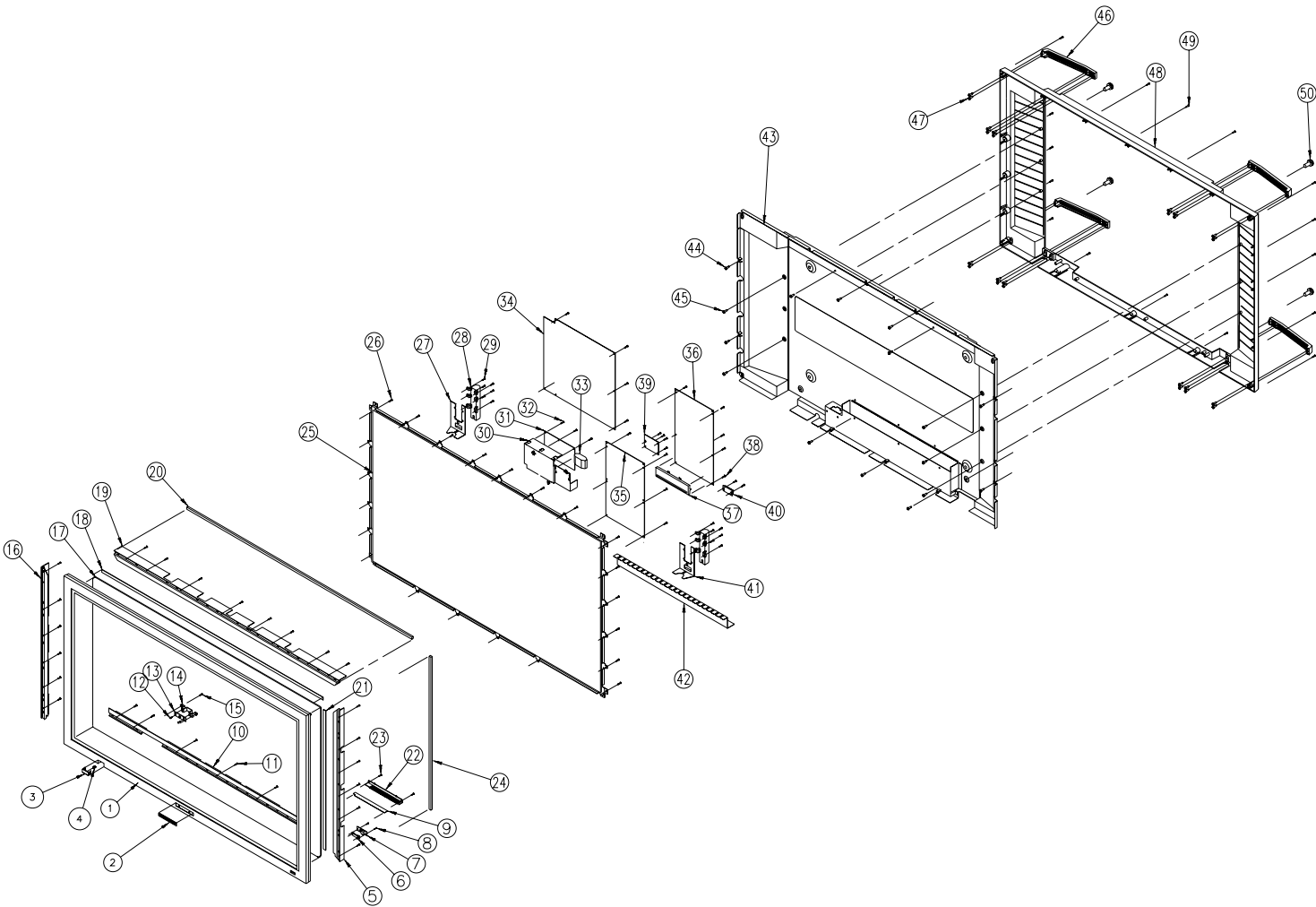
CBooter V1.5 & 2000.01.26

CBooter V1.5 & 2000.01.26

CBooter V1.5 & 2000.01.26

7. Exploded View & Parts List

7-1 PS42P2SDX/XEC



No	Code No	Description;Specification	Q'ty	Remark
1	AA64-01799C	CABINET-FRONT;HIPS HB GRAY,KUJU	1	
2	AA64-01560A	BADGE-BRAND;AL FORGING,SAMSUNG SILVER	1	
3	AA64-01566F	KNOB-MASTER;ABS HB BLK #SV-012P	1	
4	AA61-60003J	SPRING-CS;SUS 304	1	
5	AA61-01061A	BRACKET-FILTER SIDE L,ASSY;AL 6063 EXT,T1.2	1	
6	AA64-01549B	WINDOW-RMC;ACRYL VIOLET	1	
7	AA95-01837F	ASSY SUB-PCB,REMOCON;SPD-42P2S,D51A,AA95	1	
8	6003-000333	SCREW-TAPTITE;M3 * L10 YEL	2	
9	AA95-01751D	ASSY SUB-PCB CONTROL;PS42P2S,D53A,AA95-0		
10	AA61-01062A	BRACKET-FILTER BOT,ASSY;AL 6063 EXT,T1.2	1	
11	6003-001020	SCREW-TAPTITE;RH,+,B,M4,L10,ZPC(YEL)	28	
12	6006-001035	SCREW-ASSY,MACHINE;WSP,PH,M3*L8YEL	2	
13	AA95-01833D	ASSY SUB-PCB,POWER ON/OFF;SPD-42P2S,D51A	1	
14	AA61-00716B	BRACKET-POWER,;SECC,T1.0	1	
15	6003-001026	SCREW-TAPTITE;RH,+,B,M4*L15	2	
16	AA61-01060A	BRACKET-FILTER SIDE R,ASSY;AL 6063 EXT,T1.2	1	
17	AA67-00112A	MIRROR-GLASS;42INCH,P1S,MESH,55%	1	
18	AA72-00017A	SPONGE-EMI,FILTER;SHIELD-FORM,T1.2,D10,L980	2	
19	AA61-01059A	BRACKET-FILTER TOP,ASSY;AL 6063 EXT,T1.2	1	
20	AA60-00110C	SPACER-FILTER;42P2,P/U V0,L,BLK	2	
21	AA72-00018A	SPONGE-EMI,FILTER;SHIELD-FORM,T1.2,D10,L560	2	
22	AA63-00433A	COVER-BOT;42P2S,ABS HB,BLK,SV012P	1	
23	6003-001026	SCREW-TAPTITE;RH,+,B,M4,L15,ZPC(BLK),SWRCH18	2	
24	AA60-00110D	SPACER-FILTER;42P2,P/U V0,L,BLK	2	
25	AA98-00231A	ASSY-PANEL,PDP;PS-42P2S,D53A	1	
26	6003-001026	SCREW-TAPTITE;RH,+,B,M4,L15,ZPC(BLK),SWRCH18	26	
27	AA61-01054A	BRACKET-COVER,RIGHT;PDP,AL 5051,T1.5	1	
28	AA61-00584B	GUIDE-STAND;AL DIECASTING	2	
29	6006-001039	SCREW-ASSY,MACHINE;WSP,PH,M4*L12YEL	12	
30	AA61-00582C	BRACKET-LINE,FILTER;SPC T1.0	1	
31	AA95-01819A	ASSY SUB-PCB,LINE FILTER;PS42P2S,D53A,AA	1	
32	6006-001035	SCREW-ASSY,MACHINE;WSP,PH,M3*L8YEL	6	
33	2901-001222	FILTER-EMI AC LINE;22000PF,24X50X62.3MM	1	
34	AA98-00188A	ASSY-PBA,SMPS;SPD-42P2S,D51A,42SD	1	
35	AA98-00241A	ASSY-PBA,L-MAIN,;42SD,D53A,LJ41-00778A,S	1	
36	AA95-01839A	ASSY SUB-PCB,SCALER;PS42P2S,D53A,AA95-01	1	
37		SHIELD-SCALER,BOT;SPT E T0.25	1	
38	6006-001035	SCREW-ASSY,MACHINE;WSP,PH,M3*L8YEL	6	
39	AA95-01844M	ASSY SUB-PCB,SOUND;PS42P2S,D53A,AA95-013	1	
40	AA95-01770A	ASSY SUB-PCB TERMINAL;PS42P2S,D53A,AA95-	1	
41	AA61-01055A	BRACKET-COVER,LEFT;PDP,AL 5051,T1.5	1	
42	AA63-00491B	COVER-TERMINAL,TV;SUS 304,T0.5	1	
43	AA63-00232A	COVER-BACK,ASSY;AL T1.2,PS-42P2S	1	
44	6003-001019	SCREW-TAPTITE;RH,+,B,M4,L12,ZPC(BLK),SWRCH18	13	
45	6003-001020	SCREW-TAPTITE;RH,+,B,M4,L10,ZPC(YEL),SWRCH18	6	
46	AA64-01551B	HANDLE-SET;ABS,HB,BLK	4	
47	6003-001026	SCREW-TAPTITE;RH,+,B,M4*L15	24	
48	AA64-01802A	CABINET BACK;HIPS V2 BLK 42P2S	1	
49	AA60-10050T	SCREW-TAPPING;SWRCH18A,M4,L20,RH,+,2S,-,ZPC	16	
50	6006-001112	SCREW-ASS'Y MACH;WP,PH,+,M8,L16,ZPC,SWRCH18A	4	

8. Electrical Parts List

8-1 PS42P2SDX/XEC

Level	Loc. No	Code No.	Description ; Specification	Remark	Level	Loc. No.	Code No.	Description ; Specification	Remark	
ASSY CHASSIS										
1	*	AA91-01674A	ASSY CHASSIS;PS42P2SDX/XEC	S.N.A	...		0202-000187	SOLDER-WIRE FLUX;-;RS60S,D1.2,63Sn/37Pb	S.N.A	
..2		AA95-01770A	ASSY SUB-PCB TERMINAL;PS42P2S,D53A,AA95-		...		3301-001201	CORE-FERRITE;AE,21x11x32mm,1500,280G		
...	CN603A	3711-003043	CONNECTOR-HEADER;BOX,4P,1R,2.5mm,STRAIGH		..2		AA95-01837F	ASSY SUB-PCB,REMOCON;SPD-42P2S,D51A,AA95	S.N.A	
...	JK603	AA63-40258A	TERMINAL-SPEAKER;4P,ABS,4,-,-,-,BLK		...	C21	2401-000922	C-AL;22uF,20%,16V,GP,TP,5x5,5		
...	PCB	AA41-00373A	PCB-SPK TERMINAL;SPD-50P2HM,CEM-1,1L,A,1	S.N.A	...	CN21	AA39-00275A	LEAD CONNECTOR ASSY;PDP,UL1007,2547#26,U		
...	SPK	AA39-00294A	LEAD CONNECTOR ASSY;PDP,UL1007#22,UL/CSA		...	D21	0601-001381	LED;ROUND,RED/GRN,5.0MM,650/563NM		
...		0202-000187	SOLDER-WIRE FLUX;-;RS60S,D1.2,63Sn/37Pb	S.N.A	...	MD21	AA59-60002B	MODULE-REMOCON;-;ORC-50HF,38KHz,940mm,ME		
..2		AA95-01819A	ASSY SUB-PCB,LINE FILTER;PS42P2S,D53A,AA		...	PCB	AA41-00371A	PCB-REMOCON;SPD-50P2HM,FR-4,2L,A,1.6T,24	S.N.A	
...	BLF+LF	6001-000516	SCREW-MACHINE;PH,+M3,L10,ZPC(YEL),SM20C		...		AA61-00583B	HOLDER-LED;SPD-50P2H,ABS,BLK	S.N.A	
...	CN812	3711-000203	CONNECTOR-HEADER;1WALL,3P,1R,3.96MM,STRA		...		AA97-05596A	ASSY AUTO-SUB;SPD-42P2S,D51A	S.N.A	
△	CX811S	2306-000321	C-FILM,MPPF;470NF,5%,275V,TP,-,22.5		...	R21	2001-000734	R-CARBON;4.7KOHM,5%,1/8W,AA,TP,1.8X3.2MM		
△	CX812S	2306-000321	C-FILM,MPPF;470NF,5%,275V,TP,-,22.5		...	R22	2001-000793	R-CARBON;470HM,5%,1/8W,AA,TP,1.8X3.2MM		
△	CX813S	2306-000321	C-FILM,MPPF;470NF,5%,275V,TP,-,22.5		...	ZD1	0403-000510	DIODE-ZENER;MTZJ6.2B,6.2V,5.96-6.27V,500		
△	CY811S	2201-000446	C-CERAMIC,DISC;3.3nF,20%,400V,Y5U,TP,15x		...		0202-000187	SOLDER-WIRE FLUX;-;RS60S,D1.2,63Sn/37Pb	S.N.A	
△	CY812S	2201-000446	C-CERAMIC,DISC;3.3nF,20%,400V,Y5U,TP,15x		...		3301-001201	CORE-FERRITE;AE,21x11x32mm,1500,280G		
△	CY813S	2201-000446	C-CERAMIC,DISC;3.3nF,20%,400V,Y5U,TP,15x		..2		AA95-01839A	ASSY SUB-PCB,SCALER;PS42P2S,D53A,AA95-01		
△	CY814S	2201-000446	C-CERAMIC,DISC;3.3nF,20%,400V,Y5U,TP,15x		...	B601	4301-000108	BATTERY-LI;3V,220mA,H,BUTTON,20x3.2mm,NO	S.N.A	
△	CY815S	2201-000446	C-CERAMIC,DISC;3.3nF,20%,400V,Y5U,TP,15x		...	CN301	3711-002645	CONNECTOR-HEADER;BOX,6P,1R,2.5mm,STRAIGH		
△	CY816S	2201-000446	C-CERAMIC,DISC;3.3nF,20%,400V,Y5U,TP,15x		...	CN302	3711-002642	CONNECTOR-HEADER;BOX,3P,1R,2.5mm,STRAIGH	S.N.A	
...	EMI	2901-001222	FILTER-EMI AC LINE;250V,10A,UL,CSA,D,N,S		...	CN401	3711-000600	CONNECTOR-HEADER;BOX,10P,2R,2.54mm,STRAI	S.N.A	
...	FS811A	3602-000114	FUSE-HOLDER;-;30mohm		...	CN601	3711-003047	CONNECTOR-HEADER;BOX,13P,1R,2.5MM,STRAIG		
...	FS811B	3602-000114	FUSE-HOLDER;-;30mohm		...	CN603	3711-001465	CONNECTOR-HEADER;NOWALL,3P,1R,2.54mm,STR		
△	FS811S	3601-001165	FUSE-CARTRIDGE;250V,8A,TIME-LAG,CERAMIC,		...	CN604	3711-001465	CONNECTOR-HEADER;NOWALL,3P,1R,2.54mm,STR		
△	LS812S	AA27-00189A	COIL CHOKE;-;HPL5025M,20UH,10%,0.03OHM,7		...	CN605	3711-001561	CONNECTOR-HEADER;NOWALL,5P,1R,2.54mm,STR		
△	LS813S	AA27-00189A	COIL CHOKE;-;HPL5025M,20UH,10%,0.03OHM,7		...	CN606	3711-002644	CONNECTOR-HEADER;BOX,5P,1R,2.5mm,STRAIGH		
△	UX811S	AA29-00017A	FILTER LINE NOISE;-;25-4MH 7A,0.1OHM,1.5K		...	CN607	3711-001512	CONNECTOR-HEADER;NOWALL,4P,1R,2.54mm,STR		
△	UX812S	AA29-00017A	FILTER LINE NOISE;-;25-4MH 7A,0.1OHM,1.5K		...	CN608	3711-001512	CONNECTOR-HEADER;NOWALL,4P,1R,2.54mm,STR		
...	PCB	AA41-00574A	PCB-LINE FILTER;PS-42P2S,CEM-1,1L,A,1.6T	S.N.A	...	CN609	3711-003974	CONNECTOR-HEADER;BOX,12P,1R,2.5mm,STRAIG		
...	PCB+BL	6006-001035	SCREW-ASS'Y MACH;WSP,PH,+M3,L8,ZPC(YEL)	S.N.A	...	DZ602	0403-001373	DIODE-ZENER;MTZJ5.1A,4.81V-5.07V,500mW,D		
△	PD811S	3711-000203	CONNECTOR-HEADER;1WALL,3P,1R,3.96MM,STRA		...	EF602	2901-000172	FILTER-EMI ON BOARD;50V,10A,-;12x11x13		
△	RX811S	2002-001021	R-COMPOSITION;560KOHM,10%,1/2W,AA,TP,3.7		...	EF603	2901-000172	FILTER-EMI ON BOARD;50V,10A,-;12x11x13		
△	VX811S	1405-000152	VARISTOR;560V,2500A,14x8.5mm,TP		...	IC604	0909-001029	IC-REAL TIME CLOCK;8563;-;DIP,8P,300MIL,		
...		AA61-00582C	BRACKET-LINE;FILTER;SPD-42P2H,SPC,T1.0,N		...	JA501	3722-001178	JACK-PIN;1P,3.4mm,SN,YEL,#16-22		
...		AA64-02554A	INLAY-SHIELD;50P2H,PS SHEET V0,T1.0,BLK		...	JA502	3722-001163	JACK-VHS;4P,12mm,AU,BLK,N		
...		AA65-30105C	CLAMP-WIRE;ALL MODEL,NYLON 66,V2,-,NTR,5	S.N.A	...	JA504	3722-000183	JACK-SCART;21P4mm,SN,BLK,NO		
...		AA97-05562A	ASSY AUTO-SUB;PS42P2S,D53A	S.N.A	...	JA505	3701-001129	CONNECTOR-DSUB;15P,3R,FEMALE,ANGLE,AUF		
...	EL811	AA60-40011B	EYELET;ID2.0,OD3.2,-;BSP,-	S.N.A	...	SW501	3404-000176	SWITCH-TACT;12V,50mA,120gf,6x6mm,SPST		
...	EL812	AA60-40011B	EYELET;ID2.0,OD3.2,-;BSP,-	S.N.A	...	SW601	3404-000176	SWITCH-TACT;12V,50mA,120gf,6x6mm,SPST		
...	EL813	AA60-40011B	EYELET;ID2.0,OD3.2,-;BSP,-	S.N.A	...	X601	2801-003224	CRYSTAL-UNIT;32.768KHz,20ppm,28-AA,Y,12.5		
...	EL814	AA60-40011B	EYELET;ID2.0,OD3.2,-;BSP,-	S.N.A	...		4309-001012	BATTERY-HOLDER;CELL,PIN,20.2mm,24.2x22.2		
...	EY811	AA60-40011A	EYELET;ID2.0,OD2.8,-;BST,-	S.N.A	...		AA63-00343B	SHIELD-CASE,A;SPD42P1S,SPTE,0.5,-,-,-	S.N.A	
...	EY812	AA60-40011A	EYELET;ID2.0,OD2.8,-;BST,-	S.N.A	...		AA63-00344B	SHIELD-CASE,T/A;SPD42P1S,SPTE,T0.5,-,-,-	S.N.A	
...	EY813	AA60-40011A	EYELET;ID2.0,OD2.8,-;BST,-	S.N.A	...		AA97-05576A	ASSY AUTO-SUB;PS42P2S,D53A	S.N.A	
...	EY814	AA60-40011A	EYELET;ID2.0,OD2.8,-;BST,-	S.N.A4	PCB	AA41-00500A	PCB-SCALER;PS42P2S,FR-4,6L,A,1.6T,245X35	S.N.A
...	EY815	AA60-40011A	EYELET;ID2.0,OD2.8,-;BST,-	S.N.A		AA97-06273A	ASSY SMD-SUB;PS42P2S,D53A	S.N.A
...	EY816	AA60-40011A	EYELET;ID2.0,OD2.8,-;BST,-	S.N.A	...	C101	2402-001042	C-AL,SMD;100uF,20%,16V,GP,TP,6.6x6.6x5.4		
...	EY817	AA60-40011A	EYELET;ID2.0,OD2.8,-;BST,-	S.N.A	...	C102	2402-001042	C-AL,SMD;100uF,20%,16V,GP,TP,6.6x6.6x5.4		
...	EY818	AA60-40011A	EYELET;ID2.0,OD2.8,-;BST,-	S.N.A	...	C103	2402-001042	C-AL,SMD;100uF,20%,16V,GP,TP,6.6x6.6x5.4		
...	EY823	AA60-40011A	EYELET;ID2.0,OD2.8,-;BST,-	S.N.A	...	C104	2402-001042	C-AL,SMD;100uF,20%,16V,GP,TP,6.6x6.6x5.4		
...	EY824	AA60-40011A	EYELET;ID2.0,OD2.8,-;BST,-	S.N.A	...	C105	2203-000181	C-CERAMIC,CHIP;100nF,+80-20%,25V,Y5V,TP,		
...	EY825	AA60-40011A	EYELET;ID2.0,OD2.8,-;BST,-	S.N.A	...	C106	2203-000181	C-CERAMIC,CHIP;100nF,+80-20%,25V,Y5V,TP,		
...	EY826	AA60-40011A	EYELET;ID2.0,OD2.8,-;BST,-	S.N.A	...	C107	2203-000979	C-CERAMIC,CHIP;47nF,10%,50V,X7R,TP,2012		
...	EY827	AA60-40011A	EYELET;ID2.0,OD2.8,-;BST,-	S.N.A	...	C108	2203-000979	C-CERAMIC,CHIP;47nF,10%,50V,X7R,TP,2012		
...	EY828	AA60-40011A	EYELET;ID2.0,OD2.8,-;BST,-	S.N.A	...	C109	2203-000979	C-CERAMIC,CHIP;47nF,10%,50V,X7R,TP,2012		
...		AA39-00264B	LEAD CONNECTOR ASSY;PDP,UL1617#18,UL/CSA		...	C110	2203-000979	C-CERAMIC,CHIP;47nF,10%,50V,X7R,TP,2012		
...		6021-000222	NUT-HEXAGON;2C,M3,ZPC(YEL),SM20C 1		...	C111	2402-001049	C-AL,CHIP;10uF,20%,16V,GP,TP,3.3x3.3x5.4		
...		0202-000187	SOLDER-WIRE FLUX;-;RS60S,D1.2,63Sn/37Pb	S.N.A	...	C112	2203-000181	C-CERAMIC,CHIP;100nF,+80-20%,25V,Y5V,TP,		
..2		AA95-01833D	ASSY SUB-PCB,POWER ON/OFF;SPD-42P2S,D51A	S.N.A	...	C113	2203-000181	C-CERAMIC,CHIP;100nF,+80-20%,25V,Y5V,TP,		
...	CN01	AA39-20468F	LEAD CONNECTOR ASSY;PDP,UL2547#26,UL/CSA		...	C114	2203-000181	C-CERAMIC,CHIP;100nF,+80-20%,25V,Y5V,TP,		
...	PCB	AA41-00494A	PCB-POWER S/W;HPL5025M,FR-4,2L,A,1.6T,24	S.N.A	...	C115	2203-000181	C-CERAMIC,CHIP;100nF,+80-20%,25V,Y5V,TP,		
...	PCB+BP	6006-001035	SCREW-ASS'Y MACH;WSP,PH,+M3,L8,ZPC(YEL)	S.N.A	...	C116	2203-000389	C-CERAMIC,CHIP;0.015nF,5%,50V,NP0,TP,201		
...	R01	2001-000281	R-CARBON;100OHM,5%,1/8W,AA,TP,1.8X3.2MM		...	C117	2203-000389	C-CERAMIC,CHIP;0.015nF,5%,50V,NP0,TP,201		
...	SW01	3404-001006	SWITCH-TACT;12V,50mA,160gf,6x6mm,SPST		...	C118	2203-000389	C-CERAMIC,CHIP;0.015nF,5%,50V,NP0,TP,201		
...		AA61-00716B	BRACKET-POWER;SECC,T1.0		...	C119	2203-000181	C-CERAMIC,CHIP;100nF,+80-20%,25V,Y5V,TP,		
...					...	C120	2203-000181	C-CERAMIC,CHIP;100nF,+80-20%,25V,Y5V,TP,		
...					...	C121	2203-000181	C-CERAMIC,CHIP;100nF,+80-20%,25V,Y5V,TP,		
...					...	C122	2203-000181	C-CERAMIC,CHIP;100nF,+80-20%,25V,Y5V,TP,		
...					...	C123	2203-000181	C-CERAMIC,CHIP;100nF,+80-20%,25V,Y5V,TP,		

Level	Loc. No.	Code No.	Description : Specification	Remark
....5	CP130	2402-001071	C-AL,SMD;220uF,20%,10V,GP,TP,8.3x8.3x6.	
....5	CP131	2203-000181	C-CERAMIC,CHIP;100nF,+80-20%,25V,Y5V,TP,	
....5	CP132	2203-000181	C-CERAMIC,CHIP;100nF,+80-20%,25V,Y5V,TP,	
....5	CP133	2203-000838	C-CERAMIC,CHIP;0.39nF,5%,50V,N0P,TP,1608	
....5	CP134	2203-000575	C-CERAMIC,CHIP;220NF,10%,25V,X7R,TP,2012	
....5	CP135	2203-000140	C-CERAMIC,CHIP;1.5nF,10%,50V,X7R,TP,1608	
....5	CP136	2203-000181	C-CERAMIC,CHIP;100nF,+80-20%,25V,Y5V,TP,	
....5	CP137	2203-000181	C-CERAMIC,CHIP;100nF,+80-20%,25V,Y5V,TP,	
....5	CP138	2203-000181	C-CERAMIC,CHIP;100nF,+80-20%,25V,Y5V,TP,	
....5	CP139	2203-000181	C-CERAMIC,CHIP;100nF,+80-20%,25V,Y5V,TP,	
....5	CP140	2203-000181	C-CERAMIC,CHIP;100nF,+80-20%,25V,Y5V,TP,	
....5	CP141	2203-000181	C-CERAMIC,CHIP;100nF,+80-20%,25V,Y5V,TP,	
....5	CP142	2203-000181	C-CERAMIC,CHIP;100nF,+80-20%,25V,Y5V,TP,	
....5	CP143	2203-000181	C-CERAMIC,CHIP;100nF,+80-20%,25V,Y5V,TP,	
....5	CP144	2203-000181	C-CERAMIC,CHIP;100nF,+80-20%,25V,Y5V,TP,	
....5	CP145	2203-000140	C-CERAMIC,CHIP;1.5nF,10%,50V,X7R,TP,1608	
....5	CP146	2402-001042	C-AL,SMD;100uF,20%,16V,GP,TP,6.6x6.6x5.4	
....5	CP147	2203-000181	C-CERAMIC,CHIP;100nF,+80-20%,25V,Y5V,TP,	
....5	CP148	2203-000181	C-CERAMIC,CHIP;100nF,+80-20%,25V,Y5V,TP,	
....5	CP149	2203-000979	C-CERAMIC,CHIP;47nF,10%,50V,X7R,TP,2012	
....5	CP150	2203-000181	C-CERAMIC,CHIP;100nF,+80-20%,25V,Y5V,TP,	
....5	CP151	2203-000181	C-CERAMIC,CHIP;100nF,+80-20%,25V,Y5V,TP,	
....5	CP152	2203-000181	C-CERAMIC,CHIP;100nF,+80-20%,25V,Y5V,TP,	
....5	CP153	2203-000181	C-CERAMIC,CHIP;100nF,+80-20%,25V,Y5V,TP,	
....5	CP154	2203-000575	C-CERAMIC,CHIP;220NF,10%,25V,X7R,TP,2012	
....5	CP155	2203-000761	C-CERAMIC,CHIP;330nF,10%,16V,X7R,TP,2012	
....5	CP156	2203-000761	C-CERAMIC,CHIP;330nF,10%,16V,X7R,TP,2012	
....5	D301	0401-000008	DIODE-SWITCHING;DAN217,80V,100mA,SOT-23,	
....5	D302	0401-000008	DIODE-SWITCHING;DAN217,80V,100mA,SOT-23,	
....5	D303	0401-000008	DIODE-SWITCHING;DAN217,80V,100mA,SOT-23,	
....5	D304	0401-000008	DIODE-SWITCHING;DAN217,80V,100mA,SOT-23,	
....5	D401	0401-000133	DIODE-SWITCHING;RLS4148,100V,200MA,SOD-8	
....5	D402	0401-000133	DIODE-SWITCHING;RLS4148,100V,200MA,SOD-8	
....5	D403	0401-000133	DIODE-SWITCHING;RLS4148,100V,200MA,SOD-8	
....5	D501	0401-000008	DIODE-SWITCHING;DAN217,80V,100mA,SOT-23,	
....5	D502	0401-000008	DIODE-SWITCHING;DAN217,80V,100mA,SOT-23,	
....5	D503	0401-000008	DIODE-SWITCHING;DAN217,80V,100mA,SOT-23,	
....5	D504	0401-000008	DIODE-SWITCHING;DAN217,80V,100mA,SOT-23,	
....5	D505	0401-000008	DIODE-SWITCHING;DAN217,80V,100mA,SOT-23,	
....5	D506	0401-000008	DIODE-SWITCHING;DAN217,80V,100mA,SOT-23,	
....5	D507	0401-000008	DIODE-SWITCHING;DAN217,80V,100mA,SOT-23,	
....5	D508	0401-000008	DIODE-SWITCHING;DAN217,80V,100mA,SOT-23,	
....5	D509	0401-000008	DIODE-SWITCHING;DAN217,80V,100mA,SOT-23,	
....5	D510	0401-000008	DIODE-SWITCHING;DAN217,80V,100mA,SOT-23,	
....5	D511	0401-000008	DIODE-SWITCHING;DAN217,80V,100mA,SOT-23,	
....5	D512	0401-000008	DIODE-SWITCHING;DAN217,80V,100mA,SOT-23,	
....5	D513	0401-000008	DIODE-SWITCHING;DAN217,80V,100mA,SOT-23,	
....5	D514	0401-000008	DIODE-SWITCHING;DAN217,80V,100mA,SOT-23,	
....5	D515	0401-000008	DIODE-SWITCHING;DAN217,80V,100mA,SOT-23,	
....5	D516	0401-000008	DIODE-SWITCHING;DAN217,80V,100mA,SOT-23,	
....5	D517	0401-000008	DIODE-SWITCHING;DAN217,80V,100mA,SOT-23,	
....5	D518	0401-000008	DIODE-SWITCHING;DAN217,80V,100mA,SOT-23,	
....5	D519	0401-000008	DIODE-SWITCHING;DAN217,80V,100mA,SOT-23,	
....5	D601	0401-000133	DIODE-SWITCHING;RLS4148,100V,200MA,SOD-8	
....5	D602	0401-000133	DIODE-SWITCHING;RLS4148,100V,200MA,SOD-8	
....5	D603	0401-000133	DIODE-SWITCHING;RLS4148,100V,200MA,SOD-8	
....5	D604	0401-000133	DIODE-SWITCHING;RLS4148,100V,200MA,SOD-8	
....5	DZ501	0403-000314	DIODE-ZENER;RLZJ9.1B,9.1V,8.80-9.30V,400	
....5	DZ502	0403-000314	DIODE-ZENER;RLZJ9.1B,9.1V,8.80-9.30V,400	
....5	EF101	2901-001114	FILTER-EMI SMD;25VDC,2.0ADC,-,100nF,3.2x	
....5	EF102	2901-001114	FILTER-EMI SMD;25VDC,2.0ADC,-,100nF,3.2x	
....5	EF201	2901-001114	FILTER-EMI SMD;25VDC,2.0ADC,-,100nF,3.2x	
....5	EF204	2901-001114	FILTER-EMI SMD;25VDC,2.0ADC,-,100nF,3.2x	
....5	EF205	2901-001114	FILTER-EMI SMD;25VDC,2.0ADC,-,100nF,3.2x	
....5	EF206	2901-001114	FILTER-EMI SMD;25VDC,2.0ADC,-,100nF,3.2x	
....5	EF301	2901-001114	FILTER-EMI SMD;25VDC,2.0ADC,-,100nF,3.2x	
....5	EF302	2901-001114	FILTER-EMI SMD;25VDC,2.0ADC,-,100nF,3.2x	
....5	EF401	2901-001114	FILTER-EMI SMD;25VDC,2.0ADC,-,100nF,3.2x	
....5	EF402	2901-001114	FILTER-EMI SMD;25VDC,2.0ADC,-,100nF,3.2x	
....5	EF403	2901-001114	FILTER-EMI SMD;25VDC,2.0ADC,-,100nF,3.2x	
....5	EF404	2901-001114	FILTER-EMI SMD;25VDC,2.0ADC,-,100nF,3.2x	
....5	EF501	2901-000226	FILTER-EMI SMD;25V,0.3A,-,100pF,3.2x1.25	
....5	EF504	2901-000226	FILTER-EMI SMD;25V,0.3A,-,100pF,3.2x1.25	
....5	EF505	2901-000226	FILTER-EMI SMD;25V,0.3A,-,100pF,3.2x1.25	
....5	EF506	2901-000226	FILTER-EMI SMD;25V,0.3A,-,100pF,3.2x1.25	
....5	EF507	2901-000226	FILTER-EMI SMD;25V,0.3A,-,100pF,3.2x1.25	
....5	EF509	2901-000226	FILTER-EMI SMD;25V,0.3A,-,100pF,3.2x1.25	

Level	Loc. No.	Code No.	Description ; Specification	Remark	Level	Loc. No.	Code No.	Description ; Specification	Remark
.....5	EF510	2901-000226	FILTER-EMI SMD;25V,0.3A,-,100pF,3.2x1.25	5	Q502	0501-000344	TR-SMALL SIGNAL;KSC1623-G,NPN,200mW,SOT-	
.....5	EF511	2901-000226	FILTER-EMI SMD;25V,0.3A,-,100pF,3.2x1.25	5	Q503	0501-000344	TR-SMALL SIGNAL;KSC1623-G,NPN,200mW,SOT-	
.....5	EF512	2901-000226	FILTER-EMI SMD;25V,0.3A,-,100pF,3.2x1.25	5	Q504	0501-000344	TR-SMALL SIGNAL;KSC1623-G,NPN,200mW,SOT-	
.....5	EF516	2901-001114	FILTER-EMI SMD;25VDC,2.0ADC,-,100nF,3.2x	5	Q505	0501-000344	TR-SMALL SIGNAL;KSC1623-G,NPN,200mW,SOT-	
.....5	EF518	2901-001114	FILTER-EMI SMD;25VDC,2.0ADC,-,100nF,3.2x	5	Q506	0501-000344	TR-SMALL SIGNAL;KSC1623-G,NPN,200mW,SOT-	
.....5	EF519	2901-001114	FILTER-EMI SMD;25VDC,2.0ADC,-,100nF,3.2x	5	Q507	0501-000344	TR-SMALL SIGNAL;KSC1623-G,NPN,200mW,SOT-	
.....5	EF520	2901-001114	FILTER-EMI SMD;25VDC,2.0ADC,-,100nF,3.2x	5	Q508	0501-000344	TR-SMALL SIGNAL;KSC1623-G,NPN,200mW,SOT-	
.....5	EF521	2901-000226	FILTER-EMI SMD;25V,0.3A,-,100pF,3.2x1.25	5	Q510	0501-000344	TR-SMALL SIGNAL;KSC1623-G,NPN,200mW,SOT-	
.....5	EF522	2901-000226	FILTER-EMI SMD;25V,0.3A,-,100pF,3.2x1.25	5	Q511	0501-000344	TR-SMALL SIGNAL;KSC1623-G,NPN,200mW,SOT-	
.....5	EF523	2901-000226	FILTER-EMI SMD;25V,0.3A,-,100pF,3.2x1.25	5	Q601	0501-000344	TR-SMALL SIGNAL;KSC1623-G,NPN,200mW,SOT-	
.....5	EF524	2901-000226	FILTER-EMI SMD;25V,0.3A,-,100pF,3.2x1.25	5	Q602	0501-000344	TR-SMALL SIGNAL;KSC1623-G,NPN,200mW,SOT-	
.....5	EF525	2901-000226	FILTER-EMI SMD;25V,0.3A,-,100pF,3.2x1.25	5	Q603	0501-000344	TR-SMALL SIGNAL;KSC1623-G,NPN,200mW,SOT-	
.....5	EF526	2901-000226	FILTER-EMI SMD;25V,0.3A,-,100pF,3.2x1.25	5	R101	2007-000757	R-CHIP;330KOHM,5%,1/10W,DA,TP,2012	
.....5	EF601	2901-001114	FILTER-EMI SMD;25VDC,2.0ADC,-,100nF,3.2x	5	R102	2007-000102	R-CHIP;100Kohm,5%,1/16W,DA,TP,1608	
.....5	EF604	2901-001114	FILTER-EMI SMD;25VDC,2.0ADC,-,100nF,3.2x	5	R103	2007-000075	R-CHIP;220ohm,5%,1/16W,DA,TP,1608	
.....5	EF605	2901-001114	FILTER-EMI SMD;25VDC,2.0ADC,-,100nF,3.2x	5	R104	2007-000075	R-CHIP;220ohm,5%,1/16W,DA,TP,1608	
.....5	EF606	2901-001114	FILTER-EMI SMD;25VDC,2.0ADC,-,100nF,3.2x	5	R105	2007-000882	R-CHIP;4.7ohm,5%,1/16W,DA,TP,1608	
.....5	EF607	2901-001114	FILTER-EMI SMD;25VDC,2.0ADC,-,100nF,3.2x	5	R106	2007-000082	R-CHIP;3.3Kohm,5%,1/16W,DA,TP,1608	
.....5	EF608	2901-001114	FILTER-EMI SMD;25VDC,2.0ADC,-,100nF,3.2x	5	R107	2007-000084	R-CHIP;4.7Kohm,5%,1/16W,DA,TP,1608	
.....5	EF704	2901-001114	FILTER-EMI SMD;25VDC,2.0ADC,-,100nF,3.2x	5	R108	2007-000539	R-CHIP;200ohm,5%,1/16W,DA,TP,1608	
.....5	EF705	2901-001114	FILTER-EMI SMD;25VDC,2.0ADC,-,100nF,3.2x	5	R109	2007-000090	R-CHIP;10KOHM,5%,1/16W,DA,TP,1608	
.....5	EF706	2901-001114	FILTER-EMI SMD;25VDC,2.0ADC,-,100nF,3.2x	5	R110	2007-000077	R-CHIP;470ohm,5%,1/16W,DA,TP,1608	
.....5	EF707	2901-001114	FILTER-EMI SMD;25VDC,2.0ADC,-,100nF,3.2x	5	R201	2007-000078	R-CHIP;1Kohm,5%,1/16W,DA,TP,1608	
.....5	EF801	2901-001114	FILTER-EMI SMD;25VDC,2.0ADC,-,100nF,3.2x	5	R202	2007-000094	R-CHIP;22Kohm,5%,1/16W,DA,TP,1608	
.....5	EF802	2901-001114	FILTER-EMI SMD;25VDC,2.0ADC,-,100nF,3.2x	5	R203	2007-000092	R-CHIP;15Kohm,5%,1/16W,DA,TP,1608	
.....5	EFF02	2901-001114	FILTER-EMI SMD;25VDC,2.0ADC,-,100nF,3.2x	5	R204	2007-000072	R-CHIP;47ohm,5%,1/16W,DA,TP,1608	
.....5	EFF03	2901-001114	FILTER-EMI SMD;25VDC,2.0ADC,-,100nF,3.2x	5	R214	2007-001167	R-CHIP;75ohm,5%,1/16W,DA,TP,1608	
.....5	EFF04	2901-000226	FILTER-EMI SMD;25V,0.3A,-,100pF,3.2x1.25	5	R215	2007-000113	R-CHIP;33ohm,5%,1/16W,DA,TP,1608	
.....5	EFF05	2901-001114	FILTER-EMI SMD;25VDC,2.0ADC,-,100nF,3.2x	5	R216	2007-000074	R-CHIP;100ohm,5%,1/16W,DA,TP,1608	
.....5	IC101	1002-001179	IC-A/D CONVERTER;AD9884,8BIT,QFP,128P,-	5	R217	2007-000074	R-CHIP;100ohm,5%,1/16W,DA,TP,1608	
.....5	IC102	1203-001419	IC-VOLTAGE REGULATOR;4931,TO-252,3P6.6x	5	R218	2007-000074	R-CHIP;100ohm,5%,1/16W,DA,TP,1608	
.....5	IC201	1204-001598	IC-VIDEO PROCESS;VPC3230D-B2,QFP,80P,-P	5	R219	2007-000074	R-CHIP;100ohm,5%,1/16W,DA,TP,1608	
.....5	IC202	1204-001623	IC-VERTICAL PROCESS;SDA9400,QFP,64P,-P	5	R220	2007-000074	R-CHIP;100ohm,5%,1/16W,DA,TP,1608	
.....5	IC301	1003-001249	IC-LCD CONTROLLER;PW364-S1675,TBGA,352P,	5	R221	2007-000074	R-CHIP;100ohm,5%,1/16W,DA,TP,1608	
.....5	IC302	1103-000180	IC-EEPROM;24C16,2Kx8BIT,SOP,8P,150MIL,10	5	R222	2007-000074	R-CHIP;100ohm,5%,1/16W,DA,TP,1608	
.....5	IC303	2804-001411	OSCILLATOR-CLOCK;26MHZ,50PPM,30PF,TP,3.3	5	R223	2007-000078	R-CHIP;1Kohm,5%,1/16W,DA,TP,1608	
.....5	IC304	2804-001485	OSCILLATOR-CLOCK;130MHZ,100PPM,30PF,BK,3	5	R224	2007-000074	R-CHIP;100ohm,5%,1/16W,DA,TP,1608	
.....5	IC401	AA13-00084A	IC-ASIC,-,M4LV-32/32-12VCA4,TQFP,48P,-	S.N.A5	R225	2007-000074	R-CHIP;100ohm,5%,1/16W,DA,TP,1608	
.....5	IC402	1204-001550	IC-VIDEO PROCESS;CXA2101AQ,QFP,80P,-PLA	5	R226	2007-000072	R-CHIP;47ohm,5%,1/16W,DA,TP,1608	
.....5	IC404	0801-000901	IC-CMOS LOGIC;74HC04,INVERTER,SOP,14P,15	5	R227	2007-000072	R-CHIP;47ohm,5%,1/16W,DA,TP,1608	
.....5	IC502	0801-002267	IC-CMOS LOGIC;74LCX14,-,SOIC,14P,150MIL	5	R228	2007-000072	R-CHIP;47ohm,5%,1/16W,DA,TP,1608	
.....5	IC503	1205-001740	IC-TRANSMITTER;DS90C385,TSSOP,56P,240MIL	5	R229	2007-001167	R-CHIP;75ohm,5%,1/16W,DA,TP,1608	
.....5	IC504	1203-001824	IC-VOL DETECTOR;7042,SOT-89,3P,-,PLASTI	5	R302	2007-000078	R-CHIP;1Kohm,5%,1/16W,DA,TP,1608	
.....5	IC505	1002-001048	IC-A/D&D/A CONVERTER;PCF8591T,8BIT,SOP,1	5	R303	2007-001157	R-CHIP;750ohm,5%,1/16W,DA,TP,1608	
.....5	IC506	1103-001164	IC-EEPROM;24LC21A,128x8BIT,SOP,8P,150MIL	5	R304	2007-001157	R-CHIP;750ohm,5%,1/16W,DA,TP,1608	
.....5	IC602	1106-001308	IC-SRAM;616V1000,64Kx16Bit,TSSOP,44P,463M	5	R305	2007-000309	R-CHIP;10ohm,5%,1/16W,DA,TP,1608	
.....5	IC603	1006-001076	IC-DRIVER/RECEIVER;232,SOP,16P,300MIL,DU	5	R306	2007-000309	R-CHIP;10ohm,5%,1/16W,DA,TP,1608	
.....5	IC605	0801-002394	IC-CMOS LOGIC;74LCX32,OR GATE,SOIC,14P,1	5	R307	2007-000309	R-CHIP;10ohm,5%,1/16W,DA,TP,1608	
.....5	IC608	1203-001359	IC-POSIFIXED REG.;1086,TO-263,3P,15.8MM	5	R308	2007-000078	R-CHIP;1Kohm,5%,1/16W,DA,TP,1608	
.....5	IC609	1203-002074	IC-POSIFIXED REG.;MIC39150,TO-263,3P,-	5	R309	2007-000078	R-CHIP;1Kohm,5%,1/16W,DA,TP,1608	
.....5	IC610	1203-001419	IC-VOLTAGE REGULATOR;4931,TO-252,3P6.6x	5	R310	2007-000070	R-CHIP;0ohm,5%,1/16W,DA,TP,1608	
.....5	IC611	1203-001359	IC-POSIFIXED REG.;1086,TO-263,3P,15.8MM	5	R311	2007-000070	R-CHIP;0ohm,5%,1/16W,DA,TP,1608	
.....5	IC703	1002-001045	IC-D/A CONVERTER;9280,8BIT,PLCC,68P,-	5	R312	2007-000084	R-CHIP;4.7Kohm,5%,1/16W,DA,TP,1608	
.....5	IC801	1002-001179	IC-A/D CONVERTER;AD9884,8BIT,QFP,128P,-	5	R313	2007-000074	R-CHIP;100ohm,5%,1/16W,DA,TP,1608	
.....5	ICP01	1204-001598	IC-VIDEO PROCESS;VPC3230D-B2,QFP,80P,-P	5	R314	2007-000084	R-CHIP;4.7Kohm,5%,1/16W,DA,TP,1608	
.....5	ICP02	1109-001144	IC-FIFO;81V04160,2x256Kx8Bit,TQFP,100P,1	5	R315	2007-000079	R-CHIP;1.8Kohm,5%,1/16W,DA,TP,1608	
.....5	L502	2703-000125	INDUCTOR-SMD;10uH,10%,1.25x2x1.25mm	5	R316	2007-000075	R-CHIP;220ohm,5%,1/16W,DA,TP,1608	
.....5	L503	2703-000125	INDUCTOR-SMD;10uH,10%,1.25x2x1.25mm	5	R317	2007-000075	R-CHIP;220ohm,5%,1/16W,DA,TP,1608	
.....5	L504	3301-000319	CORE-FERRITE BEAD;AB,26ohm,2x1.25x0.9mm,	5	R318	2007-000075	R-CHIP;220ohm,5%,1/16W,DA,TP,1608	
.....5	L505	3301-000319	CORE-FERRITE BEAD;AB,26ohm,2x1.25x0.9mm,	5	R319	2007-000075	R-CHIP;220ohm,5%,1/16W,DA,TP,1608	
.....5	L506	3301-000319	CORE-FERRITE BEAD;AB,26ohm,2x1.25x0.9mm,	5	R320	2007-000080	R-CHIP;2Kohm,5%,1/16W,DA,TP,1608	
.....5	L507	3301-000319	CORE-FERRITE BEAD;AB,26ohm,2x1.25x0.9mm,	5	R321	2007-000080	R-CHIP;2Kohm,5%,1/16W,DA,TP,1608	
.....5	L508	3301-000319	CORE-FERRITE BEAD;AB,26ohm,2x1.25x0.9mm,	5	R322	2007-000078	R-CHIP;1Kohm,5%,1/16W,DA,TP,1608	
.....5	L509	3301-000319	CORE-FERRITE BEAD;AB,26ohm,2x1.25x0.9mm,	5	R323	2007-000074	R-CHIP;100ohm,5%,1/16W,DA,TP,1608	
.....5	L510	3301-000319	CORE-FERRITE BEAD;AB,26ohm,2x1.25x0.9mm,	5	R324	2007-000080	R-CHIP;2Kohm,5%,1/16W,DA,TP,1608	
.....5	L511	3301-000319	CORE-FERRITE BEAD;AB,26ohm,2x1.25x0.9mm,	5	R325	2007-000078	R-CHIP;1Kohm,5%,1/16W,DA,TP,1608	
.....5	L512	3301-000319	CORE-FERRITE BEAD;AB,26ohm,2x1.25x0.9mm,	5	R326	2007-000074	R-CHIP;100ohm,5%,1/16W,DA,TP,1608	
.....5	L513	3301-000319	CORE-FERRITE BEAD;AB,26ohm,2x1.25x0.9mm,	5	R328	2007-000072	R-CHIP;47ohm,5%,1/16W,DA,TP,1608	
.....5	OTP01	1107-001087	IC-FLASH MEMORY;29LV160,1Mx16BIT,SOP,48P	5	R329	2007-000080	R-CHIP;2Kohm,5%,1/16W,DA,TP,1608	
.....5	Q101	0501-000344	TR-SMALL SIGNAL;KSC1623-G,NPN,200mW,SOT-	5	R331	2007-000074	R-CHIP;100ohm,5%,1/16W,DA,TP,1608	
.....5	Q102	0501-000344	TR-SMALL SIGNAL;KSC1623-G,NPN,200mW,SOT-	5	R332	2007-000084	R-CHIP;4.7Kohm,5%,1/16W,DA,TP,1608	
.....5	Q201	0501-000344	TR-SMALL SIGNAL;KSC1623-G,NPN,200mW,SOT-	5	R333	2007-001167	R-CHIP;75ohm,5%,1/16W,DA,TP,1608	
.....5	Q401	0501-000344	TR-SMALL SIGNAL;KSC1623-G,NPN,200mW,SOT-	5	R334	2007-001167	R-CHIP;75ohm,5%,1/16W,DA,TP,1608	
.....5	Q402	0501-000344	TR-SMALL SIGNAL;KSC1623-G,NPN,200mW,SOT-	5	R335	2007-000120	R-CHIP;680ohm,5%,1/16W,DA,TP,1608	
.....5	Q403	0501-000344	TR-SMALL SIGNAL;KSC1623-G,NPN,200mW,SOT-	5	R336	2007-000084	R-CHIP;4.7Kohm,5%,1/16W,DA,TP,1608	
.....5	Q404	0501-000280	TR-SMALL SIGNAL;KSA1182,PNP,150mW,SOT-23	5	R402	2007-000084	R-CHIP;4.7Kohm,5%,1/16W,DA,TP,1608	
.....5	Q501	0501-000344	TR-SMALL SIGNAL;KSC1623-G,NPN,200mW,SOT-	5	R403	2007-000070	R-CHIP;0ohm,5%,1/16W,DA,TP,1608	

Level	Loc. No.	Code No.	Description ; Specification	Remark	Level	Loc. No.	Code No.	Description ; Specification	Remark
.....5	R625	2007-000074	R-CHIP;100ohm,5%,1/16W,DA,TP;1608	5	RW805	2011-000002	R-NETWORK;22ohm,5%,63mW/L,CHIP;8P,TP	
.....5	R626	2007-000074	R-CHIP;100ohm,5%,1/16W,DA,TP;1608	5	RW806	2011-000002	R-NETWORK;22ohm,5%,63mW/L,CHIP;8P,TP	
.....5	R627	2007-000355	R-CHIP;12KOHM,5%,1/10W,DA,TP;2012	5	RWP01	2011-000002	R-NETWORK;22ohm,5%,63mW/L,CHIP;8P,TP	
.....5	R629	2007-000079	R-CHIP;1.8Kohm,5%,1/16W,DA,TP;1608	5	RWP02	2011-000002	R-NETWORK;22ohm,5%,63mW/L,CHIP;8P,TP	
.....5	R630	2007-000084	R-CHIP;4.7Kohm,5%,1/16W,DA,TP;1608	5	RWP03	2011-000002	R-NETWORK;22ohm,5%,63mW/L,CHIP;8P,TP	
.....5	R631	2007-000234	R-CHIP;1.3Kohm,5%,1/16W,DA,TP;1608	5	RWP04	2011-000002	R-NETWORK;22ohm,5%,63mW/L,CHIP;8P,TP	
.....5	R632	2007-000077	R-CHIP;470ohm,5%,1/16W,DA,TP;1608	5	X201	2801-004004	CRYSTAL-SMD;20.25MHz,20ppm,28-AAN,13pF,2	
.....5	R713	2007-000643	R-CHIP;270ohm,5%,1/16W,DA,TP;1608	5	XP101	2801-004004	CRYSTAL-SMD;20.25MHz,20ppm,28-AAN,13pF,2	
.....5	R714	2007-000643	R-CHIP;270ohm,5%,1/16W,DA,TP;1608		...3		0202-000187	SOLDER-WIRE FLUX;-;RS60S,D1.2,63Sn/37Pb	S.N.A
.....5	R715	2007-000643	R-CHIP;270ohm,5%,1/16W,DA,TP;1608		...3		0202-001167	SOLDER-CREAM;RX3603-2330HO,S45A,PASTE,SN	S.N.A
.....5	R717	2007-000084	R-CHIP;4.7Kohm,5%,1/16W,DA,TP;1608		...2		AA95-01844M	ASSUB-PCB,SOUND;PS42P2S,D53A,AA95-013	S.N.A
.....5	R720	2007-000402	R-CHIP;150ohm,5%,1/16W,DA,TP;1608		...3	AMPMAI	AA39-00114F	CBF HARNESS;-;12P;35155-1200,S,100MM,1007	
.....5	R721	2007-000074	R-CHIP;100ohm,5%,1/16W,DA,TP;1608		...3	CN601	3711-003974	CONNECTOR-HEADER;BOX,12P;1R,2.5mm,STRAIG	
.....5	R722	2007-000074	R-CHIP;100ohm,5%,1/16W,DA,TP;1608		...3	CN602	3711-003046	CONNECTOR-HEADER;BOX,9P;1R,2.5mm,STRAIGH	
.....5	R723	2007-000074	R-CHIP;100ohm,5%,1/16W,DA,TP;1608		...3	CN603	3711-003043	CONNECTOR-HEADER;BOX,4P;1R,2.5mm,STRAIGH	
.....5	R724	2007-000074	R-CHIP;100ohm,5%,1/16W,DA,TP;1608		...3	IC601	1204-001222	IC-AUDIO PROCESSOR;TDA7429S,DIP;42P;-;PL	
.....5	R725	2007-000074	R-CHIP;100ohm,5%,1/16W,DA,TP;1608		...3	JK601	3722-001733	JACK-PIN;4P(6P)-;Ni,WHT/RED/WHT/RED;-	
.....5	R726	2007-000074	R-CHIP;100ohm,5%,1/16W,DA,TP;1608		...3	JK603	3722-000143	JACK-PHONE;1P(VER);3.4PI,AG,BLK,NO	
.....5	R728	2007-000402	R-CHIP;150ohm,5%,1/16W,DA,TP;1608		...3	L682	AA27-00119ACOIL	CHOKE;10uH,-;10uH,10%,0.07,0.1ohm M	
.....5	R729	2007-000402	R-CHIP;150ohm,5%,1/16W,DA,TP;1608		...3	L683	AA27-00119ACOIL	CHOKE;10uH,-;10uH,10%,0.07,0.1ohm M	
.....5	R730	2007-000402	R-CHIP;150ohm,5%,1/16W,DA,TP;1608		...3	L684	AA27-00119ACOIL	CHOKE;10uH,-;10uH,10%,0.07,0.1ohm M	
.....5	R731	2007-000402	R-CHIP;150ohm,5%,1/16W,DA,TP;1608		...3	L685	AA27-00119ACOIL	CHOKE;10uH,-;10uH,10%,0.07,0.1ohm M	
.....5	R734	2007-000402	R-CHIP;150ohm,5%,1/16W,DA,TP;1608		...3	PCB	AA41-00585APCB-SOUND;-;PS-42P2S,FR-4,2LA,1.6T,245X24	S.N.A	
.....5	R737	2007-000402	R-CHIP;150ohm,5%,1/16W,DA,TP;1608		...3	PWRAMP	AA39-00301ALEAD	CONNECTOR ASSY;PS-42P2S,UL1007#26,U	
.....5	R738	2007-000381	R-CHIP;13Kohm,5%,1/16W,DA,TP;1608		...3		AA97-05551A	AASSY AUTO-SUB;PS42P2S,D53A	S.N.A
.....5	R739	2007-000087	R-CHIP;6.8Kohm,5%,1/16W,DA,TP;1608		...4	C601	2401-000426	C-AL;10uF,20%,16V,GP;TP3.5x5.5	
.....5	R740	2007-000090	R-CHIP;10KOHM,5%,1/16W,DA,TP;1608		...4	C602	2301-000224	C-FILM,PEF;22nF,5%,50V,TP;7.4x3.9x13mm,5	
.....5	R748	2007-000070	R-CHIP;0ohm,5%,1/16W,DA,TP;1608		...4	C603	2301-000224	C-FILM,PEF;22nF,5%,50V,TP;7.4x3.9x13mm,5	
.....5	R801	2007-000074	R-CHIP;100ohm,5%,1/16W,DA,TP;1608		...4	C604	2301-000445	C-FILM,PEF;4.7nF,5%,50V,TP;5.5x7x3mm,5mm	
.....5	R802	2007-000084	R-CHIP;4.7Kohm,5%,1/16W,DA,TP;1608		...4	C605	2305-000665	C-FILM,MPEF;100nF,5%,63V,TP;7.5x4.0x5.0m	
.....5	R803	2007-000084	R-CHIP;4.7Kohm,5%,1/16W,DA,TP;1608		...4	C606	2301-000104	C-FILM,PEF;1.2nF,5%,50V,TP;6.5x3.0x5.5MM	
.....5	R804	2007-000084	R-CHIP;4.7Kohm,5%,1/16W,DA,TP;1608		...4	C607	2301-000289	C-FILM,PEF;5.6nF,5%,50V,TP;7x6x3,5	
.....5	R805	2007-000882	R-CHIP;4.7ohm,5%,1/16W,DA,TP;1608		...4	C608	2305-001023	C-FILM,MPEF;680nF,10%,63V,TP;7.5x5.5x14.1	
.....5	R806	2007-000082	R-CHIP;3.3Kohm,5%,1/16W,DA,TP;1608		...4	C609	2401-000647	C-AL;2.2uF,20%,50V,BP;TP5x11,5	
.....5	R807	2007-000084	R-CHIP;4.7Kohm,5%,1/16W,DA,TP;1608		...4	C610	2401-000647	C-AL;2.2uF,20%,50V,BP;TP5x11,5	
.....5	R808	2007-000539	R-CHIP;200ohm,5%,1/16W,DA,TP;1608		...4	C611	2401-000647	C-AL;2.2uF,20%,50V,BP;TP5x11,5	
.....5	R809	2007-000090	R-CHIP;10KOHM,5%,1/16W,DA,TP;1608		...4	C612	2305-000665	C-FILM,MPEF;100nF,5%,63V,TP;7.5x4.0x5.0m	
.....5	R810	2007-000077	R-CHIP;470ohm,5%,1/16W,DA,TP;1608		...4	C613	2305-000665	C-FILM,MPEF;100nF,5%,63V,TP;7.5x4.0x5.0m	
.....5	R811	2007-000075	R-CHIP;220ohm,5%,1/16W,DA,TP;1608		...4	C615	2305-000665	C-FILM,MPEF;100nF,5%,63V,TP;7.5x4.0x5.0m	
.....5	R812	2007-000075	R-CHIP;220ohm,5%,1/16W,DA,TP;1608		...4	C616	2305-000665	C-FILM,MPEF;100nF,5%,63V,TP;7.5x4.0x5.0m	
.....5	R813	2007-000070	R-CHIP;0ohm,5%,1/16W,DA,TP;1608		...4	C617	2301-000224	C-FILM,PEF;22nF,5%,50V,TP;7.4x3.9x13mm,5	
.....5	RP107	2007-000074	R-CHIP;100ohm,5%,1/16W,DA,TP;1608		...4	C618	2301-000395	C-FILM,PEF;18nF,5%,50V,TP;6.5X12.5X3.5MM	
.....5	RP108	2007-000074	R-CHIP;100ohm,5%,1/16W,DA,TP;1608		...4	C619	2301-000224	C-FILM,PEF;22nF,5%,50V,TP;7.4x3.9x13mm,5	
.....5	RP109	2007-000074	R-CHIP;100ohm,5%,1/16W,DA,TP;1608		...4	C620	2301-000395	C-FILM,PEF;18nF,5%,50V,TP;6.5X12.5X3.5MM	
.....5	RP111	2007-000072	R-CHIP;47ohm,5%,1/16W,DA,TP;1608		...4	C621	2301-000289	C-FILM,PEF;5.6nF,5%,50V,TP;7x6x3,5	
.....5	RP112	2007-000072	R-CHIP;47ohm,5%,1/16W,DA,TP;1608		...4	C622	2301-000289	C-FILM,PEF;5.6nF,5%,50V,TP;7x6x3,5	
.....5	RP113	2007-000072	R-CHIP;47ohm,5%,1/16W,DA,TP;1608		...4	C632	2401-000667	C-AL;2.2uF,20%,50V,WT;TP5x11,5	
.....5	RW101	2011-000002	R-NETWORK;22ohm,5%,63mW/L,CHIP;8P,TP		...4	C633	2401-000667	C-AL;2.2uF,20%,50V,WT;TP5x11,5	
.....5	RW102	2011-000002	R-NETWORK;22ohm,5%,63mW/L,CHIP;8P,TP		...4	C634	2401-000667	C-AL;2.2uF,20%,50V,WT;TP5x11,5	
.....5	RW103	2011-000002	R-NETWORK;22ohm,5%,63mW/L,CHIP;8P,TP		...4	C635	2401-000667	C-AL;2.2uF,20%,50V,WT;TP5x11,5	
.....5	RW104	2011-000002	R-NETWORK;22ohm,5%,63mW/L,CHIP;8P,TP		...4	C636	2401-000667	C-AL;2.2uF,20%,50V,WT;TP5x11,5	
.....5	RW105	2011-000002	R-NETWORK;22ohm,5%,63mW/L,CHIP;8P,TP		...4	C637	2401-000667	C-AL;2.2uF,20%,50V,WT;TP5x11,5	
.....5	RW106	2011-000002	R-NETWORK;22ohm,5%,63mW/L,CHIP;8P,TP		...4	C662	2401-000689	C-AL;2200uF,20%,16V,GP,TP;13x25,5	
.....5	RW107	2011-000002	R-NETWORK;22ohm,5%,63mW/L,CHIP;8P,TP		...4	C664	2401-002463	C-AL;470uF,20%,16V,GP;TP8x11.5,5	
.....5	RW108	2011-000002	R-NETWORK;22ohm,5%,63mW/L,CHIP;8P,TP		...4	C667	2401-000603	C-AL;1uF,20%,50V,GP,TP;5x11,5	
.....5	RW109	2011-000002	R-NETWORK;22ohm,5%,63mW/L,CHIP;8P,TP		...4	C668	2401-000667	C-AL;2.2uF,20%,50V,WT;TP5x11,5	
.....5	RW110	2011-000002	R-NETWORK;22ohm,5%,63mW/L,CHIP;8P,TP		...4	C669	2401-000667	C-AL;2.2uF,20%,50V,WT;TP5x11,5	
.....5	RW111	2011-000002	R-NETWORK;22ohm,5%,63mW/L,CHIP;8P,TP		...4	C681	2401-000603	C-AL;1uF,20%,50V,GP,TP;5x11,5	
.....5	RW112	2011-000002	R-NETWORK;22ohm,5%,63mW/L,CHIP;8P,TP		...4	C689	2401-002009	C-AL;100uF,20%,16V,GP,TP;6.3x7,5	
.....5	RW201	2011-000002	R-NETWORK;22ohm,5%,63mW/L,CHIP;8P,TP		...4	C691	2401-002009	C-AL;100uF,20%,16V,GP,TP;6.3x7,5	
.....5	RW202	2011-000002	R-NETWORK;22ohm,5%,63mW/L,CHIP;8P,TP		...4	L602	2702-001094	INDUCTOR-RADIAL;10uH,10%,6x4mm	
.....5	RW203	2011-000002	R-NETWORK;22ohm,5%,63mW/L,CHIP;8P,TP		...4	L681	2702-001094	INDUCTOR-RADIAL;10uH,10%,6x4mm	
.....5	RW204	2011-000002	R-NETWORK;22ohm,5%,63mW/L,CHIP;8P,TP		...4	R600	2003-000664	R-METAL OXIDE(S);33ohm,5%,2W,AF,TP;4x12mm	
.....5	RW501	2011-000002	R-NETWORK;22ohm,5%,63mW/L,CHIP;8P,TP		...4		AA97-06270A	AASSY SMD-SUB;PS42P2S,D53A	S.N.A
.....5	RW502	2011-000002	R-NETWORK;22ohm,5%,63mW/L,CHIP;8P,TP	5	C629	2203-000181	C-CERAMIC,CHIP;100nF,+80-20%,25V,Y5V,TP,	
.....5	RW503	2011-000002	R-NETWORK;22ohm,5%,63mW/L,CHIP;8P,TP	5	C661	2203-000181	C-CERAMIC,CHIP;100nF,+80-20%,25V,Y5V,TP,	
.....5	RW504	2011-000002	R-NETWORK;22ohm,5%,63mW/L,CHIP;8P,TP	5	C663	2203-000181	C-CERAMIC,CHIP;100nF,+80-20%,25V,Y5V,TP,	
.....5	RW505	2011-000002	R-NETWORK;22ohm,5%,63mW/L,CHIP;8P,TP	5	C665	2203-000181	C-CERAMIC,CHIP;100nF,+80-20%,25V,Y5V,TP,	
.....5	RW506	2011-000002	R-NETWORK;22ohm,5%,63mW/L,CHIP;8P,TP	5	C666	2203-000181	C-CERAMIC,CHIP;100nF,+80-20%,25V,Y5V,TP,	
.....5	RW705	2011-000002	R-NETWORK;22ohm,5%,63mW/L,CHIP;8P,TP	5	C670	2203-000181	C-CERAMIC,CHIP;100nF,+80-20%,25V,Y5V,TP,	
.....5	RW706	2011-000002	R-NETWORK;22ohm,5%,63mW/L,CHIP;8P,TP	5	C682	2203-000181	C-CERAMIC,CHIP;100nF,+80-20%,25V,Y5V,TP,	
.....5	RW707	2011-000002	R-NETWORK;22ohm,5%,63mW/L,CHIP;8P,TP	5	C683	2203-005809	C-CERAMIC,CHIP;1000nF,10%,16V,X7R,TP;201	
.....5	RW708	2011-000002	R-NETWORK;22ohm,5%,63mW/L,CHIP;8P,TP	5	C685	2203-000181	C-CERAMIC,CHIP;100nF,+80-20%,25V,Y5V,TP,	
.....5	RW801	2011-000002	R-NETWORK;22ohm,5%,63mW/L,CHIP;8P,TP	5	C686	2203-000239	C-CERAMIC,CHIP;0.1nF,5%,50V,NP0,TP;2012	
.....5	RW802	2011-000002	R-NETWORK;22ohm,5%,63mW/L,CHIP;8P,TP	5	C687	2203-005809	C-CERAMIC,CHIP;1000nF,10%,16V,X7R,TP;201	
.....5	RW803	2011-000002	R-NETWORK;22ohm,5%,63mW/L,CHIP;8P,TP	5	C688	2203-000181	C-CERAMIC,CHIP;100nF,+80-20%,25V,Y5V,TP,	
.....5	RW804	2011-000002	R-NETWORK;22ohm,5%,63mW/L,CHIP;8P,TP	5	C690	2203-000181	C-CERAMIC,CHIP;100nF,+80-20%,25V,Y5V,TP,	

Level	Loc. No	Code No.	Description ; Specification	Remark
.....5	C692	2203-005809	C-CERAMIC,CHIP;1000nF,10%,16V,X7R,TP,201	
.....5	C694	2203-000181	C-CERAMIC,CHIP;100nF,+80-20%,25V,Y5V,TP,	
.....5	C695	2203-000239	C-CERAMIC,CHIP;0.1nF,5%,50V,NPO,TP,2012	
.....5	C696	2203-005809	C-CERAMIC,CHIP;1000nF,10%,16V,X7R,TP,201	
.....5	C698	2203-000239	C-CERAMIC,CHIP;0.1nF,5%,50V,NPO,TP,2012	
.....5	C699	2203-000239	C-CERAMIC,CHIP;0.1nF,5%,50V,NPO,TP,2012	
.....5	DZ681	0403-001117	DIODE-ZENER;RLZ12B,5%,500mW,LL-34,TP	
.....5	DZ682	0403-001117	DIODE-ZENER;RLZ12B,5%,500mW,LL-34,TP	
.....5	DZ683	0403-001117	DIODE-ZENER;RLZ12B,5%,500mW,LL-34,TP	
.....5	DZ684	0403-001117	DIODE-ZENER;RLZ12B,5%,500mW,LL-34,TP	
.....5	IC602	1201-001681	IC-AUDIO AMP;1101,SOP,30P,433MIL,-,PLA	
.....5	R601	2007-000981	R-CHIP;5.6KOHM,5%,1/10W,DA,TP,2012	
.....5	R602	2007-000981	R-CHIP;5.6KOHM,5%,1/10W,DA,TP,2012	
.....5	R603	2007-000518	R-CHIP;2.7KOHM,5%,1/10W,DA,TP,2012	
.....5	R604	2007-000518	R-CHIP;2.7KOHM,5%,1/10W,DA,TP,2012	
.....5	R605	2007-000572	R-CHIP;220OHM,5%,1/10W,DA,TP,2012	
.....5	R606	2007-000572	R-CHIP;220OHM,5%,1/10W,DA,TP,2012	
.....5	R611	2007-000282	R-CHIP;100KOHM,5%,1/10W,DA,TP,2012	
.....5	R612	2007-000282	R-CHIP;100KOHM,5%,1/10W,DA,TP,2012	
.....5	R613	2007-000282	R-CHIP;100KOHM,5%,1/10W,DA,TP,2012	
.....5	R614	2007-000468	R-CHIP;1KOHM,5%,1/10W,DA,TP,2012	
.....5	R615	2007-000468	R-CHIP;1KOHM,5%,1/10W,DA,TP,2012	
.....5	R616	2007-000468	R-CHIP;1KOHM,5%,1/10W,DA,TP,2012	
.....5	R617	2007-000282	R-CHIP;100KOHM,5%,1/10W,DA,TP,2012	
.....5	R618	2007-000282	R-CHIP;100KOHM,5%,1/10W,DA,TP,2012	
.....5	R619	2007-000282	R-CHIP;100KOHM,5%,1/10W,DA,TP,2012	
.....5	R620	2007-000468	R-CHIP;1KOHM,5%,1/10W,DA,TP,2012	
.....5	R621	2007-000468	R-CHIP;1KOHM,5%,1/10W,DA,TP,2012	
.....5	R622	2007-000468	R-CHIP;1KOHM,5%,1/10W,DA,TP,2012	
.....5	R661	2007-001177	R-CHIP;8.2KOHM,5%,1/10W,DA,TP,2012	
.....5	R662	2007-000546	R-CHIP;20KOHM,5%,1/10W,DA,TP,2012	
.....5	R663	2007-000738	R-CHIP;30KOHM,5%,1/10W,DA,TP,2012	
.....5	R664	2007-000546	R-CHIP;20KOHM,5%,1/10W,DA,TP,2012	
.....5	R665	2007-000738	R-CHIP;30KOHM,5%,1/10W,DA,TP,2012	
.....5	R666	2007-000210	R-CHIP;1.1KOHM,5%,1/10W,DA,TP,2012	
.....5	R682	2007-000308	R-CHIP;100HM,5%,1/10W,DA,TP,2012	
.....5	R683	2007-000308	R-CHIP;100HM,5%,1/10W,DA,TP,2012	
.....5	R690	2007-001177	R-CHIP;8.2KOHM,5%,1/10W,DA,TP,2012	
.....5	R691	2007-001177	R-CHIP;8.2KOHM,5%,1/10W,DA,TP,2012	
...3		0202-000187	SOLDER-WIRE FLUX;-RS60S,D1.2,63Sn/37Pb	S.N.A
...3		0202-001167	SOLDER-CREAM;RX3603-2330HO,S45A,PASTE,SN	S.N.A
...2		AA98-00188A	AASSY-PBA,SMPS,-,SPD-42P2S,D51A,42SD,90-26	S.N.A
...2		AA98-00231A	AASSY-PANEL,PDP,-,PS42P2S,D53A,S1.0,SD,42,	S.N.A
...3		AA98-00241A	AASSY-PBA,L-MAIN;-42SD,D53A,LJ41-00778A,S	
...3		AA98-00221A	AASSY-PBA,L-BUFF(F);42SD,D51A,LJ41-00780	
...3		AA98-00218A	AASSY-PBA,L-BUFF(F);42SD,D51A,LJ41-00779	
...3		AA98-00215A	AASSY-PBA,BUFF(DOWN);42SD,D51A,LJ41-0078	
...3		AA98-00213A	AASSY-PBA,BUFF(UP);42SD,D51A,LJ41-00783A	
...3		AA98-00209A	AASSY-PBA,Y-MAIN;-42SD,D51A,LJ41-00781A,S	
...3		AA98-00206A	AASSY-PBA,X-MAIN;-42SD,D51A,LJ41-00782A,S	
...3		AA98-00200A	AASSY-PANEL,PDP,SVC,-,SPD-42P2S,D51A,300X3	S.N.A
...2		AA95-01751D	AASSY SUB-PCB CONTROL;PS42P2S,D53A,AA95-0	S.N.A
...3	CN11	AA39-00273B	LEAD CONNECTOR ASSY;PS-42P2SM,UL1007#26,	
...3	PCB	AA41-00370A	PCB-CONTROL;SPD-50P2HM,FR-1,1L,A,1.6T,-,	S.N.A
...3	SW11	3404-000178	SWITCH-TACT;12V,50mA,120gf,6x6mm,SPST	
...3	SW12	3404-000178	SWITCH-TACT;12V,50mA,120gf,6x6mm,SPST	
...3	SW13	3404-000178	SWITCH-TACT;12V,50mA,120gf,6x6mm,SPST	
...3	SW14	3404-000178	SWITCH-TACT;12V,50mA,120gf,6x6mm,SPST	
...3	SW15	3404-000178	SWITCH-TACT;12V,50mA,120gf,6x6mm,SPST	
...3	SW16	3404-000178	SWITCH-TACT;12V,50mA,120gf,6x6mm,SPST	
...3	SW17	3404-000178	SWITCH-TACT;12V,50mA,120gf,6x6mm,SPST	
...3		AA97-05597A	AASSY AUTO-SUB;PS42P2S,D53A	S.N.A
...4	R11	2001-000281	R-CARBON;100OHM,5%,1/8W,AA,TP,1.8X3.2MM	
...4	R12	2001-000281	R-CARBON;100OHM,5%,1/8W,AA,TP,1.8X3.2MM	
...4	R13	2001-000281	R-CARBON;100OHM,5%,1/8W,AA,TP,1.8X3.2MM	
...4	R14	2001-000281	R-CARBON;100OHM,5%,1/8W,AA,TP,1.8X3.2MM	
...3		0202-000187	SOLDER-WIRE FLUX;-RS60S,D1.2,63Sn/37Pb	S.N.A
...2		AA39-00199A	POWER CORD;SPD-42P1S,LP-34A,NF USE 1181	
...2		AA39-00267B	LEAD CONNECTOR ASSY;PS-42P2SM,UL1007#26,	
...2		AA39-00274B	LEAD CONNECTOR ASSY;PS-42P2SM,UL2835#28,	
...2		AA63-00491B	COVER-TERMINAL,TV;42P2,SUS,T0.3	
...2		AA67-00112A	MIRROR-GLASS;42INCH,P1S,MESH,55% 0.150HM	

ASSY COVER REAR

Level	Loc. No	Code No.	Description ; Specification	Remark
1	*	AA90-02061A	AASSY COVER REAR;PS42P2SDX/XEC	S.N.A
...2		AA91-01611B	AASSY-CABINET,BACK;KUJU,HIPS V2 BLK WP100	
...3	COB+CB	6003-001019	SCREW-TAPTITE;RH,+B,M4,L12,ZPC(BLK),SWR	S.N.A
...3	COB+CB	6003-001020	SCREW-TAPTITE;RH,+B,M4,L10,ZPC(YEL),SWR	S.N.A
...3	COB+HS	6003-001026	SCREW-TAPTITE;RH,+B,M4,L15,ZPC(BLK),SWR	S.N.A
...3		AA64-01802A	CABINET BACK;42P2,HIPS V2,BLK WP1000	S.N.A
...3		AA64-01551B	HANDLE-SET;PDP,ABS,HB,BLK	
...3		AA63-00232A	COVER-BACK,ASSY;PS-42P2S,AL5052,T1.2	
...4		AA63-00432B	COVER-BACK;42P2,AL,T1.2,EUP	S.N.A
...4		AA63-00433A	COVER-BACK,BOT;42P2,AL,T1.2	S.N.A

ASSY COVER FRONT

Level	Loc. No	Code No.	Description ; Specification	Remark
1	*	AA90-01898A	AASSY COVER FRONT;PS42P2SDX/XEC	S.N.A
...2	BFB+CF	6003-001020	SCREW-TAPTITE;RH,+B,M4,L10,ZPC(YEL),SWR	S.N.A
...2	BFS+CF	6003-001020	SCREW-TAPTITE;RH,+B,M4,L10,ZPC(YEL),SWR	S.N.A
...2	BFT+CF	6003-001020	SCREW-TAPTITE;RH,+B,M4,L10,ZPC(YEL),SWR	S.N.A
...2	BLFCHB	6006-001035	SCREW-ASS'Y MACH;WSP,PH,+M3,L8,ZPC(YEL)	S.N.A
...2	BM+CHB	6006-001035	SCREW-ASS'Y MACH;WSP,PH,+M3,L8,ZPC(YEL)	S.N.A
...2	BP+CF	6003-001026	SCREW-TAPTITE;RH,+B,M4,L15,ZPC(BLK),SWR	S.N.A
...2	CB+CF	AA60-10050T	SCREW-TAPPING;-SWRCH18A,M4,L20,RH,+2S,	S.N.A
...2	CHB+CF	6003-001026	SCREW-TAPTITE;RH,+B,M4,L15,ZPC(BLK),SWR	S.N.A
...2	COB+CB	6006-001112	SCREW-ASS'Y MACH;WP,PH,+M8,L16,ZPC(BLK)	
...2	COB+CT	6006-001035	SCREW-ASS'Y MACH;WSP,PH,+M3,L8,ZPC(YEL)	S.N.A
...2	COB+LF	6006-001035	SCREW-ASS'Y MACH;WSP,PH,+M3,L8,ZPC(YEL)	S.N.A
...2	COT+SJ	6003-000333	SCREW-TAPTITE;RH,+2S,M3,L10,ZPC(YEL),SW	S.N.A
...2	COT+SP	6003-000333	SCREW-TAPTITE;RH,+2S,M3,L10,ZPC(YEL),SW	S.N.A
...2	GS+CHB	6006-001039	SCREW-ASS'Y MACH;WSP,PH,+M4,L12,ZPC(YEL)	
...2	PCB+CF	6003-000333	SCREW-TAPTITE;RH,+2S,M3,L10,ZPC(YEL),SW	S.N.A
...2	SB+CHB	6006-001035	SCREW-ASS'Y MACH;WSP,PH,+M3,L8,ZPC(YEL)	S.N.A
...2	SMPSCH	6006-001035	SCREW-ASS'Y MACH;WSP,PH,+M3,L8,ZPC(YEL)	S.N.A
...2	SNDCHB	6006-001035	SCREW-ASS'Y MACH;WSP,PH,+M3,L8,ZPC(YEL)	S.N.A
...2	SPKCHB	6006-001035	SCREW-ASS'Y MACH;WSP,PH,+M3,L8,ZPC(YEL)	S.N.A
...2		AA61-50112A	GUIDE-STAND,L ASSY;42P2S,AL DIECASTING	
...3		AA72-00021A	SPONGE-EMI,B;PDP,SHIELD-FORM,T10,D30,L15	
...3		AA72-00007A	SPONGE-EMI;PDP,SHIELD FROM,D10,T2,L50	S.N.A
...3		AA61-01055A	ABRACKET-COVER,LEFT;PDP,AL 5051,T1.5	
...3		AA61-00584B	GUIDE-STAND;SPD-50P2H,AL,DIECASTING	
...3		6006-001035	SCREW-ASS'Y MACH;WSP,PH,+M3,L8,ZPC(YEL)	S.N.A
...2		AA61-30063A	SPONGE-EMI,BOT;42P2S,SHIELD-FORM,T30,D60	
...2		AA61-50117A	GUIDE-STAND,R ASSY;42P2S,AL DIECASTING	
...3		AA72-00021A	SPONGE-EMI,B;PDP,SHIELD-FORM,T10,D30,L15	
...3		AA72-00007A	SPONGE-EMI;PDP,SHIELD FROM,D10,T2,L50	S.N.A
...3		AA61-01054A	ABRACKET-COVER,RIGHT;PDP,AL 5051,T1.5	
...3		AA61-00584B	GUIDE-STAND;SPD-50P2H,AL,DIECASTING	
...3		6006-001035	SCREW-ASS'Y MACH;WSP,PH,+M3,L8,ZPC(YEL)	S.N.A
...2		AA63-00437B	COVER-SET;42P2,ABS HB,BLK,WP1000	
...2		AA64-01565B	KNOB-CONTROL;PDP,ABS HB,BLK,SILVER	
...2		AA72-00020A	SPONGE-EMI,A;PDP,SHIELD-FORM,T16,D20,L10	
...2		AA72-00022A	SPONGE-EMI,C;PDP,SHIELD-FORM,T20,D12,L15	
...2		AA91-00859B	ASSY CABINET FRONT;42P2,SV012P+WP1000 E	
...3		AA64-01799C	CABINET-FRONT;42P2,HIPS HB,G4309,SV012P+	
...3		AA64-01566F	KNOB-MASTER;PDP,ABS,HB,BLK,SV012P M/SA	
...3		AA64-01560A	ABADGE-BRAND;PDP,AL FORGING,L68,SILVER,SA	
...3		AA64-01549B	WINDOW-RMC;PDP,ACRYL VIOLET,20.1	
...3		AA61-60003J	SPRING-CS;-SUS304,-,OD6,N7,OD6,-,-,-,	S.N.A
...2		AA60-00110C	SPACER-FILTER;42P2,P/U V0,L,BLK	
...2		AA60-00110D	SPACER-FILTER;42P2,P/U V0,L,BLK	
...2		AA61-00829A	ABRACKET-PLATE;SPD-42P1S,PBS,T0.2,PRESS	
...2		AA61-01059A	ABRACKET-FILTER TOP,ASSY;AL 42P2,T1.2	
...3		AA72-00017A	SPONGE-EMI,FILTER;42P2,SHIELD-FORM,T1.2,	
...3		AA63-00406B	GROMMET-PANEL;PDP,PBT,T0.2	
...3		AA61-01064A	ABRACKET-EMI,FILTER;PDP,SPTE,T0.3,L62.6,	
...3		AA61-01053A	ABRACKET-FILTER,TO;42P2,AL 5051,T1.5	
...3		AA61-01044A	ABRACKET-FINGER;PDP,BE-CO,T0.15,NTR	
...2		AA61-01060A	ABRACKET-FILTER SIDE R,ASSY;AL 6063 EXT,4	
...3		AA72-00018A	SPONGE-EMI,FILTER;42P2,SHIELD-FORM,T1.2,	
...3		AA63-00406B	GROMMET-PANEL;PDP,PBT,T0.2	
...3		AA61-01064A	ABRACKET-EMI,FILTER;PDP,SPTE,T0.3,L62.6,	
...3		AA61-01052A	ABRACKET-FILTER,SIDE R;42P2,AL 5051,T1.5	

Level	Loc. No.	Code No.	Description ; Specification	Remark	Level	Loc. No.	Code No.	Description ; Specification	Remark
...3		AA61-01044	ABRACKET-FINGER;PDP,BE-CO,T0.15,NTR						
..2		AA61-01061	ABRACKET-FILTER SIDE L,ASSY;AL 6063 EXT,4						
...3		AA72-00018	ASPONGE-EMI,FILTER;42P2,SHIELD-FORM,T1.2,						
...3		AA63-00406B	GROMMET-PANEL;PDP,PBT,T0.2						
...3		AA61-01064	ABRACKET-EMI,FILTER;PDP,SPTE,T0.3,L62.6,						
...3		AA61-01051	ABRACKET-FILTER,SIDE L;42P2,AL 5051,T1.5						
...3		AA61-01044	ABRACKET-FINGER;PDP,BE-CO,T0.15,NTR						
..2		AA61-01062	ABRACKET-FILTER BOT,ASSY;AL 6063 EXT,42P2						
...3		AA72-00017	ASPONGE-EMI,FILTER;42P2,SHIELD-FORM,T1.2,						
...3		AA63-00406B	GROMMET-PANEL;PDP,PBT,T0.2						
...3		AA61-01064	ABRACKET-EMI,FILTER;PDP,SPTE,T0.3,L62.6,						
...3		AA61-01044	ABRACKET-FINGER;PDP,BE-CO,T0.15,NTR						
...3		AA61-01001B	BRACKET-FILTER BOT;AL 6063 EXT,42P2,T1.2						
..2		AA61-11012	ABRACKET-SHIELD ASSY;SVP554J,SECC-1,T1.0,	S.N.A					
...3		AA61-01006	ABRACKET-MODULE,BOT;42P2,PBS,T0.2						
...3		AA63-00141	ASPACER-FELT;42P2S,FELT,L110,T0.5,D20	S.N.A					

ASSY ACCESSORY

1	*	AA92-03204	AASSY ACCESSORY;PS42P2SDX/XEC	S.N.A
..2		AA39-00300	CABLE RCA;PS42P2S,NON-UL,1P/1P,YEL,RCA,R	
..2		AA39-40001E	CABLE-S.VHS;1500MM	
..2		AA59-00143C	REMOCON;TM63,DREAM4,53,L/GRAY,TTX,E/X	
...3		2802-000194	RESONATOR-CERAMIC;8MHz,1.0%,TP8.5x4.5x5	
...3		AA09-00051A	IC-MCU;Z86L8808SSC-R501M,SZTM-822,28PIN,	
..2		AA68-00291A	MANUAL-S/NETWORK;-SPANISH,-B5,W/P100G,	S.N.A
..2		AA68-02239A	MANUAL USERS;PS42P2S,ENG,W/P100,1,B5,D53	
..2		3301-001110	CORE-FERRITE;ZZ,35x19.5x9.0mm,-,-	
..2		3301-001305	CORE-FERRITE;AE,30X15X34(39)MM,1500,2800	
..2		4301-000103	BATTERY-ALKALINE;1.5V,750mAh,AAA,10.5x44	S.N.A
..2		AA39-00034B	CABLE RCA;PS42P2S,NON-UL,2P/2P,RED/WHT,R	
..2		AA39-00288A	CBF SIGNAL;HPL5025M,15P/15P,2990,1830MM,	

ASSY P/MATERIAL

1	*	AA92-03150A	AASSY P/MATERIAL;PS42P2SDX/XEC	S.N.A
..2		AA61-20285A	HOLDER-BOX;3456,PP,-,-,WHT,VO	S.N.A
..2		AA60-40006A	PIN-STAPLE;-,-H18,33X17.8X2.4,-,AUTO	S.N.A

ASSY BOX

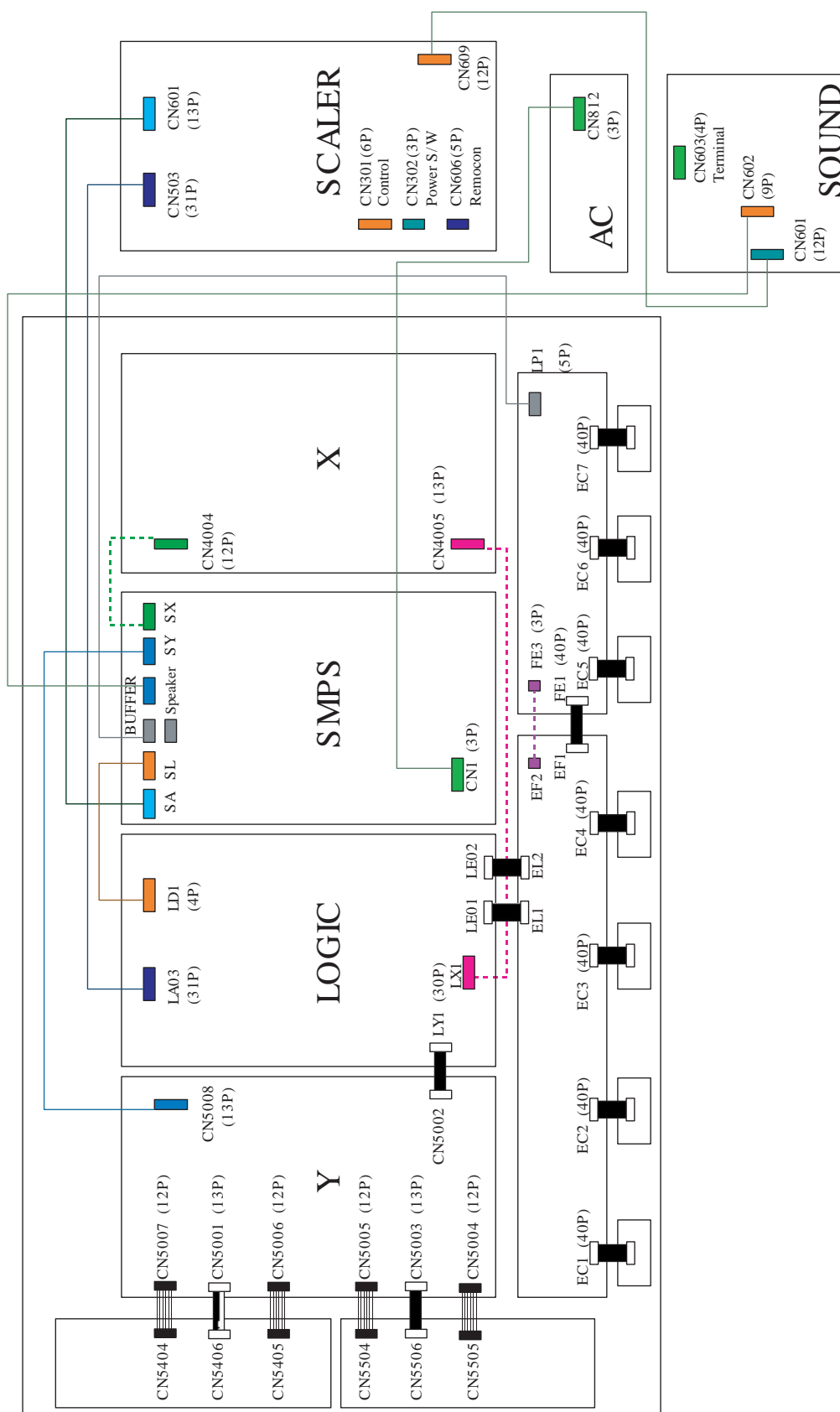
1	*	AA92-02987A	AASSY BOX;PS42P2SDX/XEC	S.N.A
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ASSY LABEL

1	*	AA92-02808A	AASSY LABEL;PS42P2SDX/XEC	S.N.A
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MEMO

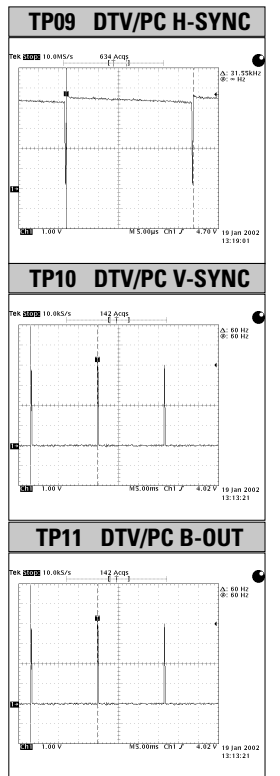
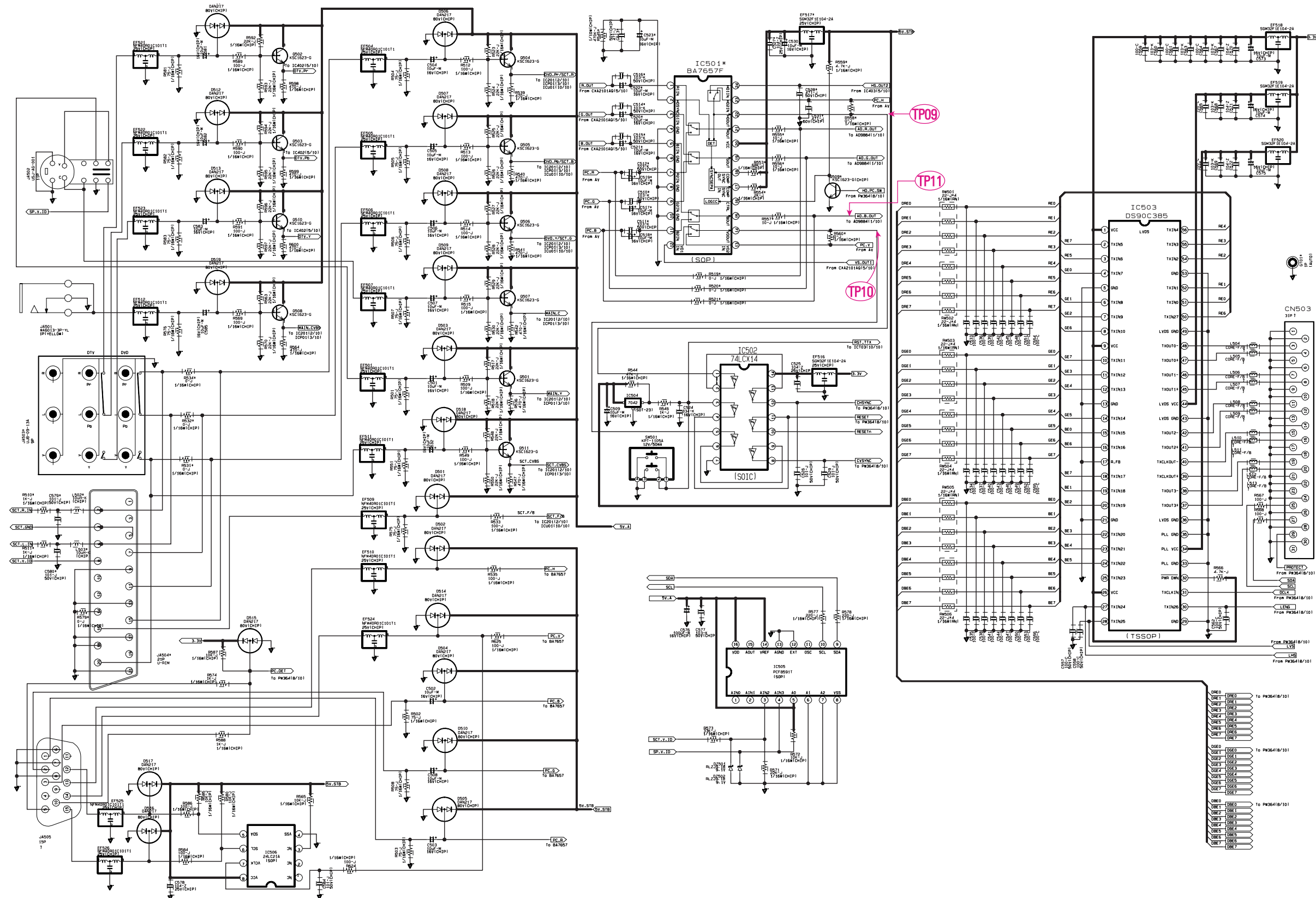
11. Wirng Diagram



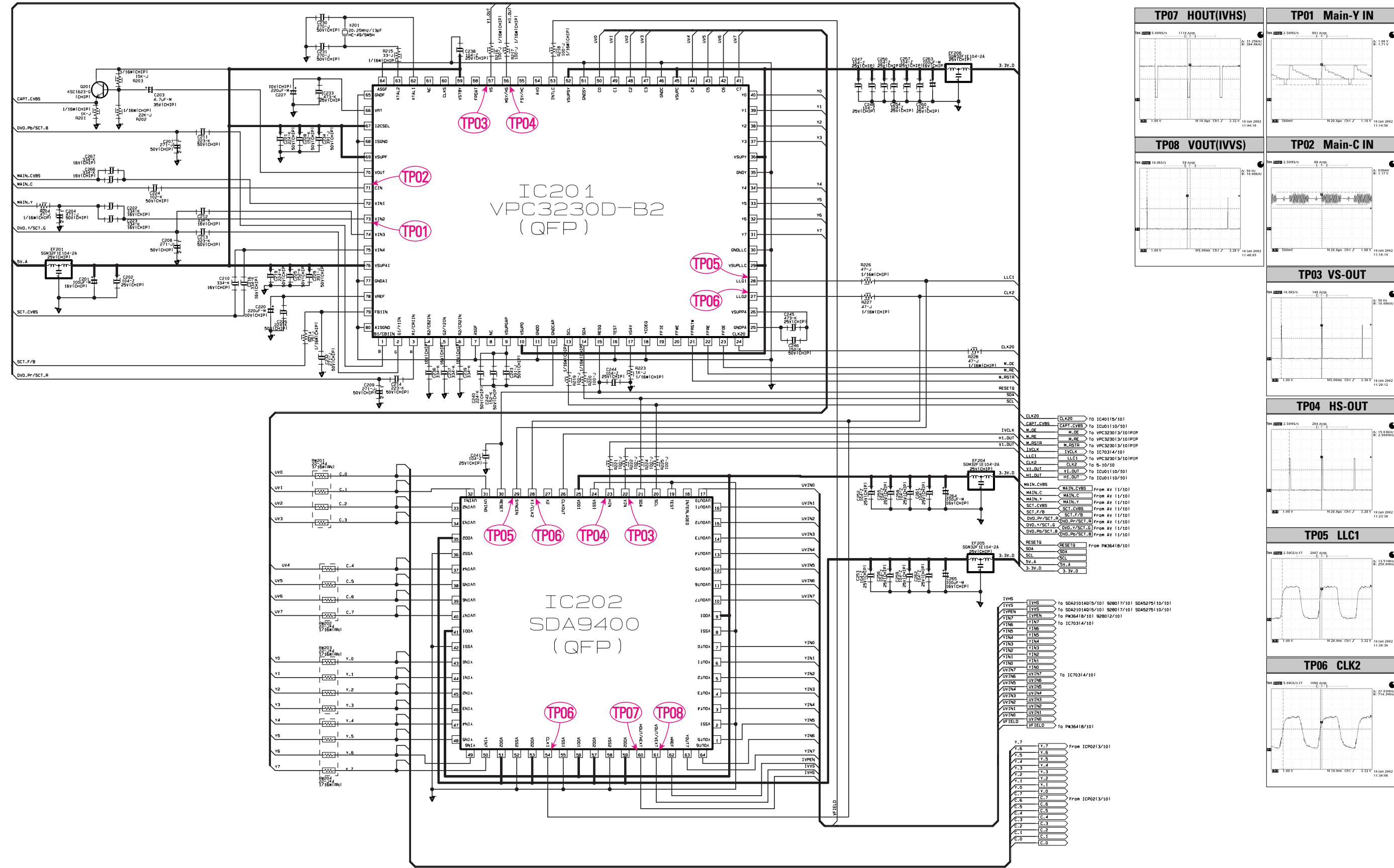
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12. Schematic Diagrams

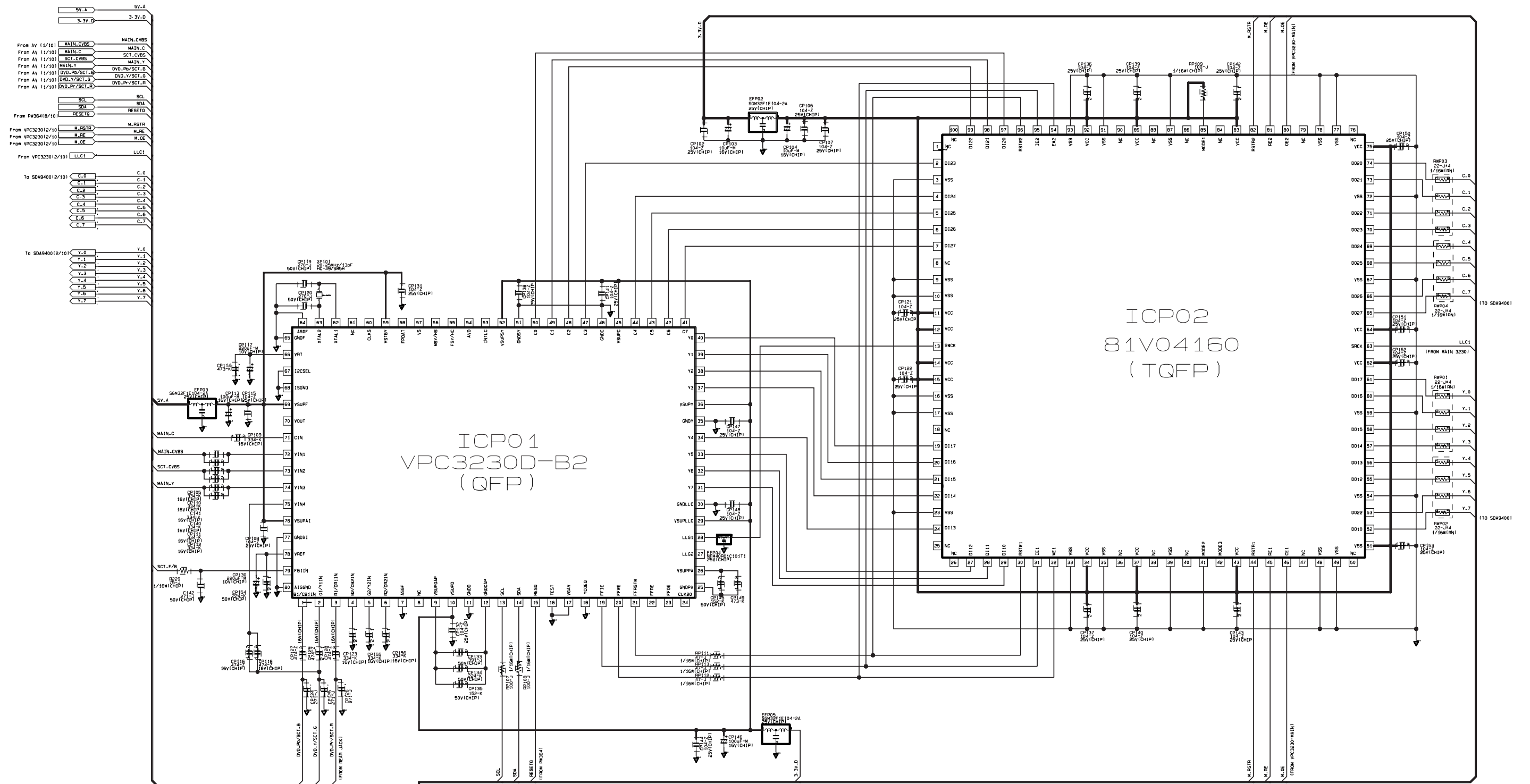
12-1 SCALER1 SIGNAL INPUT, LVDS OUTPUT



12-2 SCALER2 VIDEO DECODER MAIN, PROGRESSIVE CON.



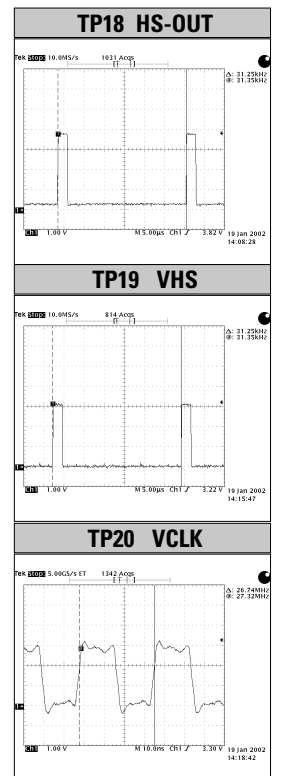
12-3 SCALER3 VIDEO DECODER PIP, FIRST IN/OUTPUT



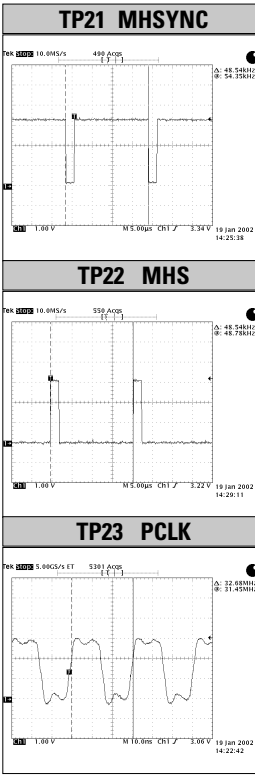
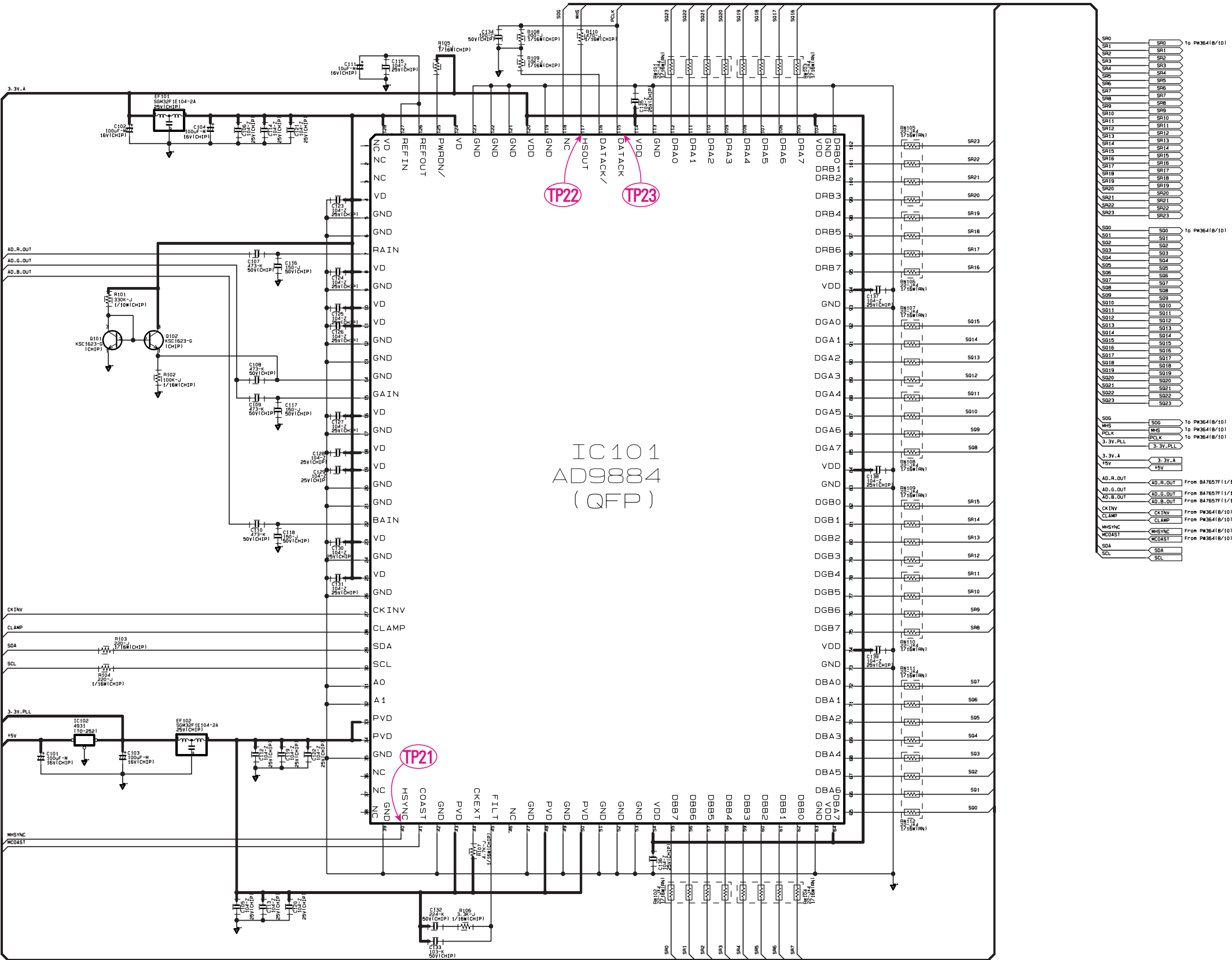


Samsung Electronics

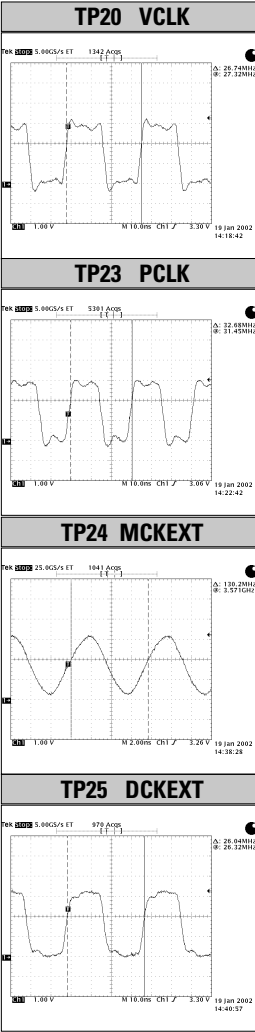
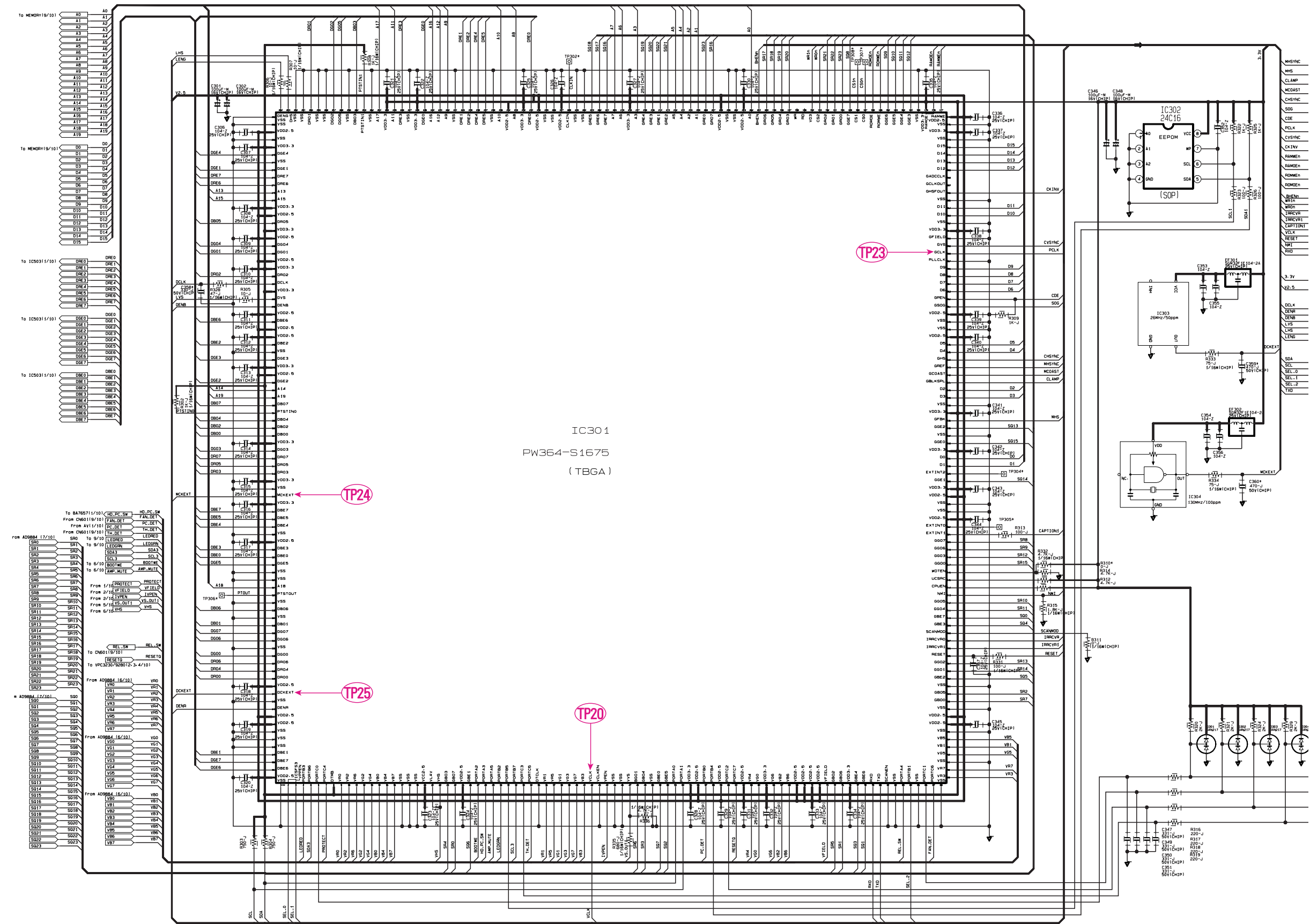




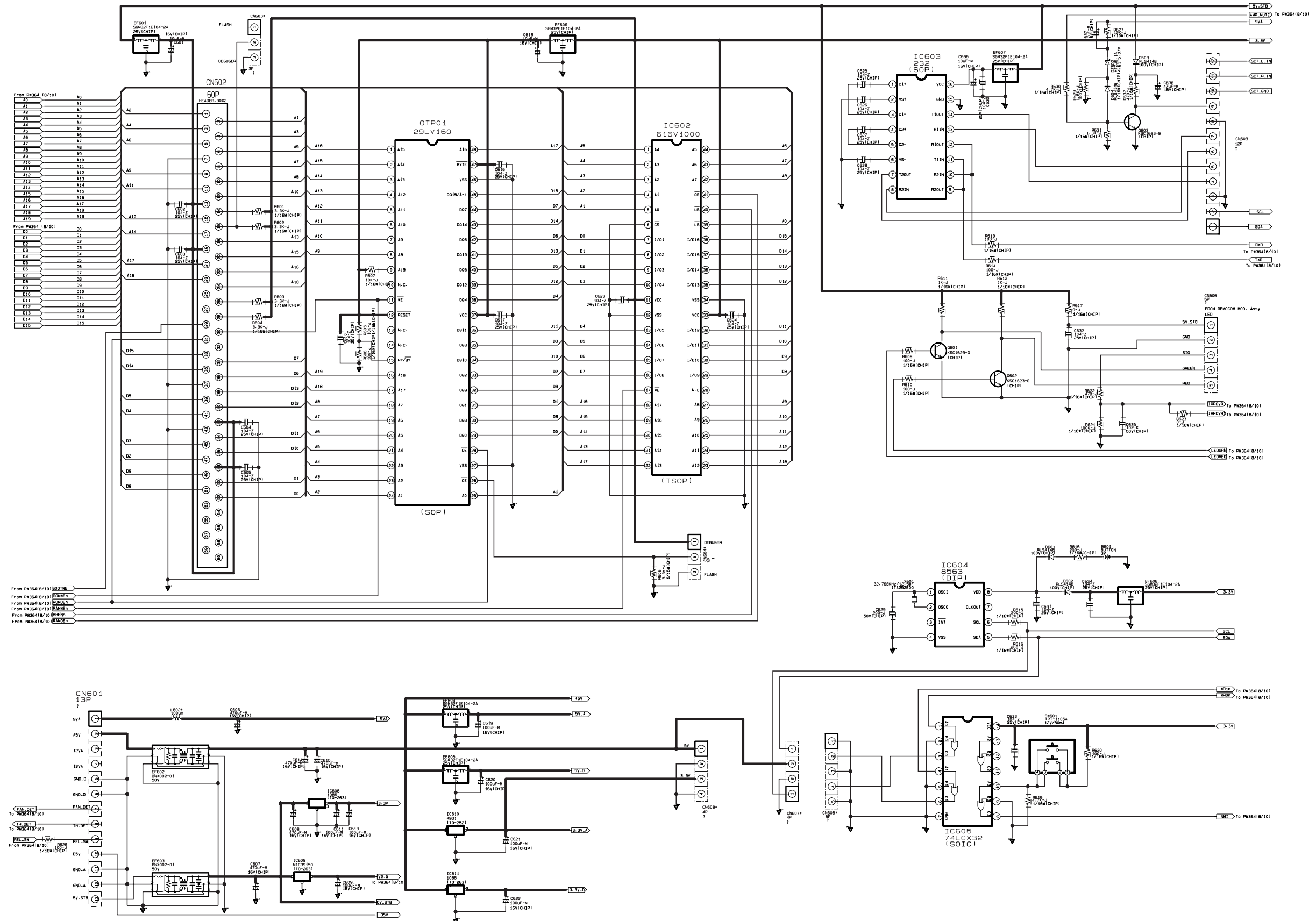
12-7 SCALER7 ADC(PC)



12-8 SCALER8 PW364

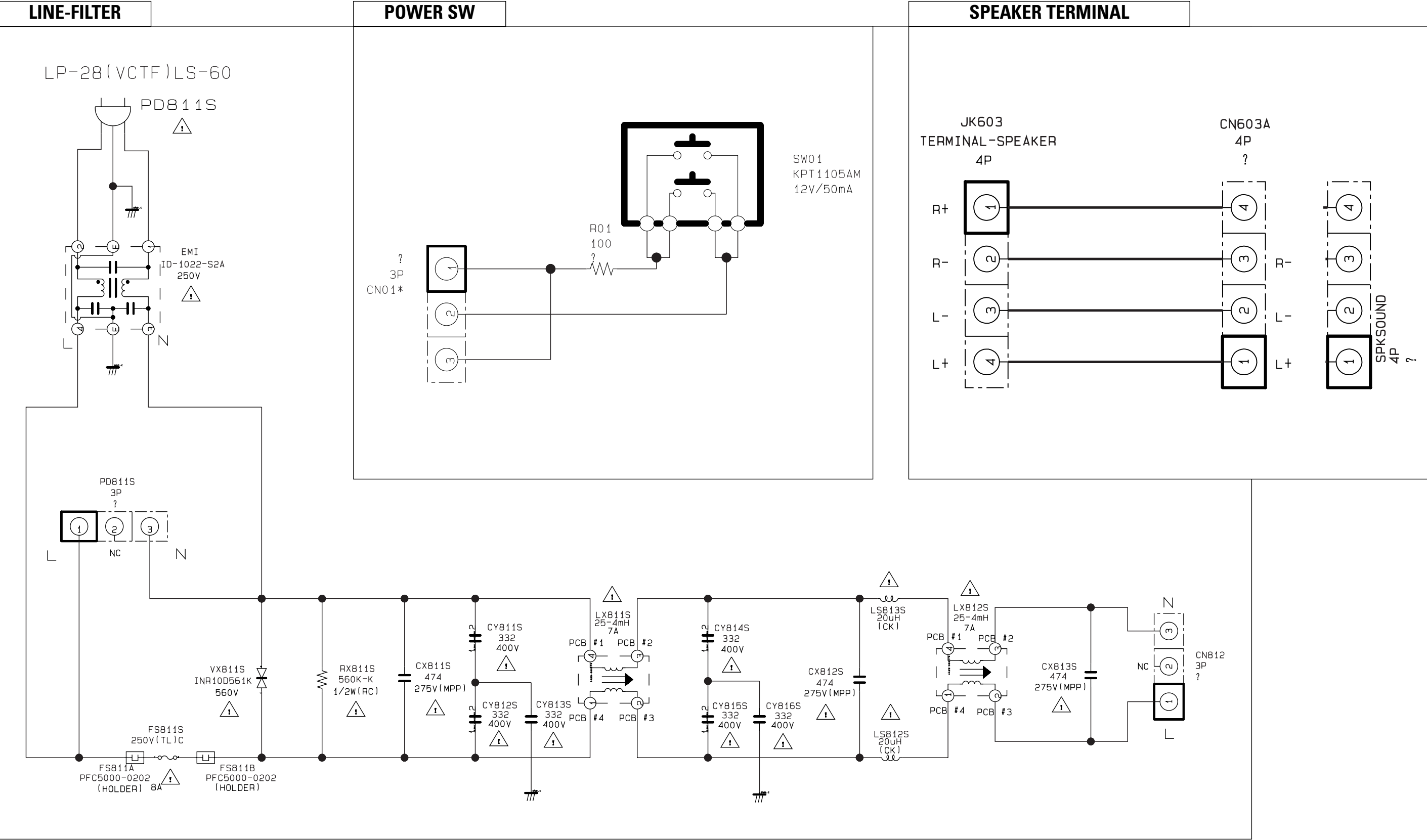


12-9 SCALER9 POWER, DEGUGER, MEMORY, REMOCON, RS232, RTC

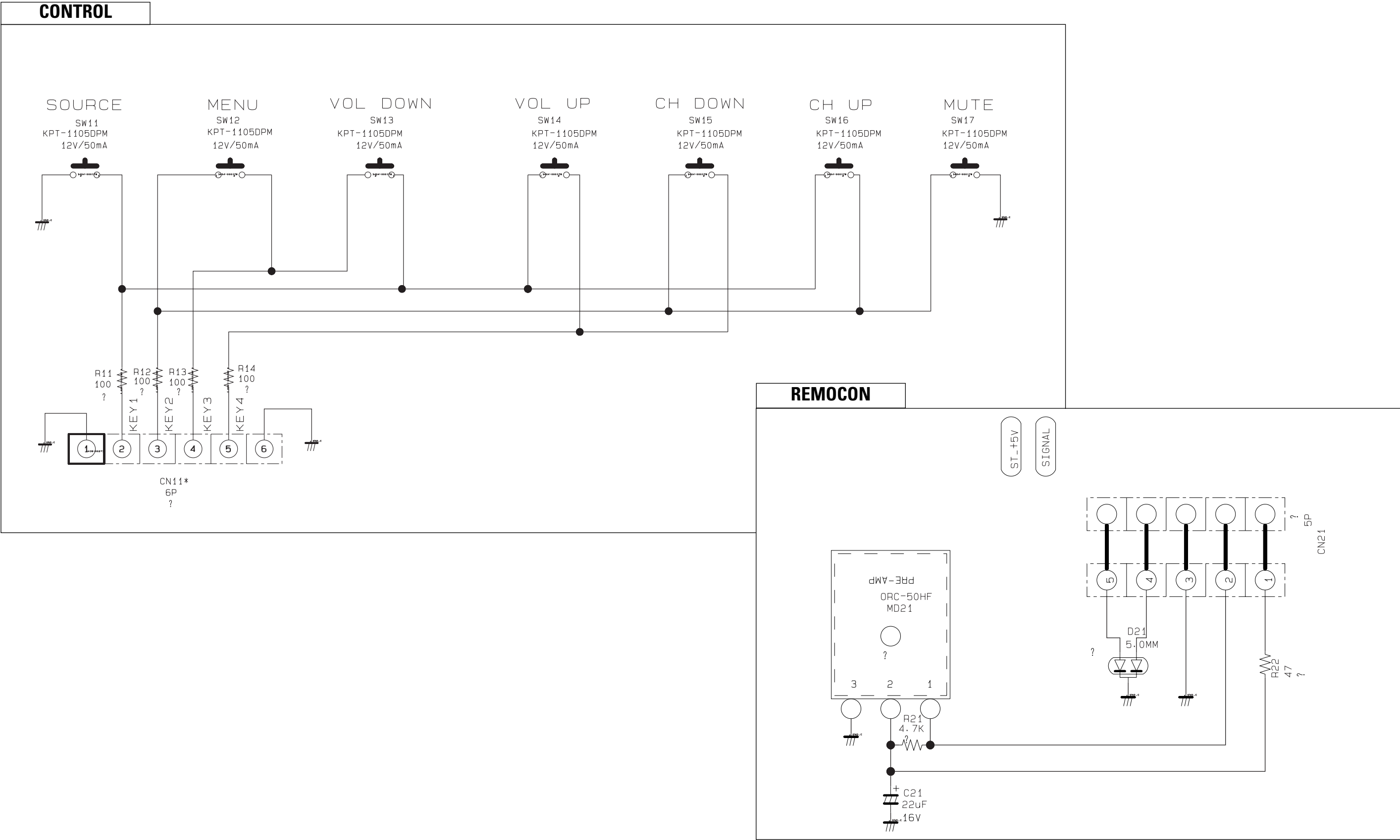




12-12 LINE-FILTER, POWER SW, SPEAKER TERMINAL



12-13 CONTROL, REMOCON



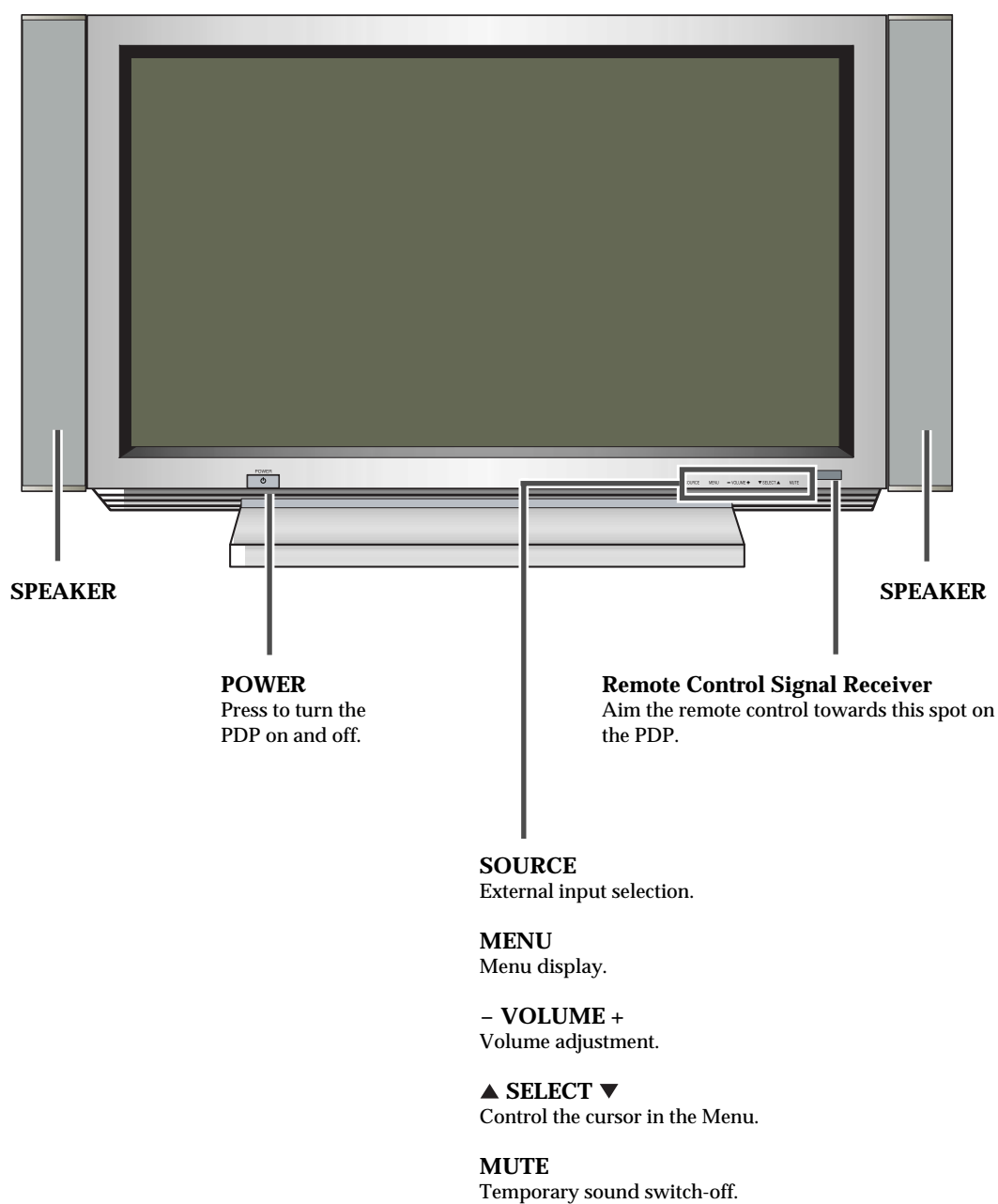
9. Handling Description

9-1 Basic Description

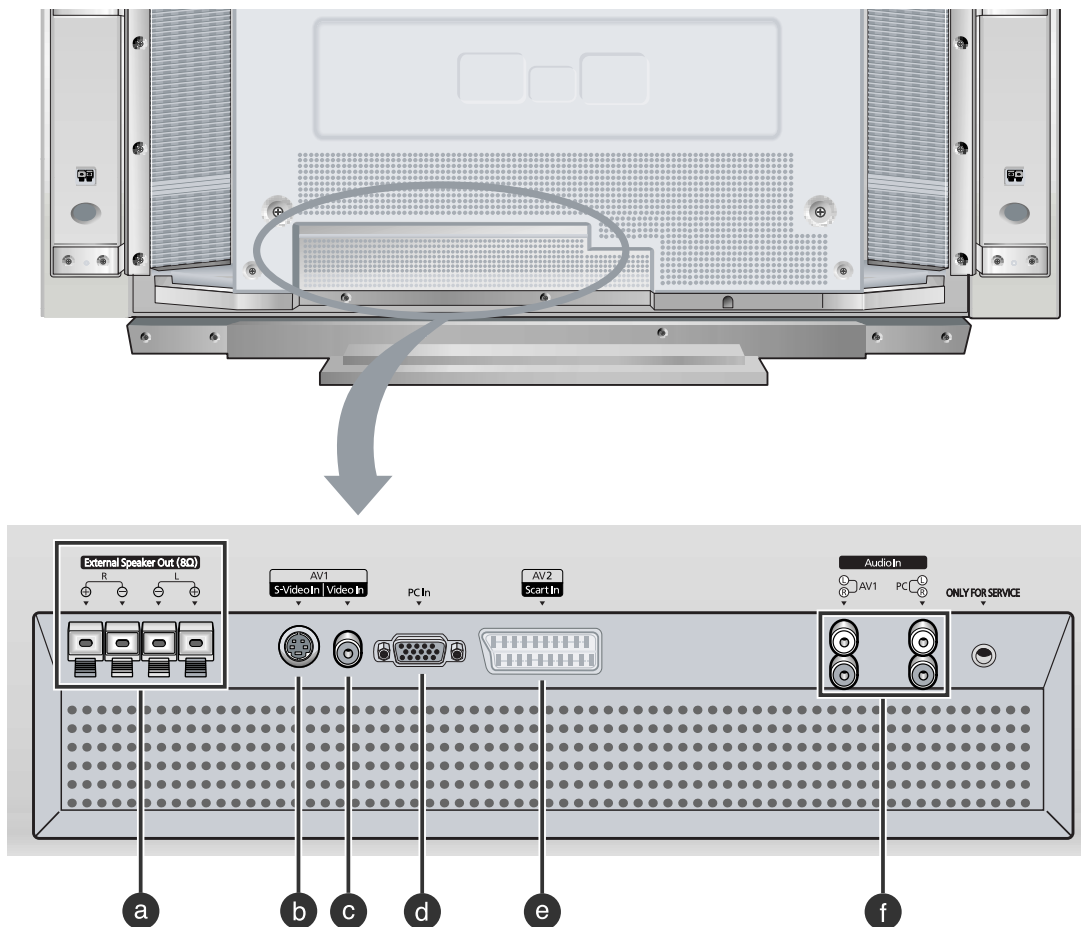
9-1-1 The Name of Each Part

9-1-1(A) PDP(Plasma Display Panel)

Front Panel



Real Panel



a) External Speaker Outputs (8Ω)
Connect external speakers.

b) S-VIDEO Input
Connect a S-Video signal from an S-VHS VCRs or DVD players.

c) VIDEO Input
Connect a video signal from external sources like VCRs or DVD players.

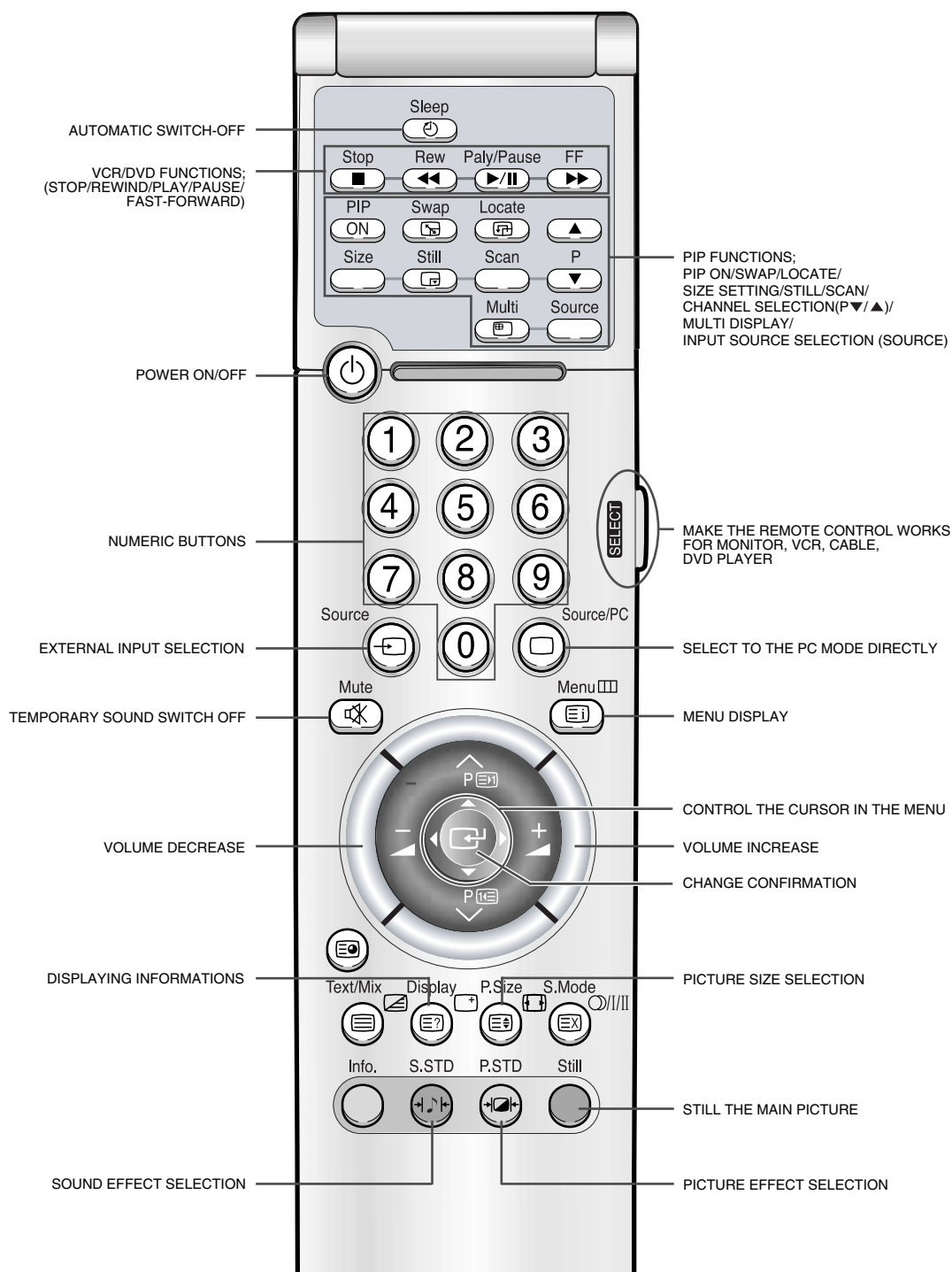
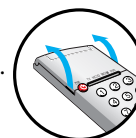
d) PC Input
Connect a PC signal from an PC.

e) SCART Audio/Video Input
Connect a audio/video signal from external sources like VCRs.

f) Audio Inputs (Video/PC)
Connect a audio signal from external sources like VCRs or PC.

9-1-1(B) REMOTE CONTROL

Filp the cover open in the arrow direction.

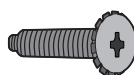
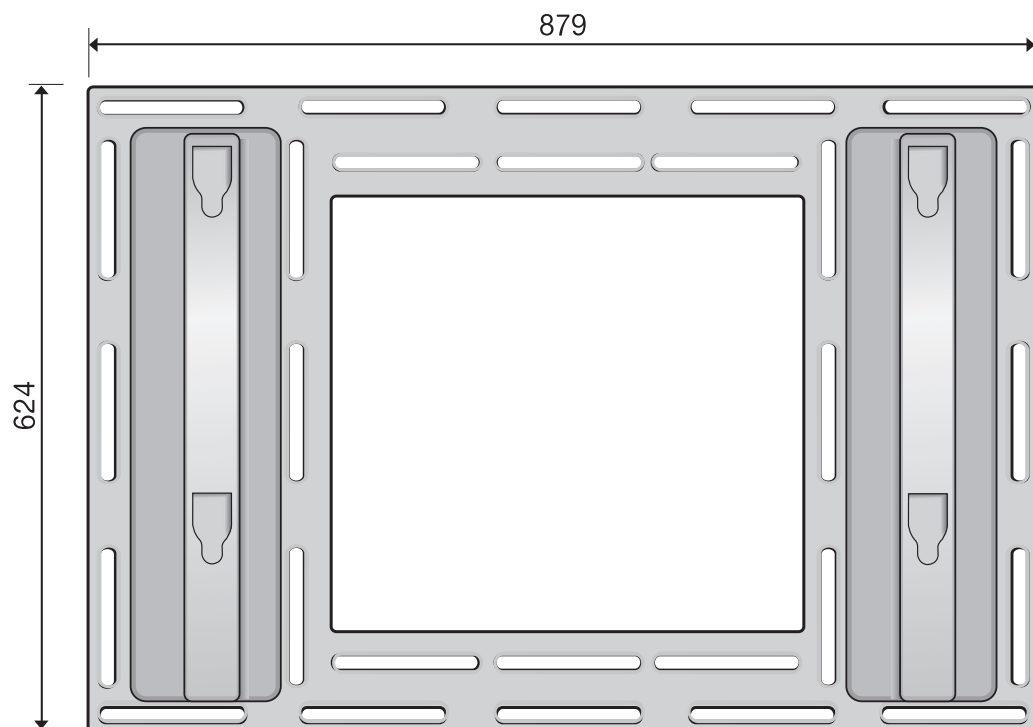


9-2 Wall Mount

9-2-1 Notice for installing

1. Do not install the PDP on any place other than veritical walls.
2. To protect the performance of the PDP and prevent problems, avoid the following place :
 - Next to spring coloer detectors.
 - Places subject to vibration or shock.
 - Near high voltage cables.
 - Around heating apparatus.
3. Install the PDP considering the construction of the wall.
4. Use only recommended parts and components for installation.

9-2-2 Parts(wall attachment panel is sold separately.)



Fixing bolt

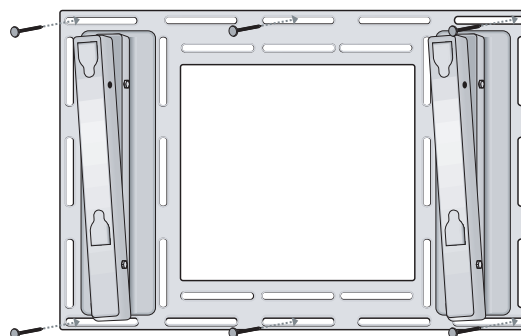


Insulation rubber

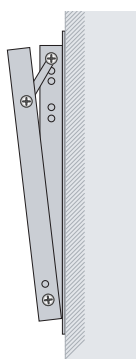
9-2-3 Installing the Display on the Wall Attachment Panel :

1. Check for the stability of the wall where the PDP is to be installed. If the wall is not enough strong to support the PDP, strengthen the wall before installation.

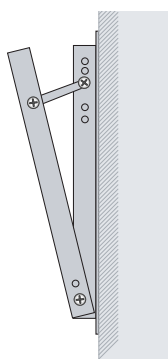
2. Fix the wall attachment panel on the wall using bolts as shown in the figure: Fixing bolts must protrude from the wall approx. 0.6 inches.



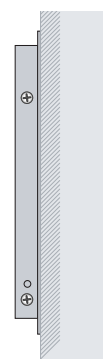
3. Using the wall attachment panel, you may adjust the angle of the display from 0 to 20 degrees. The angle can be set in 5 stages with 5 degrees of distance each using the angle control holes on the sides of the panel.



When the angle has been set to 5 degrees.

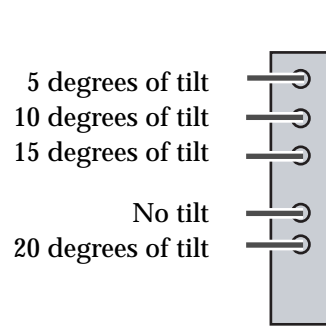


When the angle has been set to 15 degrees.

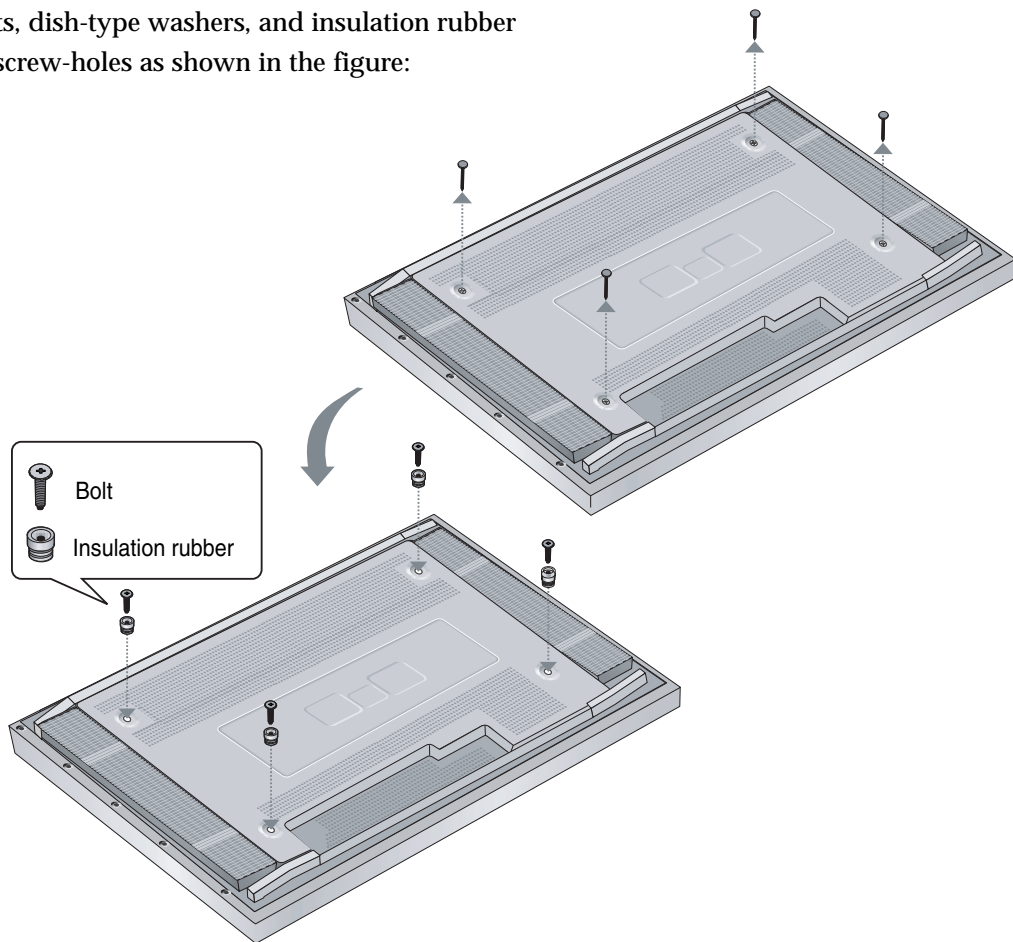


When the panel hasn't been tilted.

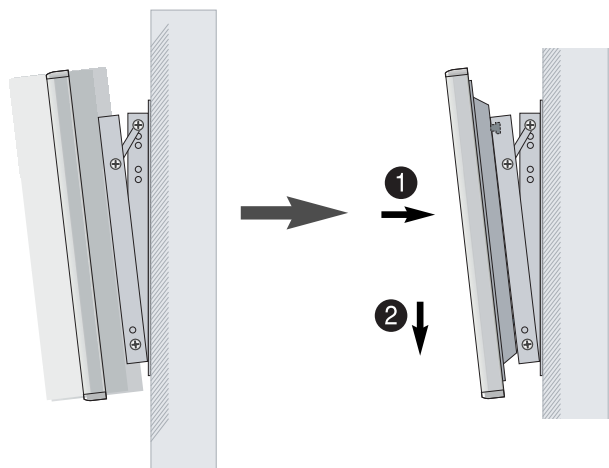
Angle control holes



4. Remove four large screws from the rear side of the display.
Insert the bolts, dish-type washers, and insulation rubber into the four screw-holes as shown in the figure:



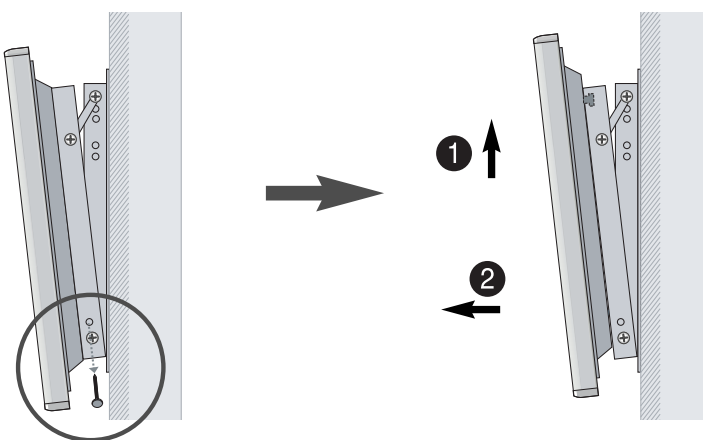
5. Put the insulation rubber point protruding from the rear top of the display in the groove on the top of the wall attachment panel. Lift up the display a little bit so that the insulation rubber point at the bottom of the rear side of the display is put to the groove at the bottom of the wall attachment panel. (Do not lift the display with any pressure. The insulation rubber at the top may be taken off.)v



9-2-4 Separating the Display from the Wall Attachment Panel :

Remove the fixing bolts from both sides(left and right) of the wall attachment panel. Lift and pull the bottom of the display a small amount, to separate the insulation rubber point from the bottom of the wall attachment panel.

Lift the display and separate the insulation rubber point from the groove on top of the wall attachment panel.



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10. Glossary

AC PDP :

Plasma display driven by alternating current plasma electric discharge.

Address discharge(Reference : scan and data) :

Term with two meanings that can be used for both scan and data (write or erase) discharge.

Address Electrode(Reference : scan and data electrode) :

Term with two meanings that can be used for both scan and data electrodes.

Address pulse(Reference : scan and data pulse) :

Address drive wave form

Address voltage(reference; scan and data voltage) :

Address drive amplitude of vibration

Addressing :

Process that gives authorization to cells to allow for turning on and off by drive wave form.

Addressing speed :

Time necessary for writing and erasing.

ADS, address display separation :

Drive tech that separates address pulse temporarily from sustained voltage.

Aging :

The change of operation expectancy- for example, operation voltage change and luminance decline-related characteristics.

Angular distribution :

Characteristics which change as function of angles between perpendicularity and surface. referring to dependency on angles of, for example, luminance or chromaticity.

Aperture ratio :

Referring to the ratio of an element activation area to the gross area.

Area luminance :

Luminance measured in relatively large area.

Aspect ratio :

The ratio of screen width to height.

Auto power control :

Circuit means for controlling panel's average or maximum power.

Auxillary anode :

Anode where discharge of DC panel has little contribution to light output power.

Back ground luminance :

Referring to the panel luminance in off mode or black screen, in other words, luminance in the vicinity of the screen.

Barrier rib :

barriers that cross all the gaps of wafers dividing the cells in panel.

Black stripe :

black substance located in between the fluorescent areas to bring about improvement in contrast by reflection ratio decline. Generally, this is striped.

Bright defect :

defects that occur when the image is rather bright than accurate.

Brightness(Reference : luminance) :

visible and subjective quality, for example, how bright matters look or how much visible rays are perceived.

Notice) Do not get confused luminance with brightness because those two are not the same. Brightness is subjective while luminance is objective.

Burn in :

element's initial operation section that takes place until the element stabilizes or the initial expectancy expiration is detected.

Bus electrode :

aggregate of sustained electrodes that are bussed together.

Cathode electrode :

cathode electrified electrode that releases electrode from element. In AC plasma panel, polarity switches in every half a cycle.

Cell :

capacity corresponding to each electric discharge. In general, it is defined by the shape of substrates and electrodes but can be defined by partitions.

Cell gap :

measurements identifying the gaps between substrates.

Cell pitch :

measurement that identifies the cells from the surface of substrates. It varies depending on the direction of rows and columns.

Charge transfer curves :

curves expressing the quantity of electric charge that is transferred, as the function of drive wave form characteristics.(for example, voltage, time and others)

Color arrangement(in other words, sub-pixel arrangement) :

term expressing the location of one pixel consisted of sub color pixels.

Color coordinates, CIE 1931 :

Color image expressing method in color dimension, originated from CIE standard of 1931, expressed by X, Y and Z. Among those three, Y element corresponds to luminous flux that is expressed as lumen while X and Y are values that express red and purple element of luminous flux. Colors of matter are expressed as color coordinates pair (x, y). Here $x=X/(X+Y+Z)$, $y=Y/(X+Y+Z)$.

Method for colors, known as (u, v), where image colors are expressed in more even color dimension.

Colors of matter are expressed as color coordinates pair (u, v). Here, $u=4X/(X+15Y+3Z)$, $y=6Y/(X+15Y+3Z)$.

Color coordinates, CIE 1960 :

Method for colors, known as (u, v), where image colors are expressed in more even color dimension. colors of matter are expressed as color coordinates pair(u, v). Here, $u=4X/(X+15Y+3Z)$, $v=6Y/(X+15Y+3Z)$.

Color coordinates, CIE 1976

Method for colors, known as (u', v'), where revised image colors are expressed in more even color dimension. v' is 1.5-fold of recommended v value of 1960. The color of matter is expressed as color coordinates pair (u', v'). Here, $u'=4X/(X+15Y+3Z)$, $v'=9Y/(X+15Y+3Z)$.

Color coordinates, CIE 1976 CIELUV and CIELAB :

Three dimensional parameters expressing with u' and v' including Ω_{∞}° against chromaticity and luminance of standard white light in display. Among the parameters, only CIELUV gets to have proper color space where additional two blend light appears in line segment. (refer to CIE Publication 15.2, Colorimetry 1st edition 1976, 2nd edition 1986)

Color depth :

The number of digital bit allocated to each major color.

Color gamut :

Physically realizable color space area.

Color reproducibility (Refer to color gamut) :

The expression of realizable colors limited by color information distinction or fluorescent substance chromaticity.

Color temperature, correlated (symbol CCT) :

Seemingly temperature expressed with absolute temperature of black body radiation with the closest chromaticity. This can be expressed as CCT, in the form of C. S. McCamy. $CCT=437N^3+3601n^2+5517$, $n=(x-0.3320)/(0.1858-y)$ and x, y=color coordinates of CIE 1931.

Columm electrode :

Vertically successive electrodes. It generally refers to data electrodes. When panel is installed along the photograph, this can be arranged along the horizontal direction.

Concurrent driving method :

Driving method to disperse address pulse and scan pulse at equal distance.

Contrast ratio Columm electrode :

Ratio of white luminance to black luminance of image. This measurement has many parameters, so measurers are required to explain the consideration for measurement to make understood the meaning of the measurement. The parameters of contrast ratio are as follows.

- CA - ratio of center luminance in all white screen to center luminance of all black screen on the condition of light being spreading around.
- CG - ratio of white luminance to black luminance in successive arrangement of white and black lines at equal distance.
- CL - ratio of white luminance to black luminance in white line against black screen of black line against white screen.
- CR - the ratio of white luminance to black luminance.

- **Cm** - Michelson contrast or contrast modulation:
Here, L_w is the luminance of the color white while L_b is the luminance of the color black.
- **CT** - Threshold contrast ratio: the minimum contrast ratio that is permissive, in general.

Chip on board(COB) :

PCB with IC on substrate.

Dark defect :

Defects in the brighter image realization than normal one.

Data electrode :

Electrodes allowed for controlling electric discharge by changing the cell's state to switch on from off (and vice versa) in AC plasma panel.

Data electrode driver :

Driving circuit to be attached to data electrode.

Data write pulse :

Wave form for data electrode that switches from off to on.

Data erase pulse :

Wave form for data electrode that switches from on to off.

DC PDP :

Display panel whose plasma discharge is driven by direct current.

Decay time :

Time required for parameters to drop from certain level to another. It can be time necessary for dropping from 90% to 10%, or to e^{-1} level of the initial value, or to certain irreversibility.

Dielectric layer :

Dielectric layer with larger sustained electric constant.

Discharge :

1. neutralization of electric charge (for example, voltage decrease of capacitor)
2. electric current flow in dielectric media such as gas.

Discharge current :

Discharge electric current.

Discharge electrode :

Another term for sustained electrode.

Discharge efficiency :

Another term for gloss efficiency

Discharge gap :

The gap among sustained electrodes in discharge space of three-electrode plasma panel.

Discharge slit :

(Refer to discharge gap)

Displacement current :

Electric current flow through capacitor that includes atomic rearrangement of discharge within electric matter.

Display color number (color number possible to be displayed with other words.) :
displayable individual color's number.

Display Diagonal :

Diagonal size of display contour

Display efficiency :

The ratio of gloss output divided by the entire display power.

Display height :

Height of display contour

Display scan electrode :

(Refer to scan electrode)

Display width :

Width of display contour

Displayed color :

Refer to displayed color number.

Displayed color number :

Color numbers that can be made by display.

Dot (Refer to cell, pixel and subpixel) :

The term is hard to be defined because it is not clear if the term refers to full color pixel or subpixel. The term is used when referring to color related elements that make up full color pixel or subpixel.

Dot pitch :

(Ambiguous expression. Refer to dot, cell pitch, pixel pitch and subpixel pitch.)

Driving waveform :

Expressing $\propto \sqrt{\Omega}$ change of driving signal voltage.

Driving scheme :

Expressing the thought applying driving voltage to display.

Efficacy :

Refer to luminous efficacy.

Energy recovery circuit :

Circuit degauss caught after reusing the power that drove AC plasma panel.

Erase :

Process where cells are erased from AC plasma panel.

Erase pulse :

Cell erasing waveform

Erase voltage :

Erase pulse voltage required for erasing cells from AC plasma panel.[symbol : V_e]

Evacuating (Interchangeable terms : evacuation, exhaust) :

Process where unwanted gas is rid from device.

Exhaust tubulation (Interchangeable terms: exhaust tube, exhaust pipe) :

Tube shaped hole in device connected to external vacuum pump, for controlling the initiation from device during process. This is usually glass tube that prevents with flannelet after filling proper gas

Filling gas (Refer to gas mixture) :

After removing air, plasma panel goes through filling with proper electric and optical gas. Therefore, panel gas composition is commonly called "filling gas".

Firing voltage :

Minimum voltage where triggers discharge in plasma device[symbol : V_f]

Flicker :

Fast and instant changes in luminance, perceivable in almost regular luminance experiment pattern.

Front substrate :

Substrates closer to the viewers, made of transparent material such as glass

Full color display :

Full color image (for example, image with more than 8 bit color tone) realizable display

Fpc(Flexible Printed Curcuit) :

Flexible substrates with circuited copper foil on polyimide

Gas mixing ratio (Interchangeable terms: gas mixture, gas composition) :

Gas composition within plasma device. It is usually expressed with ratio of the constituent gas.

Gas voltage (Interchangeable terms: gas break down voltage) :

Voltage where electrode and ion within plasma device can generate additional electrodes and ions.
-Thus, increasing the electric current within the device sharply. (break down or overflowing)

Glass substrate :

Substrates consisted of glass

Glow discharge :

Plasma discharge taking place under pressure of tens of millimeter. This is defined by ionization generated by activated electrons in discharge space and electron release in cathode by ion bombardment.

Gradation :

Gradual change in characteristics such as luminance and chromaticity

Gray scale :

The range of luminance acquired when displayed from black to white.

High strain point glass :

Glass of which strain point (temperature with viscosity of 1014.5 poise) is relatively high

Image retention :

Continuous existence of image after the stimulation is removed.

Image sticking :

(Refer to Image retention.)

Interconnect pad groups :

A group of connection terminals that attach to individual connector. (also referred to as terminal block.)

Interconnect pad pitch :

Mutual measurements for individual of interconnect pad group.

Interconnect pad spacing :

The size of non-electric conductive area between individual terminal.

Inter-electrode gap :

In Three electrodes plasma panel, the measurement of sustained voltage separated from outside discharge space.

Ion bombardment :

The bombardment of energetic ions in the surface of solid matter. The transfer of kinetic energy toward surface from ions can cause electron release, ion or neutron release and temperature change in surface.

Life time :

Time during device exerts its function. Commonly known as mean time failure (MTTF).

Low melting point glass :

Glass of which melting point (temperature with viscosity of 1014.5 poise) is relatively low.

Since glass is non-crystalline, the word melting is not appropriate, but it gets more fluid as it becomes hot.

Luminance :

Colloquial term for measurement of brightness of display.

It also refers to display related CIE Y constituent. It is expressed by cd/m².

Luminance efficacy :

It refers to gloss output against the total display consumption power. It is calculated by the value generated through dividing gloss output of ∞ white substance with gross consumption power. It is expressed as lumen/watt.

Luminance efficiency :

Gloss output value according to consumption power increase, calculated by the value generated through dividing gloss output of ∞ white substance with white screen power consumption increase against black screen. It is expressed as lumen/watt.

Luminance loading :

Luminance decline that takes place when white square luminance increases into full size all white square.

Matrix(type) PDP :

Plasma display panel made up of matrix with rows and columns.

Matrix type :

Refer to matrix PDP

Maximum firing voltage :

Voltage value required for triggering discharge in all cells.

Maximum sustain voltage :

Maximum drive voltage required not to turn off the cells.

Memory margin :

The disparity between the maximum sustained voltage for keeping discharge and the sustained voltage for turning off the cells

Memory type PDP :

Refer to AC Plasma Panel that has memory. PDP made up of cells that keep turned on or off until switch occurs.

MgO layer :

In bombardment of electrons and ions, MgO's high electron release rate, like cathode application, makes it easier to release electrons.

MgO protecting layer (Refer MgO layer) :

MgO layer on fluorescent material has secondary benefit that prevents fluorescent degradation by ion bombardment.

Minimum firing voltage :

Minimum voltage that can turn on any cells.[symbol : V1]

Minimum sustain voltage :

Minimum sustain voltage that keeps turned on cell on.[symbol : Vsm1]

Monochrome display Minimum sustain voltage :

Display that only expresses a limited color such as white, green and amber.

Multi-color display :

Display that can express multiple colors .if not all colors.

Non-discharge slit :

(Refer to inter electrode gap)

Operating margin :

AC PDP voltage range that keeps cells turned on or off. Generally, its value gets less than memory margin because of additional factors such as temperature effect, gloss ionization effect and waveform change.

Operating window :

Actual voltage range that keeps cells turned on or off in any drive levels and surrounding environment.

Operating window degradation :

Gradual decline in operating window, according to operating time.

Opposed discharge :

Traditional two-electrode plasma panel structure where discharge occurs between the two sustained electrodes across from each other.

Opposed discharge PDP :

(Refer to opposed discharge.)

Peak luminance :

Maximum luminance generated in one pixel in panel.

Peak luminance enhancement :

Circuit and drive technology that accommodates increasing peak luminance.

Phosphor degradation :

Gradual decline in fluorescence efficiency according to operating expectancy.

Phosphor layer :

Thin layer made up of phosphor. Fluorescence substance must be thick enough to optimize transferring the ultraviolet rays from plasma discharge to visible light

Pixel, picture element :

The smallest unit that can display the entire range of luminance and chromaticity. Generally, pixel consists of sub pixels (or dots).

Pixel arrangement :

Expression of sub pixels within a pixel.

Pixel count :

The number of pixels that make up a display. It is described as the number of column pixels against the number of row pixels.

Pixel pitch :

The distance between the centers of the two closest pixels. Move as far as the pitch and reach the identical location.

Plasma display :

Electrically driven display device for causing electric discharge in gas within device. Electric energy generates light with atomic light release or from proper colored fluorescence substance.

Positive column discharge :

The plasma area for long glow discharge. This area is a low electric field but relatively electric conductive plasma area.

Pre discharge :

Cell's state where pre discharge is taking place. In this case, cell's state becomes electric conductive due to formation of discharge generated by ionization process of gas.

Priming :

The stage where ions are generated for forming discharge. Generally, this is required for injection.

Priming pulse :

Electric waveform to define the proper conditions for the next cell discharge.[symbol : Pp]

Priming voltage :

Voltage of priming pulse.[symbol : Vp]

Protecting layer :

The layers applied to the device function constituents (for example, fluorescence, electrode and glass layers).

Quantum efficiency :

Substrates farther from the viewers. These can be opaque.

Rear substrate :

Efficiency measurement that is directly expressed with the number of output particles against the number of input particles. In case of plasma panel, the number of photons in visible area, generated from photons in ultraviolet area

Reset :

(Refer to erase.)

Reset discharge, Reset pulse :

(Refer to erase.)

Resolution :

Display's ability to enable to distinguish the matters close to each other. It is confusing with addressability that generates pattern undistinguishable to the eyes.

Row electrodes :

Horizontally successive electrodes. In terms of traditional drive concept, these are the sustained electrodes. If the panel is installed toward portrait, these row electrodes can be arranged horizontally.

Sand discharge :

Process where grinding of surface occurs. It is used for making three dimensional surface in lithography or silt in sheet.

Scan discharge :

Discharge injected along the pair of sustained electrodes.

Scan electrode :

Electrodes of the pair of sustained electrodes that inject discharge downward along the panel columns.

Scan pulse :

Waveform that injects discharge with new columns.
Optic defects where scratches display over certain size.

Seal :

Combining the substrates or substrate with ventilation tube.

Seal layer :

Material layer that provides the connection of substrates. This can be a single layer of solder glass (frit) or the combination of solder glass and ring.

Sealing :

Process where free electrons that get out of the surface by extracting static electricity field when energetic electrons or ions are limited to a surface.

Secondary electron emission :

Process where drags discharged cell to certain waveform. This could occur before ionization offset when cell voltage decreases.

Self erase :

Plasma display in the form where stimulating discharge occurs for discharge process precedes below panel.

Self-scan type PDP :

Plasma display in the form where stimulating discharge occurs for discharge process precedes below panel.

Self-shift type PDP :

Process of combining substrates. High temperature process that melts solder glass combining substrates.

Space charge :

Mutual repulsion caused by accumulation of electric charge of similar signal.

Stripe rib :

Stripe shaped partition structure. It follows panel column direction.

Sub frame :

(Refer to sub field)

Sub field :

A part of panel

Surface charge :

It refers to the location of discharge in AS plasma panel where sustained electrodes are on the same surface.

Surface charge PDP :

AS plasma panel where sustained electrodes are on the same surface.

Sustain :

Discharge in AC plasma panel that keeps on or off until the cell is erased or written. Sustained electrodes are divided into bus (common electrodes) and addressable electrodes.

Sustain driver :

Circuit that drives sustained electrodes.

Sustain electrode :

Electrodes driven by AC voltage that provides plasma with energy major parts. This electrode is driven by enough waveform to keep discharge of turned on state. In turned off cell, trigger discharge does not takes place.

Sustain margin :

The disparity between sustained voltage that keeps turned on cells and sustained voltage that can turn off cells.

Sustain pulse :

Sustained drive waveform[symbol : Ps]

Sustain voltage :

Voltage level of sustained waveform

Thermal compaction :

Substrates successive density increase observed by substrates pattern contraction.

Thermal radiation :

Radiation in infrared rays over 800nm.

Three electrode type :

Modern AC panel has three electrodes for each cell and a pair of thermal electrodes provide cells with AC power. Data electrodes in opposite substrates provide unique writing and erasing signals to each cell

Time modulation driving method (Other terms: time division multiplex method) :

Modulation method in proportion to certain time applied to stimulation with regular output. Output strength is changed according to input time.

Tip pipe :

(Refer to exhaust turbulation.)

Townsend discharge :

Self sustained plasma discharge expressed by Townsend in 1901. This discharge requires 200v voltage.

Transparent electrode :

Electrode made up of transparent electric conductive matter such as ITO.

Two electrode type :

Original AC plasma panel used two electrodes that provide not only sustained waveform but also write and erase waveform.

Ultraviolet ray :

Ultraviolet light below 380nm in spectrum.

Vacuum ultraviolet :

Ultraviolet ray of wavelength below 200nm.

Viewing angle :

Vertical angle that can display the image. It is normally limited by the change in luminance and chromaticity.

Viewable screen diagonal :

Releasable screen diagonal length measured between outmost pixel edges

Viewable screen height :

Releasable screen height measured between outmost pixel edges

Viewable screen width :

Releasable screen width measured between outmost pixel edges.

Visible defect :

Imperfection that prevents displaying with proper image.

Wall charge :

Pure accumulation of positive and negative charges in cell wall.

Wall charge erase pulse :

Pulse that neutralizes wall charge

Wall charge transfer curve :

Curve related to wall charge pulse parameters and the changes in wall charge.

Wall voltage transfer curve :

Curve expressed with wall transfer that is caused by any changes in electric charges including wall charges and wall charge pulse related parameters.

White back :

White coating for minimize absorbing valid gloss, located black contrast improvement layer and fluorescent material.

Write electrode :

(Refer to data electrode.)

Write electrode :

(Refer to data electrode)[symbol : Pw]

Write electrode :

(Refer to data electrode)[symbol : Vw]

MEMO

